



Quad-Core Intel® Xeon® Processor 5300 Series

Datasheet

March 2007



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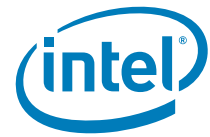


Contents

| | | |
|--------|--|-----|
| 1 | Introduction..... | 9 |
| 1.1 | Terminology | 11 |
| 1.2 | State of Data | 13 |
| 1.3 | References | 13 |
| 2 | Electrical Specifications | 15 |
| 2.1 | Front Side Bus and GTLREF | 15 |
| 2.2 | Power and Ground Lands..... | 16 |
| 2.3 | Decoupling Guidelines | 16 |
| 2.3.1 | VCC Decoupling..... | 16 |
| 2.3.2 | VTT Decoupling | 16 |
| 2.3.3 | Front Side Bus AGTL+ Decoupling | 17 |
| 2.4 | Front Side Bus Clock (BCLK[1:0]) and Processor Clocking | 17 |
| 2.4.1 | Front Side Bus Frequency Select Signals (BSEL[2:0]) | 18 |
| 2.4.2 | PLL Power Supply | 19 |
| 2.5 | Voltage Identification (VID) | 19 |
| 2.6 | Reserved, Unused, or Test Signals..... | 21 |
| 2.7 | Front Side Bus Signal Groups..... | 22 |
| 2.8 | CMOS Asynchronous and Open Drain Asynchronous Signals | 24 |
| 2.9 | Test Access Port (TAP) Connection..... | 24 |
| 2.10 | Platform Environmental Control Interface (PECI) DC Specifications..... | 24 |
| 2.10.1 | DC Characteristics | 25 |
| 2.10.2 | Input Device Hysteresis | 25 |
| 2.11 | Mixing Processors..... | 26 |
| 2.12 | Absolute Maximum and Minimum Ratings | 26 |
| 2.13 | Processor DC Specifications | 27 |
| 2.13.1 | Flexible Motherboard Guidelines (FMB) | 27 |
| 2.13.2 | VCC Overshoot Specification | 35 |
| 2.13.3 | Die Voltage Validation | 36 |
| 2.14 | AGTL+ FSB Specifications..... | 36 |
| 3 | Mechanical Specifications..... | 41 |
| 3.1 | Package Mechanical Drawings | 41 |
| 3.2 | Processor Component Keepout Zones..... | 45 |
| 3.3 | Package Loading Specifications | 45 |
| 3.4 | Package Handling Guidelines..... | 46 |
| 3.5 | Package Insertion Specifications..... | 46 |
| 3.6 | Processor Mass Specifications | 46 |
| 3.7 | Processor Materials..... | 46 |
| 3.8 | Processor Markings..... | 47 |
| 3.9 | Processor Land Coordinates | 47 |
| 4 | Land Listing | 51 |
| 4.1 | Quad-Core Intel® Xeon® Processor 5300 Series Pin Assignments | 51 |
| 4.1.1 | Land Listing by Land Name | 51 |
| 4.1.2 | Land Listing by Land Number | 73 |
| 5 | Signal Definitions | 93 |
| 5.1 | Signal Definitions | 93 |
| 6 | Thermal Specifications | 101 |
| 6.1 | Package Thermal Specifications | 101 |
| 6.1.1 | Thermal Specifications | 101 |
| 6.1.2 | Thermal Metrology | 107 |
| 6.2 | Processor Thermal Features..... | 108 |



| | | |
|-------|--|-----|
| 6.2.1 | Thermal Monitor Features | 108 |
| 6.2.2 | Thermal Monitor (TM1) | 108 |
| 6.2.3 | Thermal Monitor 2 | 108 |
| 6.2.4 | On-Demand Mode | 110 |
| 6.2.5 | PROCHOT# Signal | 110 |
| 6.2.6 | FORCEPR# Signal | 110 |
| 6.2.7 | THERMTRIP# Signal | 111 |
| 6.3 | Platform Environment Control Interface (PECI) | 111 |
| 6.3.1 | Introduction | 111 |
| 6.3.2 | PECI Specifications | 113 |
| 7 | Features | 115 |
| 7.1 | Power-On Configuration Options | 115 |
| 7.2 | Clock Control and Low Power States | 115 |
| 7.2.1 | Normal State | 116 |
| 7.2.2 | HALT or Extended HALT State | 116 |
| 7.2.3 | Stop-Grant State | 118 |
| 7.2.4 | Extended HALT Snoop or HALT Snoop State, Stop Grant Snoop State | 119 |
| 7.3 | Enhanced Intel SpeedStep® Technology | 119 |
| 8 | Boxed Processor Specifications | 121 |
| 8.1 | Introduction | 121 |
| 8.2 | Mechanical Specifications | 123 |
| 8.2.1 | Boxed Processor Heat Sink Dimensions (CEK) | 123 |
| 8.2.2 | Boxed Processor Heat Sink Weight | 131 |
| 8.2.3 | Boxed Processor Retention Mechanism and Heat Sink Support (CEK) | 131 |
| 8.3 | Electrical Requirements | 131 |
| 8.3.1 | Fan Power Supply (Active CEK) | 131 |
| 8.3.2 | Boxed Processor Cooling Requirements | 132 |
| 8.4 | Boxed Processor Contents | 133 |
| 9 | Debug Tools Specifications | 135 |
| 9.1 | Debug Port System Requirements | 135 |
| 9.2 | Target System Implementation | 135 |
| 9.2.1 | System Implementation | 135 |
| 9.3 | Logic Analyzer Interface (LAI) | 135 |
| 9.3.1 | Mechanical Considerations | 136 |
| 9.3.2 | Electrical Considerations | 136 |



Figures

| | | |
|------|--|-----|
| 2-1 | Input Device Hysteresis | 26 |
| 2-2 | Quad-Core Intel® Xeon® Processor E5300 Series Load Current versus Time..... | 30 |
| 2-3 | Quad-Core Intel® Xeon® Processor X5300 Series Load Current versus Time | 30 |
| 2-4 | Quad-Core Intel® Xeon® Processor L5300 Series Load Current versus Time..... | 31 |
| 2-5 | Quad-Core Intel® Xeon® Processor E5300 Series VCC Static and Transient Tolerance Load Lines..... | 32 |
| 2-6 | Quad-Core Intel® Xeon® Processor X5300 Series VCC Static and Transient Tolerance Load Lines..... | 33 |
| 2-7 | Quad-Core Intel® Xeon® Processor L5300 Series VCC Static and Transient Tolerance Load Lines..... | 34 |
| 2-8 | VCC Overshoot Example Waveform..... | 36 |
| 2-9 | Electrical Test Circuit | 38 |
| 2-10 | Differential Clock Waveform..... | 38 |
| 2-11 | Differential Clock Crosspoint Specification..... | 39 |
| 3-1 | Processor Package Assembly Sketch | 41 |
| 3-2 | Processor Package Drawing (Sheet 1 of 3)..... | 42 |
| 3-3 | Processor Package Drawing (Sheet 2 of 3)..... | 43 |
| 3-4 | Processor Package Drawing (Sheet 3 of 3)..... | 44 |
| 3-5 | Processor Top-side Markings (Example)..... | 47 |
| 3-6 | Processor Land Coordinates, Top View..... | 48 |
| 3-7 | Processor Land Coordinates, Bottom View..... | 49 |
| 6-1 | Quad-Core Intel® Xeon® Processor E5300 Series Thermal Profile | 103 |
| 6-2 | Quad-Core Intel® Xeon® Processor X5300 Series Thermal Profiles..... | 104 |
| 6-3 | Quad-Core Intel® Xeon® Processor L5300 Series Thermal Profile..... | 106 |
| 6-4 | Case Temperature (TCASE) Measurement Location | 107 |
| 6-5 | Thermal Monitor 2 Frequency and Voltage Ordering | 109 |
| 6-6 | PECI Topology | 112 |
| 6-7 | Conceptual Fan Control Diagram For A PECI-Based Platform..... | 112 |
| 7-1 | Stop Clock State Machine | 118 |
| 8-1 | Boxed Quad-Core Intel® Xeon® Processor 5300 Series 1U Passive/3U+ Active Combination Heat Sink (With Removable Fan) | 121 |
| 8-2 | Boxed Quad-Core Intel® Xeon® Processor 5300 Series 2U Passive Heat Sink | 122 |
| 8-3 | 2U Passive Quad-Core Intel® Xeon® Processor 5300 Series Processor Thermal Solution (Exploded View) | 122 |
| 8-4 | Top Side Board Keepout Zones (Part 1) | 124 |
| 8-5 | Top Side Board Keepout Zones (Part 2) | 125 |
| 8-6 | Bottom Side Board Keepout Zones..... | 126 |
| 8-7 | Board Mounting-Hole Keepout Zones | 127 |
| 8-8 | Volumetric Height Keep-Ins | 128 |
| 8-9 | 4-Pin Fan Cable Connector (For Active CEK Heat Sink) | 129 |
| 8-10 | 4-Pin Base Board Fan Header (For Active CEK Heat Sink)..... | 130 |
| 8-11 | Fan Cable Connector Pin Out for 4-Pin Active CEK Thermal Solution | 132 |

Tables

| | | |
|-----|---|----|
| 1-1 | Quad-Core Intel® Xeon® Processor 5300 Series Features | 10 |
| 2-1 | Core Frequency to FSB Multiplier Configuration | 18 |
| 2-2 | BSEL[2:0] Frequency Table | 18 |
| 2-3 | Voltage Identification Definition..... | 20 |
| 2-4 | Loadline Selection Truth Table for LL_ID[1:0] | 21 |
| 2-5 | Market Segment Selection Truth Table for MS_ID[1:0] | 21 |



| | | |
|------|---|-----|
| 2-6 | FSB Signal Groups | 22 |
| 2-7 | AGTL+ Signal Description Table | 23 |
| 2-8 | Non AGTL+ Signal Description Table..... | 23 |
| 2-9 | Signal Reference Voltages..... | 24 |
| 2-10 | PECI DC Electrical Limits..... | 25 |
| 2-11 | Processor Absolute Maximum Ratings | 27 |
| 2-12 | Voltage and Current Specifications | 28 |
| 2-13 | VCC Static and Transient Tolerance | 31 |
| 2-14 | AGTL+ Signal Group Specifications..... | 34 |
| 2-15 | CMOS Signal Input/Output Group and TAP Signal Group DC Specifications..... | 35 |
| 2-16 | Open Drain Output Signal Group DC Specifications | 35 |
| 2-17 | VCC Overshoot Specifications | 35 |
| 2-18 | AGTL+ Bus Voltage Definitions | 37 |
| 2-19 | FSB Differential BCLK Specifications | 37 |
| 3-1 | Package Loading Specifications..... | 45 |
| 3-2 | Package Handling Guidelines | 46 |
| 3-3 | Processor Materials | 46 |
| 4-1 | Land Listing by Land Name | 51 |
| 4-2 | Land Listing by Land Number | 73 |
| 5-1 | Signal Definitions..... | 93 |
| 6-1 | Quad-Core Intel® Xeon® Processor E5300 Series Thermal Specifications..... | 102 |
| 6-2 | Quad-Core Intel® Xeon® Processor E5300 Series Thermal Profile Table | 103 |
| 6-3 | Quad-Core Intel® Xeon® Processor X5300 Series Thermal Specifications | 104 |
| 6-4 | Quad-Core Intel® Xeon® Processor X5300 Series Thermal Profile A Table | 105 |
| 6-5 | Quad-Core Intel® Xeon® Processor X5300 Series Thermal Profile B Table | 105 |
| 6-6 | Quad-Core Intel® Xeon® Processor L5300 Series Thermal Specifications | 106 |
| 6-7 | Quad-Core Intel® Xeon® Processor L5300 Series Thermal Profile | 107 |
| 6-8 | GetTemp0() and GetTemp1() Error Codes..... | 114 |
| 7-1 | Power-On Configuration Option Lands..... | 115 |
| 7-2 | Extended HALT Maximum Power | 117 |
| 8-1 | PWM Fan Frequency Specifications for 4-Pin Active CEK Thermal Solution..... | 132 |
| 8-2 | Fan Specifications for 4-Pin Active CEK Thermal Solution..... | 132 |
| 8-3 | Fan Cable Connector Pin Out for 4-Pin Active CEK Thermal Solution..... | 132 |



Revision History

| Revision | Description | Date |
|----------|---|---------------|
| 001 | Initial Release | November 2006 |
| 002 | Added Quad-Core Intel® Xeon® Processor L5300 Series | March 2007 |

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1 Introduction

The Quad-Core Intel® Xeon® Processor 5300 Series are 64-bit server/workstation processors utilizing four Intel Core™ microarchitecture cores. These processors are based on Intel's 65 nanometer process technology combining high performance with the power efficiencies of low-power Intel Core™ microarchitecture cores. The Quad-Core Intel® Xeon® Processor 5300 Series consists of two die, each containing two processor cores. All processors maintain the tradition of compatibility with IA-32 software. Some key features include on-die, 32 KB Level 1 instruction data caches per core and 4 MB shared Level 2 cache per die (8 MB Total Cache per processor) with Advanced Transfer Cache Architecture. The processor's Data Prefetch Logic speculatively fetches data to the L2 cache before an L1 cache requests occurs, resulting in reduced bus cycle penalties and improved performance. The 1333 MHz Front Side Bus (FSB) is a quad-pumped bus running off a 333 MHz system clock, which results in 10.6 GBytes per second data transfer. The 1066 MHz Front Side Bus is based on a 266 MHz system clock for an 8.5 GBytes per second data transfer rate. The Quad-Core Intel® Xeon® Processor X5300 Series offers higher clock frequencies than the Quad-Core Intel® Xeon® Processor E5300 Series for platforms that are targeted for the performance optimized segment. The Quad-Core Intel® Xeon® Processor L5300 Series is a lower voltage, lower power processor intended for ultra dense platforms.

Enhanced thermal and power management capabilities are implemented including Thermal Monitor 1 (TM1), Thermal Monitor 2 (TM2) and Enhanced Intel SpeedStep® Technology. TM1 and TM2 provide efficient and effective cooling in high temperature situations. Enhanced Intel SpeedStep® Technology provides power management capabilities to servers and workstations.

The Quad-Core Intel® Xeon® Processor 5300 Series features include Advanced Dynamic Execution, enhanced floating point and multi-media units, Streaming SIMD Extensions 2 (SSE2) and Streaming SIMD Extensions 3 (SSE3). Advanced Dynamic Execution improves speculative execution and branch prediction internal to the processor. The floating point and multi-media units include 128-bit wide registers and a separate register for data movement. SSE3 instructions provide highly efficient double-precision floating point, SIMD integer, and memory management operations.

The Quad-Core Intel® Xeon® Processor 5300 Series supports Intel® 64 architecture as an enhancement to Intel's IA-32 architecture. This enhancement allows the processor to execute operating systems and applications written to take advantage of the 64-bit extension technology. Further details on Intel 64 architecture and its programming model can be found in the Intel® 64 and IA-32 Architecture Software Developer's Manual.

In addition, the Quad-Core Intel® Xeon® Processor 5300 Series supports the Execute Disable Bit functionality. When used in conjunction with a supporting operating system, Execute Disable allows memory to be marked as executable or non executable. This feature can prevent some classes of viruses that exploit buffer overrun vulnerabilities and can thus help improve the overall security of the system. Further details on Execute Disable can be found at <http://www.intel.com/cd/ids/developer/asmo-na/eng/149308.htm>.

The Quad-Core Intel® Xeon® Processor 5300 Series supports Intel® Virtualization Technology for hardware-assisted virtualization within the processor. Intel Virtualization Technology is a set of hardware enhancements that can improve virtualization solutions. Intel Virtualization Technology is used in conjunction with Virtual Machine



Monitor software enabling multiple, independent software environments inside a single platform. Further details on Intel Virtualization Technology can be found at <http://developer.intel.com/technology/vt>.

The Quad-Core Intel® Xeon® Processor 5300 Series are intended for high performance server and workstation systems. The processors support a Dual Independent Bus (DIB) architecture with one processor on each bus, up to two processor sockets in a system. The DIB architecture provides improved performance by allowing increased FSB speeds and bandwidth. The processors will be packaged in an FC-LGA6 Land Grid Array package with 771 lands for improved power delivery. It utilizes a surface mount LGA771 socket that supports Direct Socket Loading (DSL).

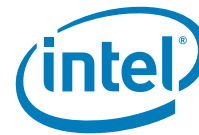
Table 1-1. Quad-Core Intel® Xeon® Processor 5300 Series Features

| # of Processor Cores | L1 Cache (per core) | L2 Advanced Transfer Cache | Front Side Bus Frequency | Package |
|----------------------|---------------------------------|---|--------------------------|----------------------|
| 4 | 32 KB instruction 32 KB data | 4MB Shared L2 Cache per die 8MB Total Cache | 1333 MHz 1066 MHz | FC-LGA6 771 Lands |

Quad-Core Intel® Xeon® Processor 5300 Series based platforms implement independent core voltage (V_{CC}) power planes for each processor. FSB termination voltage (V_{TT}) is shared and must connect to all FSB agents. The processor core voltage utilizes power delivery guidelines specified by VRM/EVRD 11.0 and its associated load line (see *Voltage Regulator Module (VRM) and Enterprise Voltage Regulator-Down (EVRD) 11.0 Design Guidelines* for further details). VRM/EVRD 11.0 will support the power requirements of all frequencies of the processors including Flexible Motherboard Guidelines (FMB) (see [Section 2.13.1](#)). Refer to the appropriate platform design guidelines for implementation details.

The Quad-Core Intel® Xeon® Processor 5300 Series support either 1333 or 1066 MHz Front Side Bus operation. The FSB utilizes a split-transaction, deferred reply protocol and Source-Synchronous Transfer (SST) of address and data to improve performance. The processor transfers data four times per bus clock (4X data transfer rate, as in AGP 4X). Along with the 4X data bus, the address bus can deliver addresses two times per bus clock and is referred to as a 'double-clocked' or a 2X address bus. In addition, the Request Phase completes in one clock cycle. Working together, the 4X data bus and 2X address bus provide a data bus bandwidth of up to 10.66 GBytes (1333 MHz) or 8.5 GBytes (1066 MHz) per second. The FSB is also used to deliver interrupts.

Signals on the FSB use Assisted Gunning Transceiver Logic (AGTL+) level voltages. [Section 2.1](#) contains the electrical specifications of the FSB while implementation details are fully described in the appropriate platform design guidelines (refer to [Section 1.3](#)).



1.1 Terminology

A '#' symbol after a signal name refers to an active low signal, indicating a signal is in the asserted state when driven to a low level. For example, when RESET# is low, a reset has been requested. Conversely, when NMI is high, a nonmaskable interrupt has occurred. In the case of signals where the name does not imply an active state but describes part of a binary sequence (such as *address* or *data*), the '#' symbol implies that the signal is inverted. For example, D[3:0] = 'HLHL' refers to a hex 'A', and D[3:0]# = 'LHLH' also refers to a hex 'A' (H= High logic level, L= Low logic level).

Commonly used terms are explained here for clarification:

- **Quad-Core Intel® Xeon® Processor 5300 Series** – Intel 64-bit microprocessor intended for dual processor servers and workstations. The Quad-Core Intel® Xeon® Processor 5300 Series is based on Intel's 65 nanometer process, in the FC-LGA6 package with four processor cores. For this document, "processor" is used as the generic term for the "Quad-Core Intel® Xeon® Processor 5300 Series". The term 'processors' and "Quad-Core Intel® Xeon® Processor 5300 Series" are inclusive of Quad-Core Intel® Xeon® Processor E5300 Series, Quad-Core Intel® Xeon® Processor X5300 Series and Quad-Core Intel® Xeon® Processor L5300 Series.
- **Quad-Core Intel® Xeon® Processor E5300 Series** – A mainstream performance version of the Quad-Core Intel® Xeon® Processor E5300 Series. For this document "Quad-Core Intel® Xeon® Processor E5300 Series" is used to call out specifications that are unique to the Quad-Core Intel® Xeon® Processor E5300 Series SKU.
- **Quad-Core Intel® Xeon® Processor X5300 Series** – An accelerated performance version of the Quad-Core Intel® Xeon® Processor X5300 Series. For this document "Quad-Core Intel® Xeon® Processor X5300 Series" is used to call out specifications that are unique to the Quad-Core Intel® Xeon® Processor X5300 Series SKU.
- **Quad-Core Intel® Xeon® Processor L5300 Series** - Intel 64-bit microprocessor intended for dual processor server blades and embedded servers. The Quad-Core Intel® Xeon® Processor L5300 Series is a lower voltage, lower power version of the Quad-Core Intel® Xeon® Processor L5300 Series. For this document "Quad-Core Intel® Xeon® Processor L5300 Series" is used to call out specifications that are unique to the Quad-Core Intel® Xeon® Processor L5300 Series.
- **FC-LGA6 (Flip Chip Land Grid Array) Package** – The Quad-Core Intel® Xeon® Processor 5300 Series package is a Land Grid Array, consisting of a processor core mounted on a pinless substrate with 771 lands, and includes an integrated heat spreader (IHS).
- **LGA771 socket** – The Quad-Core Intel® Xeon® Processor 5300 Series interfaces to the baseboard through this surface mount, 771 Land socket. See the *LGA771 Socket Design Guidelines* for details regarding this socket.
- **Processor core** – Processor core with integrated L1 cache. L2 cache and system bus interface are shared between the two cores on the die. All AC timing and signal integrity specifications are at the pads of the processor die.
- **FSB (Front Side Bus)** – The electrical interface that connects the processor to the chipset. Also referred to as the processor system bus or the system bus. All memory and I/O transactions as well as interrupt messages pass between the processor and chipset over the FSB.



- **Dual Independent Bus (DIB)** – A front side bus architecture with one processor on each bus, rather than a FSB shared between two processor agents. The DIB architecture provides improved performance by allowing increased FSB speeds and bandwidth.
- **Flexible Motherboard Guidelines (FMB)** – Are estimates of the maximum values the Quad-Core Intel® Xeon® Processor 5300 Series will have over certain time periods. The values are only estimates and actual specifications for future processors may differ.
- **Functional Operation** – Refers to the normal operating conditions in which all processor specifications, including DC, AC, FSB, signal quality, mechanical and thermal are satisfied.
- **Storage Conditions** – Refers to a non-operational state. The processor may be installed in a platform, in a tray, or loose. Processors may be sealed in packaging or exposed to free air. Under these conditions, processor lands should not be connected to any supply voltages, have any I/Os biased or receive any clocks. Upon exposure to “free air” (that is, unsealed packaging or a device removed from packaging material) the processor must be handled in accordance with moisture sensitivity labeling (MSL) as indicated on the packaging material.
- **Priority Agent** – The priority agent is the host bridge to the processor and is typically known as the chipset.
- **Symmetric Agent** – A symmetric agent is a processor which shares the same I/O subsystem and memory array, and runs the same operating system as another processor in a system. Systems using symmetric agents are known as Symmetric Multiprocessing (SMP) systems.
- **Integrated Heat Spreader (IHS)** – A component of the processor package used to enhance the thermal performance of the package. Component thermal solutions interface with the processor at the IHS surface.
- **Thermal Design Power** – Processor thermal solutions should be designed to meet this target. It is the highest expected sustainable power while running known power intensive real applications. TDP is not the maximum power that the processor can dissipate.
- **Intel® 64 Architecture** – Instruction set architecture and programming environment of Intel's 64-bit processors, which are a superset of and compatible with IA-32. This 64-bit instruction set architecture was formerly known as IA-32 with EM64T or Intel® EM64T.
- **Enhanced Intel SpeedStep® Technology** – Technology that provides power management capabilities to servers and workstations.
- **Platform Environment Control Interface (PECI)** – A proprietary one-wire bus interface that provides a communication channel between Intel processor and chipset components to external thermal monitoring devices, for use in fan speed control. PECI communicates readings from the processor's Digital Thermal Sensor (DTS). The replaces the thermal diode available in previous processors.
- **Intel® Virtualization Technology (Intel® VT)** – Processor virtualization which when used in conjunction with Virtual Machine Monitor software enables multiple, robust independent software environments inside a single platform.
- **VRM (Voltage Regulator Module)** – DC-DC converter built onto a module that interfaces with a card edge socket and supplies the correct voltage and current to the processor based on the logic state of the processor VID bits.



- **EVRD (Enterprise Voltage Regulator Down)** – DC-DC converter integrated onto the system board that provides the correct voltage and current to the processor based on the logic state of the processor VID bits.
- **V_{CC}** – The processor core power supply.
- **V_{SS}** – The processor ground.
- **V_{TT}** – FSB termination voltage. (Note: In some Intel processor EMTS documents, V_{TT} is instead called V_{CCP}.)

1.2 State of Data

The data contained within this document is the most accurate information available by the publication date of this document.

1.3 References

Material and concepts available in the following documents may be beneficial when reading this document:

| Document | Document Number ¹ | Notes |
|---|------------------------------|-------|
| <i>AP-485, Intel® Processor Identification and the CPUID Instruction</i> | 241618 | 2 |
| <i>Intel® 64 and IA-32 Architectures Software Developer's Manual, Volume 1</i> | 253665 | 2 |
| <i>Intel® 64 and IA-32 Architectures Software Developer's Manual, Volume 2A</i> | 253666 | |
| <i>Intel® 64 and IA-32 Architectures Software Developer's Manual, Volume 2B</i> | 253667 | |
| <i>Intel® 64 and IA-32 Architectures Software Developer's Manual, Volume 3A</i> | 253668 | |
| <i>Intel® 64 and IA-32 Architectures Software Developer's Manual, Volume 3B</i> | 253669 | |
| <i>IA-32 Intel® Architecture Optimization Reference Manual</i> | 248966 | 2 |
| <i>Intel® Virtualization Technology Specification for the IA-32 Intel® Architecture</i> | C97063 | 2 |
| <i>Quad-Core Intel® Xeon® Processor 5300 Series Specification Update</i> | | 3 |



| Document | Document Number ¹ | Notes |
|--|------------------------------|-------|
| <i>Quad-Core Intel® Xeon® Processor 5300 Series Thermal/Mechanical Design Guidelines</i> | | |
| <i>Clovertown Processor Boundary Scan Descriptive Language (BSDL) Model</i> | | 10 |
| <i>Debug Port Design Guide for UP/DP Systems</i> | | 1 |

Notes: Contact your Intel representative for the latest revision of these documents.
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2 Electrical Specifications

2.1 Front Side Bus and GTLREF

Most Quad-Core Intel® Xeon® Processor 5300 Series FSB signals use Assisted Gunning Transceiver Logic (AGTL+) signaling technology. This technology provides improved noise margins and reduced ringing through low voltage swings and controlled edge rates. AGTL+ buffers are open-drain and require pull-up resistors to provide the high logic level and termination. AGTL+ output buffers differ from GTL+ buffers with the addition of an active PMOS pull-up transistor to “assist” the pull-up resistors during the first clock of a low-to-high voltage transition. Platforms implement a termination voltage level for AGTL+ signals defined as V_{TT} . Because platforms implement separate power planes for each processor (and chipset), separate V_{CC} and V_{TT} supplies are necessary. This configuration allows for improved noise tolerance as processor frequency increases. Speed enhancements to data and address buses have made signal integrity considerations and platform design methods even more critical than with previous processor families. Design guidelines for the processor FSB are detailed in the appropriate platform design guidelines (refer to [Section 1.3](#)).

The AGTL+ inputs require reference voltages (GTLREF_DATA_MID, GTLREF_DATA_END, GTLREF_ADD_MID and GTLREF_ADD_END) which are used by the receivers to determine if a signal is a logical 0 or a logical 1. GTLREF_DATA_MID and GTLREF_DATA_END are used for the 4X front side bus signaling group and GTLREF_ADD_MID and GTLREF_ADD_END are used for the 2X and common clock front side bus signaling groups. GTLREF_DATA_MID, GTLREF_DATA_END, GTLREF_ADD_MID, and GTLREF_ADD_END must be generated on the baseboard (See [Table 2-18](#) for GTLREF_DATA_MID, GTLREF_DATA_END, GTLREF_ADD_MID and GTLREF_ADD_END specifications). Refer to the applicable platform design guidelines for details. Termination resistors (R_{TT}) for AGTL+ signals are provided on the processor silicon and are terminated to V_{TT} . The on-die termination resistors are always enabled on the processor to control reflections on the transmission line. Intel chipsets also provide on-die termination, thus eliminating the need to terminate the bus on the baseboard for most AGTL+ signals.

Some FSB signals do not include on-die termination (R_{TT}) and must be terminated on the baseboard. See [Table 2-7](#) and [Table 2-8](#) for details regarding these signals.

The AGTL+ bus depends on incident wave switching. Therefore, timing calculations for AGTL+ signals are based on flight time as opposed to capacitive deratings. Analog signal simulation of the FSB, including trace lengths, is highly recommended when designing a system. Contact your Intel Field Representative to obtain the applicable signal integrity models, which includes buffer and package models.



2.2 Power and Ground Lands

For clean on-chip processor core power distribution, the processor has 223 V_{CC} (power) and 267 V_{SS} (ground) inputs. All V_{CC} lands must be connected to the processor power plane, while all V_{SS} lands must be connected to the system ground plane. The processor V_{CC} lands must be supplied with the voltage determined by the processor Voltage Identification (VID) signals. See [Table 2-3](#) for VID definitions.

Twenty two lands are specified as V_{TT} , which provide termination for the FSB and provides power to the I/O buffers. The platform must implement a separate supply for these lands which meets the V_{TT} specifications outlined in [Table 2-12](#).

2.3 Decoupling Guidelines

Due to its large number of transistors and high internal clock speeds, the processor is capable of generating large average current swings between low and full power states. This may cause voltages on power planes to sag below their minimum values if bulk decoupling is not adequate. Larger bulk storage (C_{BULK}), such as electrolytic capacitors, supply current during longer lasting changes in current demand by the component, such as coming out of an idle condition. Similarly, they act as a storage well for current when entering an idle condition from a running condition. Care must be taken in the baseboard design to ensure that the voltage provided to the processor remains within the specifications listed in [Table 2-12](#). Failure to do so can result in timing violations or reduced lifetime of the component. For further information and guidelines, refer to the appropriate platform design guidelines.

2.3.1 V_{CC} Decoupling

V_{CC} regulator solutions need to provide bulk capacitance with a low Effective Series Resistance (ESR), and the baseboard designer must assure a low interconnect resistance from the regulator (EVRD or VRM pins) to the LGA771 socket. Bulk decoupling must be provided on the baseboard to handle large current swings. The power delivery solution must insure the voltage and current specifications are met (as defined in [Table 2-12](#)). For further information regarding power delivery, decoupling and layout guidelines, refer to the appropriate platform design guidelines.

2.3.2 V_{TT} Decoupling

Bulk decoupling must be provided on the baseboard. Decoupling solutions must be sized to meet the expected load. To insure optimal performance, various factors associated with the power delivery solution must be considered including regulator type, power plane and trace sizing, and component placement. A conservative decoupling solution consists of a combination of low ESR bulk capacitors and high frequency ceramic capacitors. For further information regarding power delivery, decoupling and layout guidelines, refer to the appropriate platform design guidelines.



2.3.3 Front Side Bus AGTL+ Decoupling

The processor integrates signal termination on the die, as well as a portion of the required high frequency decoupling capacitance on the processor package. However, additional high frequency capacitance must be added to the baseboard to properly decouple the return currents from the FSB. Bulk decoupling must also be provided by the baseboard for proper AGTL+ bus operation. Decoupling guidelines are described in the appropriate platform design guidelines.

2.4 Front Side Bus Clock (BCLK[1:0]) and Processor Clocking

BCLK[1:0] directly controls the FSB interface speed as well as the core frequency of the processor. As in previous processor generations, the processor core frequency is a multiple of the BCLK[1:0] frequency. The processor bus ratio multiplier is set during manufacturing. The default setting is for the maximum speed of the processor. It is possible to override this setting using software (see the *Conroe and Woodcrest Processor Family BIOS Writer's Guide*). This permits operation at lower frequencies than the processor's tested frequency.

The processor core frequency is configured during reset by using values stored internally during manufacturing. The stored value sets the highest bus fraction at which the particular processor can operate. If lower speeds are desired, the appropriate ratio can be configured via the CLOCK_FLEX_MAX Model Specific Register (MSR). For details of operation at core frequencies lower than the maximum rated processor speed, refer to the *Intel® 64 and IA-32 Architectures Software Developer's Manual*.

Clock multiplying within the processor is provided by the internal phase locked loop (PLL), which requires a constant frequency BCLK[1:0] input, with exceptions for spread spectrum clocking. Processor DC and AC specifications for the BCLK[1:0] inputs are provided in [Table 2-19](#). These specifications must be met while also meeting signal integrity requirements as outlined in [Table 2-19](#). The processor utilizes differential clocks.



Table 2-1. Core Frequency to FSB Multiplier Configuration

| Core Frequency to FSB Multiplier | Core Frequency with 333.333 MHz Bus Clock | Core Frequency with 266.666 MHz Bus Clock | Notes |
|----------------------------------|---|---|------------|
| 1/6 | 2 GHz | 1.60 GHz | 1, 2, 3, 4 |
| 1/7 | 2.33 GHz | 1.86 GHz | 1, 2, 3 |
| 1/8 | 2.66 GHz | 2.13 GHz | 1, 2, 3 |
| 1/9 | 3 GHz | 2.40 GHz | 1, 2, 3 |
| 1/10 | 3.33 GHz | 2.66 GHz | 1, 2, 3 |
| 1/11 | 3.66 GHz | 2.93 GHz | 1, 2, 3 |
| 1/12 | 4 GHz | 3.20 GHz | 1, 2, 3 |

Notes:

1. Individual processors operate only at or below the frequency marked on the package.
2. Listed frequencies are not necessarily committed production frequencies.
3. For valid processor core frequencies, refer to the *Quad-Core Intel® Xeon® Processor 5300 Series Specification Update*.
4. The lowest bus ratio supported is 1/6.

2.4.1 Front Side Bus Frequency Select Signals (BSEL[2:0])

Upon power up, the FSB frequency is set to the maximum supported by the individual processor. BSEL[2:0] are CMOS outputs which must be pulled up to V_{TT} , and are used to select the FSB frequency. Please refer to [Table 2-15](#) for DC specifications. [Table 2-2](#) defines the possible combinations of the signals and the frequency associated with each combination. The frequency is determined by the processor(s), chipset, and clock synthesizer. All FSB agents must operate at the same core and FSB frequency. See the appropriate platform design guidelines for further details.

Table 2-2. BSEL[2:0] Frequency Table

| BSEL2 | BSEL1 | BSEL0 | Bus Clock Frequency |
|-------|-------|-------|---------------------|
| 0 | 0 | 0 | 266.666 MHz |
| 0 | 0 | 1 | Reserved |
| 0 | 1 | 0 | Reserved |
| 0 | 1 | 1 | Reserved |
| 1 | 0 | 0 | 333.333 MHz |
| 1 | 0 | 1 | Reserved |
| 1 | 1 | 0 | Reserved |
| 1 | 1 | 1 | Reserved |



2.4.2 PLL Power Supply

An on-die PLL filter solution is implemented on the processor. The V_{CCPLL} input is used to provide power to the on chip PLL of the processor. Please refer to [Table 2-12](#) for DC specifications. Refer to the appropriate platform design guidelines for decoupling and routing guidelines.

2.5 Voltage Identification (VID)

The Voltage Identification (VID) specification for the processor is defined by the *Voltage Regulator Module (VRM) and Enterprise Voltage Regulator-Down (EVRD) 11.0 Design Guidelines*. The voltage set by the VID signals is the reference VR output voltage to be delivered to the processor Vcc pins. Please refer to [Table 2-16](#) for the DC specifications for these signals. A voltage range is provided in [Table 2-12](#) and changes with frequency. The specifications have been set such that one voltage regulator can operate with all supported frequencies.

Individual processor VID values may be calibrated during manufacturing such that two devices at the same core frequency may have different default VID settings. This is reflected by the VID range values provided in [Table 2-3](#).

The Quad-Core Intel® Xeon® Processor 5300 Series uses six voltage identification signals, VID[6:1], to support automatic selection of power supply voltages. [Table 2-3](#) specifies the voltage level corresponding to the state of VID[6:1]. A '1' in this table refers to a high voltage level and a '0' refers to a low voltage level. The definition provided in [Table 2-3](#) is not related in any way to previous Intel® Xeon® processors or voltage regulator designs. If the processor socket is empty (VID[6:1] = 111111), or the voltage regulation circuit cannot supply the voltage that is requested, the voltage regulator must disable itself. See the *Voltage Regulator Module (VRM) and Enterprise Voltage Regulator-Down (EVRD) 11.0 Design Guidelines* for further details.

Although the *Voltage Regulator Module (VRM) and Enterprise Voltage Regulator-Down (EVRD) 11.0 Design Guidelines* defines VID [7:0], VID 7 and VID 0 are not used on the Quad-Core Intel® Xeon® Processor 5300 Series. Please refer to the *Clovertown, Harpertown, and Wolfdale-DP Processors Compatibility Design Guide* for details.

The Quad-Core Intel® Xeon® Processor 5300 Series provide the ability to operate while transitioning to an adjacent VID and its associated processor core voltage (V_{CC}). This will represent a DC shift in the load line. It should be noted that a low-to-high or high-to-low voltage state change may result in as many VID transitions as necessary to reach the target core voltage. Transitions above the specified VID are not permitted. [Table 2-12](#) includes VID step sizes and DC shift ranges. Minimum and maximum voltages must be maintained as shown in [Table 2-13](#).

The VRM or EVRD utilized must be capable of regulating its output to the value defined by the new VID. DC specifications for dynamic VID transitions are included in [Table 2-12](#). Refer to the *Voltage Regulator Module (VRM) and Enterprise Voltage Regulator-Down (EVRD) 11.0 Design Guidelines* for further details.

Power source characteristics must be guaranteed to be stable whenever the supply to the voltage regulator is stable.



Table 2-3. Voltage Identification Definition

| HEX | VID6 400 mV | VID5 200 mV | VID4 100 mV | VID3 50 mV | VID2 25 mV | VID1 12.5 mV | V _{CC_MAX} | HEX | VID6 400 mV | VID5 200 mV | VID4 100 mV | VID3 50 mV | VID2 25 mV | VID1 12.5 mV | V _{CC_MAX} |
|-----|-------------------|-------------------|-------------------|------------------|------------------|--------------------|---------------------|-----|-------------------|-------------------|-------------------|------------------|------------------|--------------------|---------------------|
| 7A | 1 | 1 | 1 | 1 | 0 | 1 | 0.8500 | 3C | 0 | 1 | 1 | 1 | 1 | 0 | 1.2375 |
| 78 | 1 | 1 | 1 | 1 | 0 | 0 | 0.8625 | 3A | 0 | 1 | 1 | 1 | 0 | 1 | 1.2500 |
| 76 | 1 | 1 | 1 | 0 | 1 | 1 | 0.8750 | 38 | 0 | 1 | 1 | 1 | 0 | 0 | 1.2625 |
| 74 | 1 | 1 | 1 | 0 | 1 | 0 | 0.8875 | 36 | 0 | 1 | 1 | 0 | 1 | 1 | 1.2750 |
| 72 | 1 | 1 | 1 | 0 | 0 | 1 | 0.9000 | 34 | 0 | 1 | 1 | 0 | 1 | 0 | 1.2875 |
| 70 | 1 | 1 | 1 | 0 | 0 | 0 | 0.9125 | 32 | 0 | 1 | 1 | 0 | 0 | 1 | 1.3000 |
| 6E | 1 | 1 | 0 | 1 | 1 | 1 | 0.9250 | 30 | 0 | 1 | 1 | 0 | 0 | 0 | 1.3125 |
| 6C | 1 | 1 | 0 | 1 | 1 | 0 | 0.9375 | 2E | 0 | 1 | 0 | 1 | 1 | 1 | 1.3250 |
| 6A | 1 | 1 | 0 | 1 | 0 | 1 | 0.9500 | 2C | 0 | 1 | 0 | 1 | 1 | 0 | 1.3375 |
| 68 | 1 | 1 | 0 | 1 | 0 | 0 | 0.9625 | 2A | 0 | 1 | 0 | 1 | 0 | 1 | 1.3500 |
| 66 | 1 | 1 | 0 | 0 | 1 | 1 | 0.9750 | 28 | 0 | 1 | 0 | 1 | 0 | 0 | 1.3625 |
| 64 | 1 | 1 | 0 | 0 | 1 | 0 | 0.9875 | 26 | 0 | 1 | 0 | 0 | 1 | 1 | 1.3750 |
| 62 | 1 | 1 | 0 | 0 | 0 | 1 | 1.0000 | 24 | 0 | 1 | 0 | 0 | 1 | 0 | 1.3875 |
| 60 | 1 | 1 | 0 | 0 | 0 | 0 | 1.0125 | 22 | 0 | 1 | 0 | 0 | 0 | 1 | 1.4000 |
| 5E | 1 | 0 | 1 | 1 | 1 | 1 | 1.0250 | 20 | 0 | 1 | 0 | 0 | 0 | 0 | 1.4125 |
| 5C | 1 | 0 | 1 | 1 | 1 | 0 | 1.0375 | 1E | 0 | 0 | 1 | 1 | 1 | 1 | 1.4250 |
| 5A | 1 | 0 | 1 | 1 | 0 | 1 | 1.0500 | 1C | 0 | 0 | 1 | 1 | 1 | 0 | 1.4375 |
| 58 | 1 | 0 | 1 | 1 | 0 | 0 | 1.0625 | 1A | 0 | 0 | 1 | 1 | 0 | 1 | 1.4500 |
| 56 | 1 | 0 | 1 | 0 | 1 | 1 | 1.0750 | 18 | 0 | 0 | 1 | 1 | 0 | 0 | 1.4625 |
| 54 | 1 | 0 | 1 | 0 | 1 | 0 | 1.0875 | 16 | 0 | 0 | 1 | 0 | 1 | 1 | 1.4750 |
| 52 | 1 | 0 | 1 | 0 | 0 | 1 | 1.1000 | 14 | 0 | 0 | 1 | 0 | 1 | 0 | 1.4875 |
| 50 | 1 | 0 | 1 | 0 | 0 | 0 | 1.1125 | 12 | 0 | 0 | 1 | 0 | 0 | 1 | 1.5000 |
| 4E | 1 | 0 | 0 | 1 | 1 | 1 | 1.1250 | 10 | 0 | 0 | 1 | 0 | 0 | 0 | 1.5125 |
| 4C | 1 | 0 | 0 | 1 | 1 | 0 | 1.1375 | 0E | 0 | 0 | 0 | 1 | 1 | 1 | 1.5250 |
| 4A | 1 | 0 | 0 | 1 | 0 | 1 | 1.1500 | 0C | 0 | 0 | 0 | 1 | 1 | 0 | 1.5375 |
| 48 | 1 | 0 | 0 | 1 | 0 | 0 | 1.1625 | 0A | 0 | 0 | 0 | 1 | 0 | 1 | 1.5500 |
| 46 | 1 | 0 | 0 | 0 | 1 | 1 | 1.1750 | 08 | 0 | 0 | 0 | 1 | 0 | 0 | 1.5625 |
| 44 | 1 | 0 | 0 | 0 | 1 | 0 | 1.1875 | 06 | 0 | 0 | 0 | 0 | 1 | 1 | 1.5750 |
| 42 | 1 | 0 | 0 | 0 | 0 | 1 | 1.2000 | 04 | 0 | 0 | 0 | 0 | 1 | 0 | 1.5875 |
| 40 | 1 | 0 | 0 | 0 | 0 | 0 | 1.2125 | 02 | 0 | 0 | 0 | 0 | 0 | 1 | 1.6000 |
| 3E | 0 | 1 | 1 | 1 | 1 | 1 | 1.2250 | 00 | 0 | 0 | 0 | 0 | 0 | 0 | OFF ¹ |

Notes:

1. When the "111111" VID pattern is observed, the voltage regulator output should be disabled.
2. Shading denotes the expected VID range of the Quad-Core Intel® Xeon® Processor 5300 Series.
3. The VID range includes VID transitions that may be initiated by thermal events, assertion of the FORCEPR# signal (see Section 6.2.3), Extended HALT state transitions (see Section 7.2.2), or Enhanced Intel SpeedStep® Technology transitions (see Section 7.3). **The Extended HALT state must be enabled for the processor to remain within its specifications.**
4. Once the VRM/EVRD is operating after power-up, if either the Output Enable signal is de-asserted or a specific VID off code is received, the VRM/EVRD must turn off its output (the output should go to high impedance) within 500 ms and latch off until power is cycled. Refer to *Voltage Regulator Module (VRM) and Enterprise Voltage Regulator-Down (EVRD) 11.0 Design Guidelines*.


Table 2-4. Loadline Selection Truth Table for LL_ID[1:0]

| LL_ID1 | LL_ID0 | Description |
|--------|--------|--|
| 0 | 0 | Reserved |
| 0 | 1 | Dual-Core Intel® Xeon® Processor 5000 Series Dual-Core Intel® Xeon® Processor 5100 Series |
| 1 | 0 | Reserved |
| 1 | 1 | All Quad-Core Intel® Xeon® Processor 5300 Series |

Note: The LL_ID[1:0] signals are used by the platform to select the correct loadline slope for the processor.

Table 2-5. Market Segment Selection Truth Table for MS_ID[1:0]

| MS_ID1 | MS_ID0 | Description |
|--------|--------|--|
| 0 | 0 | Dual-Core Intel® Xeon® Processor 5000 Series |
| 0 | 1 | Dual-Core Intel® Xeon® Processor 5100 Series |
| 1 | 0 | All Quad-Core Intel® Xeon® Processor 5300 Series |
| 1 | 1 | Reserved |

Note: The MS_ID[1:0] signals are provided to indicate the Market Segment for the processor and may be used for future processor compatibility or for keying.

2.6 Reserved, Unused, or Test Signals

All Reserved signals must remain unconnected. Connection of these signals to V_{CC} , V_{TT} , V_{SS} , or to any other signal (including each other) can result in component malfunction or incompatibility with future processors. See [Section 4](#) for a land listing of the processor and the location of all Reserved signals.

For reliable operation, always connect unused inputs or bidirectional signals to an appropriate signal level. Unused active high inputs, should be connected through a resistor to ground (V_{SS}). Unused outputs can be left unconnected; however, this may interfere with some TAP functions, complicate debug probing, and prevent boundary scan testing. A resistor must be used when tying bidirectional signals to power or ground. When tying any signal to power or ground, a resistor will also allow for system testability. Resistor values should be within $\pm 20\%$ of the impedance of the baseboard trace for FSB signals, unless otherwise noticed in the appropriate platform design guidelines. For unused AGTL+ input or I/O signals, use pull-up resistors of the same value as the on-die termination resistors (R_{TT}). For details see [Table 2-18](#).

TAP, Asynchronous GTL+ inputs, and Asynchronous GTL+ outputs do not include on-die termination. Inputs and utilized outputs must be terminated on the baseboard. Unused outputs may be terminated on the baseboard or left unconnected. Note that leaving unused outputs unterminated may interfere with some TAP functions, complicate debug probing, and prevent boundary scan testing. Signal termination for these signal types is discussed in the appropriate platform design guidelines.

For each processor socket, connect the TESTIN1 and TESTIN2 signals together, then terminate the net with a 51 Ω resistor to V_{TT} .

The TESTHI signals must be tied to the processor V_{TT} using a matched resistor, where a matched resistor has a resistance value within $\pm 20\%$ of the impedance of the board transmission line traces. For example, if the trace impedance is 50 Ω then a value between 40 Ω and 60 Ω is required.



The TESTHI signals may use individual pull-up resistors or be grouped together as detailed below. A matched resistor must be used for each group:

- TESTHI[1:0] - can be grouped together with a single pull-up to V_{TT}
- TESTHI[7:2] - can be grouped together with a single pull-up to V_{TT}
- TESTHI10 – cannot be grouped with other TESTHI signals
- TESTHI11 – cannot be grouped with other TESTHI signals

2.7 Front Side Bus Signal Groups

The FSB signals have been combined into groups by buffer type. AGTL+ input signals have differential input buffers, which use GTLREF_DATA_MID, GTLREF_DATA_END, GTLREF_ADD_MID, and GTLREF_ADD_END as reference levels. In this document, the term “AGTL+ Input” refers to the AGTL+ input group as well as the AGTL+ I/O group when receiving. Similarly, “AGTL+ Output” refers to the AGTL+ output group as well as the AGTL+ I/O group when driving. AGTL+ asynchronous outputs can become active anytime and include an active PMOS pull-up transistor to assist during the first clock of a low-to-high voltage transition.

With the implementation of a source synchronous data bus comes the need to specify two sets of timing parameters. One set is for common clock signals whose timings are specified with respect to rising edge of BCLK0 (ADS#, HIT#, HITM#, etc.) and the second set is for the source synchronous signals which are relative to their respective strobe lines (data and address) as well as rising edge of BCLK0. Asynchronous signals are still present (A20M#, IGNNE#, etc.) and can become active at any time during the clock cycle. Table 2-6 identifies which signals are common clock, source synchronous and asynchronous.

Table 2-6. FSB Signal Groups (Sheet 1 of 2)

| Signal Group | Type | Signals ¹ | | | | | | | | | | | | | | |
|------------------------------|------------------------------|--|-------------------|-------------------|---|---------|-----------|---------|-----------------|------------------|------------------|------------------|------------------|------------------|------------------|------------------|
| AGTL+ Common Clock Input | Synchronous to BCLK[1:0] | BPRI#, DEFER#, RESET#, RS[2:0]#, RSP#, TRDY#; | | | | | | | | | | | | | | |
| AGTL+ Common Clock Output | Synchronous to BCLK[1:0] | BPM4#, BPM[2:1]#, BPMb[2:1]# | | | | | | | | | | | | | | |
| AGTL+ Common Clock I/O | Synchronous to BCLK[1:0] | ADS#, AP[1:0]#, BINIT# ² , BNR# ² , BPM5#, BPM3#, BPM0#, BPMb3#, BPMb0#, BR[1:0]#, DBSY#, DP[3:0]#, DRDY#, HIT# ² , HITM# ² , LOCK#, MCERR# ² | | | | | | | | | | | | | | |
| AGTL+ Source Synchronous I/O | Synchronous to assoc. strobe | <table border="1"> <thead> <tr> <th>Signals</th> <th>Associated Strobe</th> </tr> </thead> <tbody> <tr> <td>REQ[4:0]#, A[16:3]#, A[37:36]#³</td> <td>ADSTB0#</td> </tr> <tr> <td>A[35:17]#</td> <td>ADSTB1#</td> </tr> <tr> <td>D[15:0]#, DBI0#</td> <td>DSTBP0#, DSTBN0#</td> </tr> <tr> <td>D[31:16]#, DBI1#</td> <td>DSTBP1#, DSTBN1#</td> </tr> <tr> <td>D[47:32]#, DBI2#</td> <td>DSTBP2#, DSTBN2#</td> </tr> <tr> <td>D[63:48]#, DBI3#</td> <td>DSTBP3#, DSTBN3#</td> </tr> </tbody> </table> | Signals | Associated Strobe | REQ[4:0]#, A[16:3]#, A[37:36]# ³ | ADSTB0# | A[35:17]# | ADSTB1# | D[15:0]#, DBI0# | DSTBP0#, DSTBN0# | D[31:16]#, DBI1# | DSTBP1#, DSTBN1# | D[47:32]#, DBI2# | DSTBP2#, DSTBN2# | D[63:48]#, DBI3# | DSTBP3#, DSTBN3# |
| | | Signals | Associated Strobe | | | | | | | | | | | | | |
| | | REQ[4:0]#, A[16:3]#, A[37:36]# ³ | ADSTB0# | | | | | | | | | | | | | |
| | | A[35:17]# | ADSTB1# | | | | | | | | | | | | | |
| | | D[15:0]#, DBI0# | DSTBP0#, DSTBN0# | | | | | | | | | | | | | |
| | | D[31:16]#, DBI1# | DSTBP1#, DSTBN1# | | | | | | | | | | | | | |
| | | D[47:32]#, DBI2# | DSTBP2#, DSTBN2# | | | | | | | | | | | | | |
| D[63:48]#, DBI3# | DSTBP3#, DSTBN3# | | | | | | | | | | | | | | | |
| AGTL+ Strobes I/O | Synchronous to BCLK[1:0] | ADSTB[1:0]#, DSTBP[3:0]#, DSTBN[3:0]# | | | | | | | | | | | | | | |
| Open Drain Output | Asynchronous | FERR#/PBE#, IERR#, PROCHOT#, THERMTRIP# | | | | | | | | | | | | | | |



Table 2-6. FSB Signal Groups (Sheet 2 of 2)

| Signal Group | Type | Signals ¹ |
|--------------------------|--------------------|---|
| CMOS Asynchronous Input | Asynchronous | A20M#, FORCEPR#, IGNNE#, INIT#, LINTO/ INTR, LINT1/NMI, PWGOOD, SMI#, STPCLK#, |
| CMOS Asynchronous Output | Asynchronous | BSEL[2:0], VID[6:1] |
| FSB Clock | Clock | BCLK[1:0] |
| TAP Input | Synchronous to TCK | TCK, TDI, TMS, TRST# |
| TAP Output | Synchronous to TCK | TDO |
| Power/Other | Power/Other | COMP[3:0], GTLREF_ADD_MID, GTLREF_ADD_END, GTLREF_DATA_MID, GTLREF_DATA_END, LL_ID[1:0], MS_ID[1:0], PECI, RESERVED, SKTOCC#, TESTHI[11:10], TESTHI[7:0], TESTIN1, TESTIN2, VCC, VCC_DIE_SENSE, VCC_DIE_SENSE2, VCCPLL, VID_SELECT, VSS_DIE_SENSE, VSS_DIE_SENSE2, VSS, VTT, VTT_OUT, VTT_SEL |

Notes:

1. Refer to [Section 5](#) for signal descriptions.
2. These signals may be driven simultaneously by multiple agents (Wired-OR).
3. Not all Quad-Core Intel® Xeon® Processor 5300 Series support the additional signals A[37:36]#. Processors that support these signals will be outlined in the *Quad-Core Intel® Xeon® Processor 5300 Series NDA Specification Update*.

[Table 2-7](#) and [Table 2-8](#) outline the signals which include on-die termination (R_{TT}). [Table 2-7](#) denotes AGTL+ signals, while [Table 2-8](#) outlines non AGTL+ signals including open drain signals. [Table 2-9](#) provides signal reference voltages.

Table 2-7. AGTL+ Signal Description Table

| AGTL+ signals with R _{TT} | AGTL+ signals with no R _{TT} |
|---|---|
| A[37:3]# ¹ , ADS#, ADSTB[1:0]#, AP[1:0]#, BINIT#, BNR#, BPRI#, D[63:0]#, DBI[3:0]#, DBSY#, DEFER#, DP[3:0]#, DRDY#, DSTBN[3:0]#, DSTBP[3:0]#, HIT#, HITM#, LOCK#, MCERR#, REQ[4:0]#, RS[2:0]#, RSP#, TRDY# | BPM[5:0]#, BPMb[3:0]#, RESET#, BR[1:0]# |

Note:

1. Not all Quad-Core Intel® Xeon® Processor 5300 Series support the additional signals A[37:36]#. Processors that support these signals will be outlined in the *Quad-Core Intel® Xeon® Processor 5300 Series NDA Specification Update*.

Table 2-8. Non AGTL+ Signal Description Table

| Signals with R _{TT} | Signals with no R _{TT} |
|---|---|
| FORCEPR# ¹ , PROCHOT# ¹ | A20M#, BCLK[1:0], BSEL[2:0], COMP[3:0], FERR#/ PBE#, GTLREF_ADD_MID, GTLREF_ADD_END, GTLREF_DATA_MID, GTLREF_DATA_END, IERR#, IGNNE#, INIT#, LINTO/INTR, LINT1/NMI, LL_ID[1:0], MS_ID[1:0], PECI, PWGOOD, SKTOCC#, SMI#, STPCLK#, TCK, TDI, TDO, TESTHI[11:10], TESTHI[7:0], TESTIN1, TESTIN2, THERMTRIP#, TMS, TRST#, VCC_DIE_SENSE, VCC_DIE_SENSE2, VID[6:1], VID_SELECT, VSS_DIE_SENSE, VSS_DIE_SENSE2, VTT_SEL |

Note:

1. Signals that have a 50 Ω pullup to V_{TT} on package.



Table 2-9. Signal Reference Voltages

| GTLREF | CMOS |
|--|---|
| A[37:3]# ¹ , ADS#, ADSTB[1:0]#, AP[1:0]#, BINIT#, BNR#, BPM[5:0]#, BPMb[3:0]#, BPRI#, BR[1:0]#, D[63:0]#, DBI[3:0]#, DBSY#, DEFER#, DP[3:0]#, DRDY#, DSTBN[3:0]#, DSTBP[3:0]#, HIT#, HITM#, LOCK#, MCERR#, RESET#, REQ[4:0]#, RS[2:0]#, RSP#, TRDY# | A20M#, FORCEPR#, IGNNE#, INIT#, LINT0/INTR, LINT1/NMI, PWRGOOD, SMI#, STPCLK#, TCK, TDI, TMS, TRST# |

Note:

- Not all Quad-Core Intel® Xeon® Processor 5300 Series support the additional signals A[37:36]#. Processors that support these signals will be outlined in the *Quad-Core Intel® Xeon® Processor 5300 Series NDA Specification Update*.

2.8 CMOS Asynchronous and Open Drain Asynchronous Signals

Legacy input signals such as A20M#, IGNNE#, INIT#, SMI#, and STPCLK# utilize CMOS input buffers. Legacy output signals such as FERR#/PBE#, IERR#, PROCHOT#, and THERMTRIP# utilize open drain output buffers. All of the CMOS and Open Drain signals are required to be asserted/deasserted for at least eight BCLKs in order for the processor to recognize the proper signal state. See [Section 2.13](#) for the DC specifications. See [Section 7](#) for additional timing requirements for entering and leaving the low power states.

2.9 Test Access Port (TAP) Connection

Due to the voltage levels supported by other components in the Test Access Port (TAP) logic, it is recommended that the processor(s) be first in the TAP chain and followed by any other components within the system. A translation buffer should be used to connect to the rest of the chain unless one of the other components is capable of accepting an input of the appropriate voltage. Similar considerations must be made for TCK, TDO, TMS, and TRST#. Two copies of each signal may be required with each driving a different voltage level.

2.10 Platform Environmental Control Interface (PECI) DC Specifications

PECI is an Intel proprietary one-wire interface that provides a communication channel between Intel processor and external thermal monitoring devices. The Quad-Core Intel® Xeon® Processor 5300 Series contains Digital Thermal Sensors (DTS) distributed throughout the die. These sensors are implemented as analog-to-digital converters calibrated at the factor for reasonable accuracy to provide a digital representation of relative processor temperature. PECI provides an interface to relay the highest DTS temperature within a die to external management devices for thermal/fan speed control. More detailed information may be found in the *Platform Environment Control Interface (PECI) External Architecture Specification*.



2.10.1 DC Characteristics

A PECEI device interface operates at a nominal voltage set by V_{TT} . The set of DC electrical specifications shown in Table 2-10 is used with devices normally operating from a V_{TT} interface supply. V_{TT} nominal levels will vary between processor families. All PECEI devices will operate at the V_{TT} level determined by the processor installed in the system. For V_{TT} specifications, refer to Table 2-12.

Table 2-10. PECEI DC Electrical Limits

| Symbol | Definition and Conditions | Min | Max | Units | Notes ¹ |
|------------------|---|------------------|------------------|-----------|--------------------|
| V_{in} | Input Voltage Range | -0.150 | V_{TT} | V | |
| $V_{hysteresis}$ | Hysteresis | $0.1 * V_{TT}$ | N/A | V | |
| V_N | Negative-edge threshold voltage | $0.275 * V_{TT}$ | $0.500 * V_{TT}$ | V | |
| V_P | Positive-edge threshold voltage | $0.550 * V_{TT}$ | $0.725 * V_{TT}$ | V | |
| I_{source} | High level output source ($V_{OH} = 0.75 * V_{TT}$) | -6.0 | N/A | mA | |
| I_{sink} | Low level output sink ($V_{OL} = 0.25 * V_{TT}$) | 0.5 | 1.0 | mA | |
| I_{leak+} | High impedance state leakage to V_{TT} ($V_{leak} = V_{OL}$) | N/A | 50 | μA | 2 |
| I_{leak-} | High impedance leakage to GND ($V_{leak} = V_{OH}$) | N/A | 10 | μA | 2 |
| C_{bus} | Bus capacitance per node | N/A | 10 | pF | 3 |
| V_{noise} | Signal noise immunity above 300 MHz | $0.1 * V_{TT}$ | N/A | V_{p-p} | |

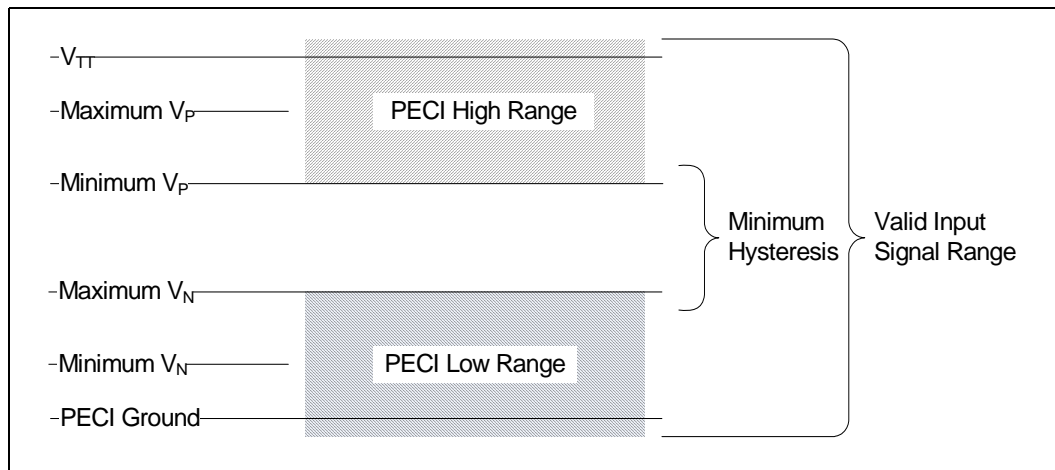
Note:

1. V_{TT} supplies the PECEI interface. PECEI behavior does not affect V_{TT} min/max specifications.
2. The leakage specification applies to powered devices on the PECEI bus.
3. One node is counted for each client and one node for the system host. Extended trace lengths might appear as additional nodes.

2.10.2 Input Device Hysteresis

The input buffers in both client and host models must use a Schmitt-triggered input design for improved noise immunity. Use Figure 2-1 as a guide for input buffer design.

Figure 2-1. Input Device Hysteresis



2.11 Mixing Processors

Intel supports and validates dual processor configurations only in which both processors operate with the same FSB frequency, core frequency, number of cores, and have the same internal cache sizes. Mixing components operating at different internal clock frequencies is not supported and will not be validated by Intel. Combining processors from different power segments is also not supported.

Note: Processors within a system must operate at the same frequency per bits [12:8] of the CLOCK_FLEX_MAX MSR; however this does not apply to frequency transitions initiated due to thermal events, Extended HALT, Enhanced Intel SpeedStep® Technology transitions, or assertion of the FORCEPR# signal.

Not all operating systems can support dual processors with mixed frequencies. Mixing processors of different steppings but the same model (as per CPUID instruction) is supported. Details regarding the CPUID instruction are provided in the *AP-485 Intel® Processor Identification and the CPUID Instruction* application note.

2.12 Absolute Maximum and Minimum Ratings

Table 2-11 specifies absolute maximum and minimum ratings only, which lie outside the functional limits of the processor. Only within specified operation limits, can functionality and long-term reliability be expected.

At conditions outside functional operation condition limits, but within absolute maximum and minimum ratings, neither functionality nor long-term reliability can be expected. If a device is returned to conditions within functional operation limits after having been subjected to conditions outside these limits, but within the absolute maximum and minimum ratings, the device may be functional, but with its lifetime degraded depending on exposure to conditions exceeding the functional operation condition limits.

At conditions exceeding absolute maximum and minimum ratings, neither functionality nor long-term reliability can be expected. Moreover, if a device is subjected to these conditions for any length of time then, when returned to conditions within the functional operating condition limits, it will either not function or its reliability will be severely degraded.



Although the processor contains protective circuitry to resist damage from static electric discharge, precautions should always be taken to avoid high static voltages or electric fields.

Table 2-11. Processor Absolute Maximum Ratings

| Symbol | Parameter | Min | Max | Unit | Notes ^{1, 2} |
|----------------------|---|---------------|---------------|------|-----------------------|
| V _{CC} | Core voltage with respect to V _{SS} | -0.30 | 1.55 | V | |
| V _{TT} | FSB termination voltage with respect to V _{SS} | -0.30 | 1.55 | V | |
| T _{CASE} | Processor case temperature | See Section 6 | See Section 6 | °C | |
| T _{STORAGE} | Storage temperature | -40 | 85 | °C | 3, 4, 5 |

Notes:

1. For functional operation, all processor electrical, signal quality, mechanical and thermal specifications must be satisfied.
2. Overshoot and undershoot voltage guidelines for input, output, and I/O signals are outlined in Section 3. Excessive overshoot or undershoot on any signal will likely result in permanent damage to the processor.
3. Storage temperature is applicable to storage conditions only. In this scenario, the processor must not receive a clock, and no lands can be connected to a voltage bias. Storage within these limits will not affect the long-term reliability of the device. For functional operation, please refer to the processor case temperature specifications.
4. This rating applies to the processor and does not include any tray or packaging.
5. Failure to adhere to this specification can affect the long-term reliability of the processor.

2.13 Processor DC Specifications

The processor DC specifications in this section are defined at the processor die (pads) unless noted otherwise. See Table 4-1 for the Quad-Core Intel® Xeon® Processor 5300 Series land listings and Table 5-1 for signal definitions. Voltage and current specifications are detailed in Table 2-12. For platform planning refer to Table 2-13, which provides V_{CC} Static and Transient Tolerances. This same information is presented graphically in Figure 2-5, Figure 2-6 and Figure 2-7.

The FSB clock signal group is detailed in Table 2-19. The DC specifications for the AGTL+ signals are listed in Table 2-14. Legacy signals and Test Access Port (TAP) signals follow DC specifications similar to GTL+. The DC specifications for the PWRGOOD input and TAP signal group are listed in Table 2-15.

Table 2-12 through Table 2-16 list the DC specifications for the processor and are valid only while meeting specifications for case temperature (T_{CASE} as specified in Section 6), clock frequency, and input voltages. Care should be taken to read all notes associated with each parameter.

2.13.1 Flexible Motherboard Guidelines (FMB)

The Flexible Motherboard (FMB) guidelines are estimates of the maximum values the Quad-Core Intel® Xeon® Processor 5300 Series will have over certain time periods. The values are only estimates and actual specifications for future processors may differ. Processors may or may not have specifications equal to the FMB value in the foreseeable future. System designers should meet the FMB values to ensure their systems will be compatible with future processors.



Table 2-12. Voltage and Current Specifications (Sheet 1 of 2)

| Symbol | Parameter | Min | Typ | Max | Unit | Notes ^{1,11} |
|------------------------|---|--|-------|------------|--------|-----------------------|
| VID | VID range for Quad-Core Intel® Xeon® Processor E5300 Series and Quad-Core Intel® Xeon® Processor X5300 Series | 1.0000 | | 1.5000 | V | |
| VID | VID Range for Quad-Core Intel® Xeon® Processor L5300 Series | 1.1000 | | 1.2500 | V | |
| V _{CC} | V _{CC} for processor core Launch - FMB | See Table 2-13, Figure 2-5, Figure 2-6 and Table 2-7 | | | V | 2, 3, 4, 6, 9 |
| V _{CC_BOOT} | Default V _{CC} Voltage for initial power up | | 1.10 | | V | 2 |
| V _{VID_STEP} | VID step size during a transition | | | ± 12.5 | mV | |
| V _{VID_SHIFT} | Total allowable DC load line shift from VID steps | | | 450 | mV | 10 |
| V _{TT} | FSB termination voltage (DC + AC specification) | 1.14 | 1.20 | 1.26 | V | 8,13 |
| V _{CCPLL} | PLL supply voltage (DC + AC specification) | 1.455 | 1.500 | 1.605 | V | |
| I _{CC} | I _{CC} for Quad-Core Intel® Xeon® Processor E5300 Series core with multiple VID Launch - FMB | | | 90 | A | 4,5,6,9 |
| I _{CC_RESET} | I _{CC_RESET} for Quad-Core Intel® Xeon® Processor E5300 Series core with multiple VID Launch - FMB | | | 90 | A | 17 |
| I _{CC} | I _{CC} for Quad-Core Intel® Xeon® Processor X5300 Series core with multiple VID Launch - FMB | | | 125 | A | 4,5,6,9 |
| I _{CC_RESET} | I _{CC_RESET} for Quad-Core Intel® Xeon® Processor X5300 Series core with multiple VID Launch - FMB | | | 125 | A | 17 |
| I _{CC} | I _{CC} for Quad-Core Intel® Xeon® Processor L5300 Series processor core with multiple VID Launch - FMB | | | 60 | A | 4,5,6,9 |
| I _{CC_RESET} | I _{CC_RESET} for Quad-Core Intel® Xeon® Processor L5300 Series processor core with multiple VID Launch - FMB | | | 60 | A | 17 |
| I _{TT} | I _{CC} for V _{TT} supply before V _{CC} stable I _{CC} for V _{TT} supply after V _{CC} stable | | | 8.0 7.0 | A A | 15 |
| I _{CC_TDC} | Thermal Design Current (TDC) Quad-Core Intel® Xeon® Processor E5300 Series Launch - FMB | | | 70 | A | 6,14 |



Table 2-12. Voltage and Current Specifications (Sheet 2 of 2)

| Symbol | Parameter | Min | Typ | Max | Unit | Notes ^{1,11} |
|-------------------------|---|-----|-----|-----|------|-----------------------|
| I _{CC_TDC} | Thermal Design Current (TDC) Quad-Core Intel® Xeon® Processor X5300 Series Launch - FMB | | | 110 | A | 6,14 |
| I _{CC_TDC} | Thermal Design Current (TDC) Quad-Core Intel® Xeon® Processor L5300 Series Launch - FMB | | | 50 | A | 6,14 |
| I _{CC_VTT_OUT} | DC current that may be drawn from V _{TT_OUT} per land | | | 580 | mA | 16 |
| I _{CC_GTLREF} | I _{CC} for GTLREF_DATA_MID, GTLREF_DATA_END, GTLREF_ADD_MID, GTLREF_ADD_END | | | 200 | µA | 7 |
| I _{CC_VCCPLL} | I _{CC} for PLL supply | | | 260 | mA | 12 |
| I _{TCC} | I _{CC} for Quad-Core Intel® Xeon® Processor E5300 Series during active thermal control circuit (TCC) | | | 90 | A | |
| I _{TCC} | I _{CC} for Quad-Core Intel® Xeon® Processor X5300 Series during active thermal control circuit (TCC) | | | 125 | A | |
| I _{TCC} | I _{CC} for Quad-Core Intel® Xeon® Processor L5300 Series during active thermal control circuit (TCC) | | | 60 | A | |

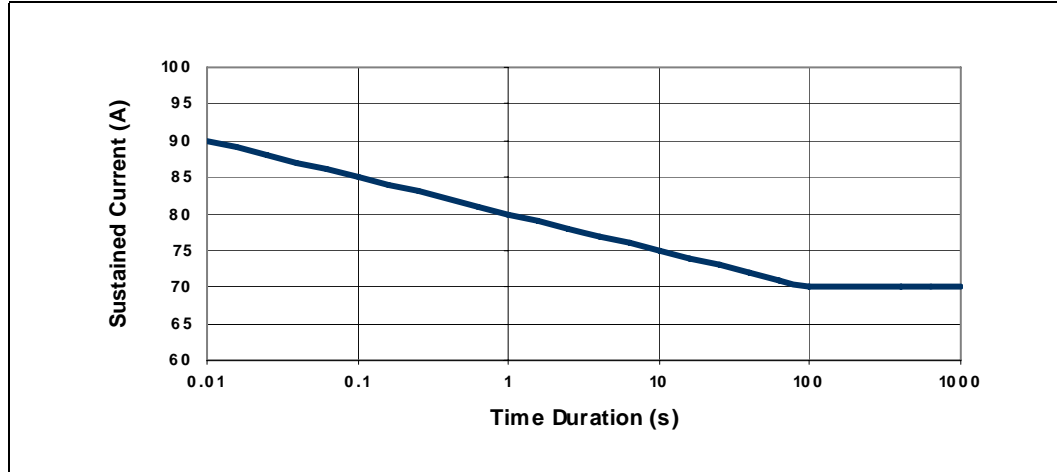
Notes:

- Unless otherwise noted, all specifications in this table are based on final silicon characterization data.
- These voltages are targets only. A variable voltage source should exist on systems in the event that a different voltage is required. See Section 2.5 for more information.
- The voltage specification requirements are measured across the VCC_DIE_SENSE and VSS_DIE_SENSE lands and across the VCC_DIE_SENSE2 and VSS_DIE_SENSE2 lands with an oscilloscope set to 100 MHz bandwidth, 1.5 pF maximum probe capacitance, and 1 MΩ minimum impedance. The maximum length of ground wire on the probe should be less than 5 mm. Ensure external noise from the system is not coupled in the scope probe.
- The processor must not be subjected to any static V_{CC} level that exceeds the V_{CC_MAX} associated with any particular current. Failure to adhere to this specification can shorten processor lifetime.
- I_{CC_MAX} specification is based on maximum V_{CC} loadline Refer to Figure 2-8 for details. The processor is capable of drawing I_{CC_MAX} for up to 10 ms. Refer to Figure 2-4, Figure 2-2, and Figure 2-3 for further details on the average processor current draw over various time durations.
- FMB is the flexible motherboard guideline. These guidelines are for estimation purposes only. See Section 2.13.1 for further details on FMB guidelines.
- This specification represents the total current for GTLREF_DATA_MID, GTLREF_DATA_END, GTLREF_ADD_MID, and GTLREF_ADD_END.
- V_{TT} must be provided via a separate voltage source and must not be connected to V_{CC}. This specification is measured at the land.
- Minimum V_{CC} and maximum I_{CC} are specified at the maximum processor case temperature (T_{CASE}) shown in Figure 6-1.
- This specification refers to the total reduction of the load line due to VID transitions below the specified VID.
- Individual processor VID values may be calibrated during manufacturing such that two devices at the same frequency may have different VID settings.
- This specification applies to the VCCPLL land.
- Baseboard bandwidth is limited to 20 MHz.
- I_{CC_TDC} is the sustained (DC equivalent) current that the processor is capable of drawing indefinitely and should be used for the voltage regulator temperature assessment. The voltage regulator is responsible for monitoring its temperature and asserting the necessary signal to inform the processor of a thermal excursion. Please see the applicable design guidelines for further details. The processor is capable of drawing I_{CC_TDC} indefinitely. Refer to Figure 2-4, Figure 2-2 and Figure 2-3 for further details on the average processor current draw over various time durations. This parameter is based on design characterization and is not tested.



- 15. This is the maximum total current drawn from the V_{TT} plane by only one processor with R_{TT} enabled. This specification does not include the current coming from on-board termination (R_{TT}), through the signal line. Refer to the appropriate platform design guide and the Voltage Regulator Design Guidelines to determine the total I_{TT} drawn by the system. This parameter is based on design characterization and is not tested.
- 16. $I_{CC_VTT_OUT}$ is specified at 1.2 V.
- 17. I_{CC_RESET} is specified while PWRGOOD and RESET# are asserted.

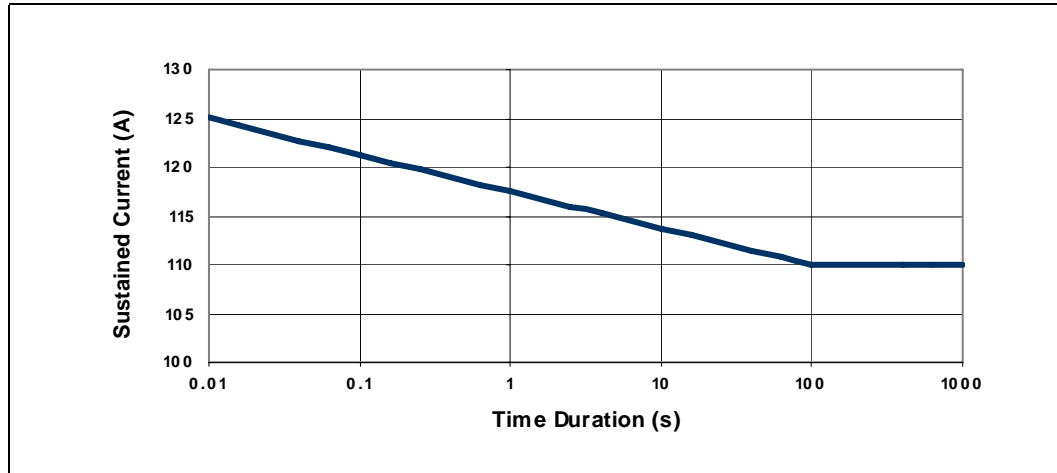
Figure 2-2. Quad-Core Intel® Xeon® Processor E5300 Series Load Current versus Time



Notes:

- 1. Processor or voltage regulator thermal protection circuitry should not trip for load currents greater than I_{CC_TDC} .
- 2. Not 100% tested. Specified by design characterization.

Figure 2-3. Quad-Core Intel® Xeon® Processor X5300 Series Load Current versus Time

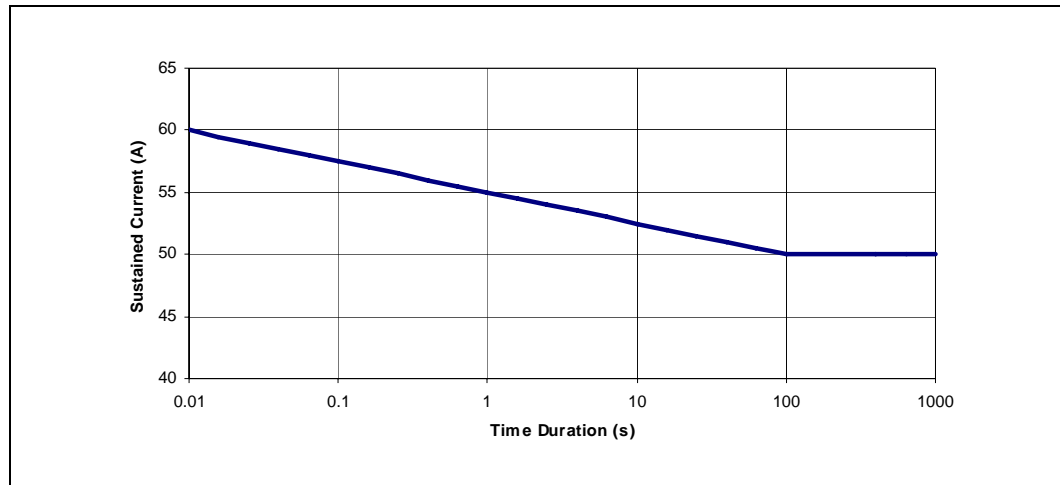


Notes:

- 1. Processor or voltage regulator thermal protection circuitry should not trip for load currents greater than I_{CC_TDC} .
- 2. Not 100% tested. Specified by design characterization.



Figure 2-4. Quad-Core Intel® Xeon® Processor L5300 Series Load Current versus Time



Notes:

1. Processor or voltage regulator thermal protection circuitry should not trip for load currents greater than I_{CC_TDC} .
2. Not 100% tested. Specified by design characterization.

Table 2-13. V_{CC} Static and Transient Tolerance (Sheet 1 of 2)

| I_{CC} (A) | V_{CC_Max} (V) | V_{CC_Typ} (V) | V_{CC_Min} (V) | Notes |
|--------------|-------------------|-------------------|-------------------|------------|
| 0 | VID - 0.000 | VID - 0.015 | VID - 0.030 | 1, 2, 3 |
| 5 | VID - 0.006 | VID - 0.021 | VID - 0.036 | 1, 2, 3 |
| 10 | VID - 0.013 | VID - 0.028 | VID - 0.043 | 1, 2, 3 |
| 15 | VID - 0.019 | VID - 0.034 | VID - 0.049 | 1, 2, 3 |
| 20 | VID - 0.025 | VID - 0.040 | VID - 0.055 | 1, 2, 3 |
| 25 | VID - 0.031 | VID - 0.046 | VID - 0.061 | 1, 2, 3 |
| 30 | VID - 0.038 | VID - 0.053 | VID - 0.068 | 1, 2, 3 |
| 35 | VID - 0.044 | VID - 0.059 | VID - 0.074 | 1, 2, 3 |
| 40 | VID - 0.050 | VID - 0.065 | VID - 0.080 | 1, 2, 3 |
| 45 | VID - 0.056 | VID - 0.071 | VID - 0.086 | 1, 2, 3 |
| 50 | VID - 0.069 | VID - 0.084 | VID - 0.099 | 1, 2, 3 |
| 55 | VID - 0.069 | VID - 0.077 | VID - 0.093 | 1, 2, 3 |
| 60 | VID - 0.075 | VID - 0.090 | VID - 0.105 | 1, 2, 3 |
| 65 | VID - 0.081 | VID - 0.096 | VID - 0.111 | 1, 2, 3 |
| 70 | VID - 0.087 | VID - 0.103 | VID - 0.118 | 1, 2, 3 |
| 75 | VID - 0.094 | VID - 0.109 | VID - 0.124 | 1, 2, 3 |
| 80 | VID - 0.100 | VID - 0.115 | VID - 0.130 | 1, 2, 3 |
| 85 | VID - 0.106 | VID - 0.121 | VID - 0.136 | 1, 2, 3 |
| 90 | VID - 0.113 | VID - 0.128 | VID - 0.143 | 1, 2, 3, |
| 95 | VID - 0.119 | VID - 0.134 | VID - 0.149 | 1, 2, 3, 4 |
| 100 | VID - 0.125 | VID - 0.140 | VID - 0.155 | 1, 2, 3, 4 |
| 105 | VID - 0.131 | VID - 0.146 | VID - 0.161 | 1, 2, 3, 4 |
| 110 | VID - 0.138 | VID - 0.153 | VID - 0.168 | 1, 2, 3, 4 |
| 115 | VID - 0.144 | VID - 0.159 | VID - 0.174 | 1, 2, 3, 4 |

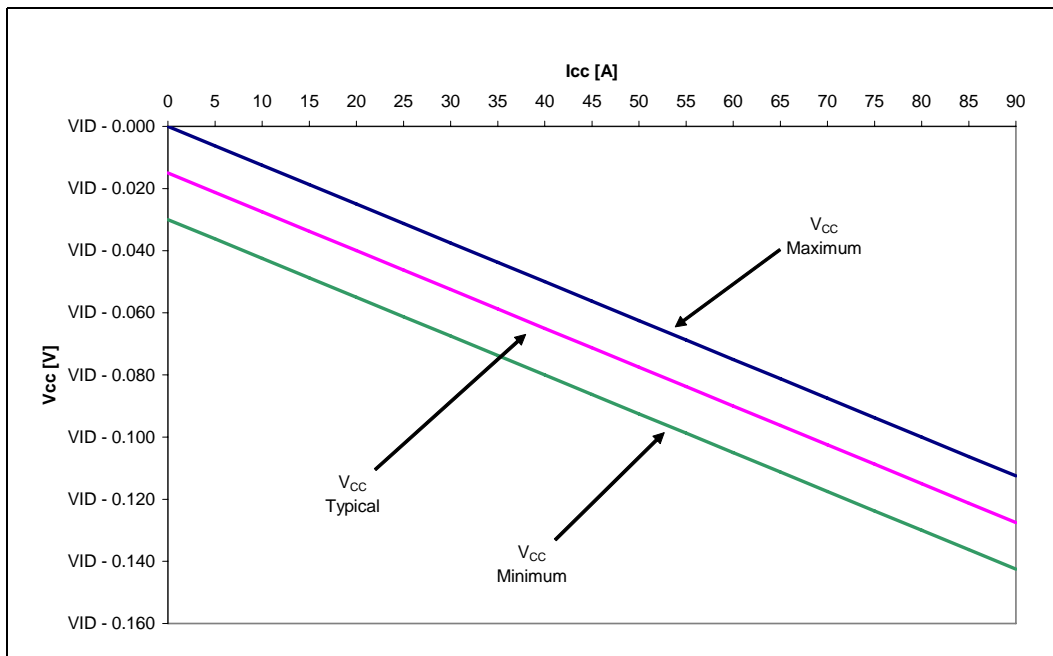
Table 2-13. V_{CC} Static and Transient Tolerance (Sheet 2 of 2)

| I_{CC} (A) | V_{CC_Max} (V) | V_{CC_Typ} (V) | V_{CC_Min} (V) | Notes |
|--------------|-------------------|-------------------|-------------------|------------|
| 120 | VID - 0.150 | VID - 0.165 | VID - 0.180 | 1, 2, 3, 4 |
| 125 | VID - 0.156 | VID - 0.171 | VID - 0.186 | 1, 2, 3, 4 |

Notes:

1. The V_{CC_MIN} and V_{CC_MAX} loadlines represent static and transient limits. Please see Section 2.13.2 for V_{CC} overshoot specifications.
2. This table is intended to aid in reading discrete points on Figure 2-5 for Quad-Core Intel® Xeon® Processor E5300 Series, Figure 2-6 for Quad-Core Intel® Xeon® Processor X5300 Series and Figure 2-7 for Quad-Core Intel® Xeon® Processor L5300 Series.
3. The loadlines specify voltage limits at the die measured at the $V_{CC_DIE_SENSE}$ and $V_{SS_DIE_SENSE}$ lands and across the $V_{CC_DIE_SENSE2}$ and $V_{SS_DIE_SENSE2}$ lands. Voltage regulation feedback for voltage regulator circuits must also be taken from processor $V_{CC_DIE_SENSE}$ and $V_{SS_DIE_SENSE}$ lands and $V_{CC_DIE_SENSE2}$ and $V_{SS_DIE_SENSE2}$ lands. Refer to the *Voltage Regulator Module (VRM) and Enterprise Voltage Regulator Down (EVRD) 11.0 Design Guidelines* for socket load line guidelines and VR implementation. Please refer to the appropriate platform design guide for details on VR implementation.
4. I_{CC} values greater than 90 A and 60 A are not applicable for the Quad-Core Intel® Xeon® Processor E5300 Series and Quad-Core Intel® Xeon® Processor L5300 Series, respectively.

Figure 2-5. Quad-Core Intel® Xeon® Processor E5300 Series V_{CC} Static and Transient Tolerance Load Lines

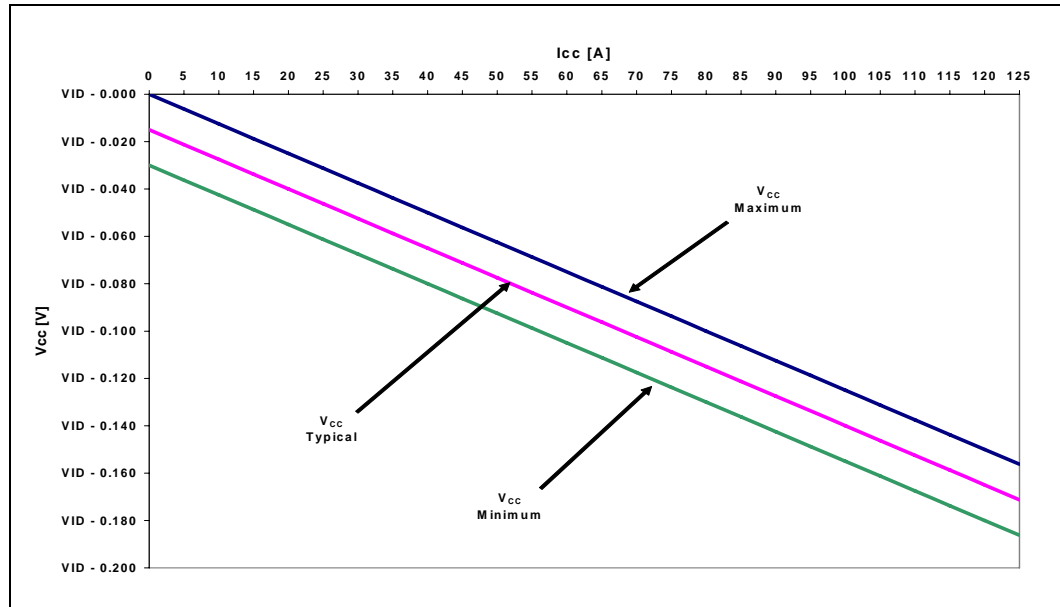


Notes:

1. The V_{CC_MIN} and V_{CC_MAX} loadlines represent static and transient limits. Please see Section 2.13.2 for V_{CC} overshoot specifications.
2. Refer to Table 2-12 for processor VID information.
3. Refer to Table 2-13 for V_{CC} Static and Transient Tolerance
4. The load lines specify voltage limits at the die measured at the $V_{CC_DIE_SENSE}$ and $V_{SS_DIE_SENSE}$ lands and the $V_{CC_DIE_SENSE2}$ and $V_{SS_DIE_SENSE2}$ lands. Voltage regulation feedback for voltage regulator circuits must also be taken from processor $V_{CC_DIE_SENSE}$ and $V_{SS_DIE_SENSE}$ lands and $V_{CC_DIE_SENSE2}$ and $V_{SS_DIE_SENSE2}$ lands. Refer to the *Voltage Regulator Module (VRM) and Enterprise Voltage Regulator Down (EVRD) 11.0 Design Guidelines* for socket load line guidelines and VR implementation. Please refer to the appropriate platform design guide for details on VR implementation.



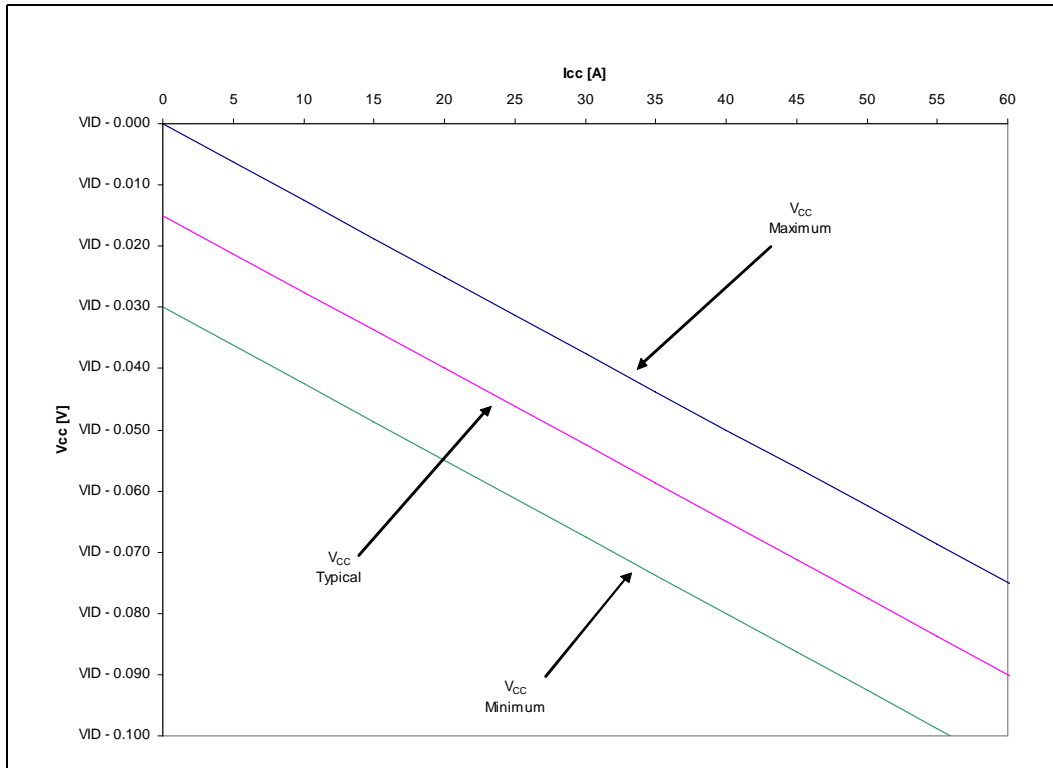
Figure 2-6. Quad-Core Intel® Xeon® Processor X5300 Series V_{CC} Static and Transient Tolerance Load Lines



Notes:

1. The V_{CC_MIN} and V_{CC_MAX} loadlines represent static and transient limits. Please see [Section 2.13.2](#) for VCC overshoot specifications.
2. Refer to [Table 2-12](#) for processor VID information.
3. Refer to [Table 2-13](#) for V_{CC} Static and Transient Tolerance
4. The load lines specify voltage limits at the die measured at the VCC_DIE_SENSE and VSS_DIE_SENSE lands and the VCC_DIE_SENSE2 and VSS_DIE_SENSE2 lands. Voltage regulation feedback for voltage regulator circuits must also be taken from processor VCC_DIE_SENSE and VSS_DIE_SENSE lands and VCC_DIE_SENSE2 and VSS_DIE_SENSE2 lands. Refer to the *Voltage Regulator Module (VRM) and Enterprise Voltage Regulator Down (EVRD) 11.0 Design Guidelines* for socket load line guidelines and VR implementation. Please refer to the appropriate platform design guide for details on VR implementation.

Figure 2-7. Quad-Core Intel® Xeon® Processor L5300 Series V_{CC} Static and Transient Tolerance Load Lines



Notes:

1. The V_{CC_MIN} and V_{CC_MAX} loadlines represent static and transient limits. Please see Section 2.13.2 for VCC overshoot specifications.
2. Refer to Table 2-12 for processor VID information.
3. Refer to Table 2-13 for V_{CC}Static and Transient Tolerance
4. The load lines specify voltage limits at the die measured at the VCC_DIE_SENSE and VSS_DIE_SENSE lands and the VCC_DIE_SENSE2 and VSS_DIE_SENSE2 lands. Voltage regulation feedback for voltage regulator circuits must also be taken from processor VCC_DIE_SENSE and VSS_DIE_SENSE lands and VCC_DIE_SENSE2 and VSS_DIE_SENSE2 lands. Refer to the Voltage Regulator Module (VRM) and Enterprise Voltage Regulator Down (EVRD) 11.0 Design Guidelines for socket load line guidelines and VR implementation. Please refer to the appropriate platform design guide for details on VR implementation.

Table 2-14. AGTL+ Signal Group Specifications

| Symbol | Parameter | Min | Typ | Max | Units | Notes ¹ |
|-----------------|-----------------------|------------------------|-----------------|-----------------------|-------|--------------------|
| V _{IL} | Input Low Voltage | -0.10 | 0 | GTLREF-0.10 | V | 2,4,6 |
| V _{IH} | Input High Voltage | GTLREF+0.10 | V _{TT} | V _{TT} +0.10 | V | 3,6 |
| V _{OH} | Output High Voltage | V _{TT} - 0.10 | N/A | V _{TT} | V | 4,6 |
| R _{ON} | Buffer On Resistance | 10.00 | 11.50 | 13.00 | W | 5 |
| I _{LI} | Input Leakage Current | N/A | N/A | +/- 200 | μA | 7,8 |

Notes:

1. Unless otherwise noted, all specifications in this table apply to all processor frequencies.
2. V_{IL} is defined as the maximum voltage level at a receiving agent that will be interpreted as a logical low value.
3. V_{IH} is defined as the minimum voltage level at a receiving agent that will be interpreted as a logical high value.
4. V_{IH} and V_{OH} may experience excursions above V_{TT}. However, input signal drivers must comply with the signal quality specifications.
5. This is the pull down driver resistance. Refer to processor I/O Buffer Models for I/V characteristics. Measured at 0.31*V_{TT}. R_{ON} (min) = 0.225*R_{TT}. R_{ON} (typ) = 0.250*R_{TT}. R_{ON} (max) = 0.275*R_{TT}.



6. GTLREF should be generated from V_{TT} with a 1% tolerance resistor divider. The V_{TT} referred to in these specifications is the instantaneous V_{TT} .
7. Specified when on-die R_{TT} and R_{ON} are turned off. V_{IN} between 0 and V_{TT} .
8. This is the measurement at the pin.

Table 2-15. CMOS Signal Input/Output Group and TAP Signal Group DC Specifications

| Symbol | Parameter | Min | Typ | Max | Units | Notes ¹ |
|----------|-----------------------|----------------|----------|----------------|---------|--------------------|
| V_{IL} | Input Low Voltage | -0.10 | 0.00 | $0.3 * V_{TT}$ | V | 2,3 |
| V_{IH} | Input High Voltage | $0.7 * V_{TT}$ | V_{TT} | $V_{TT} + 0.1$ | V | 2 |
| V_{OL} | Output Low Voltage | -0.10 | 0 | $0.1 * V_{TT}$ | V | 2 |
| V_{OH} | Output High Voltage | $0.9 * V_{TT}$ | V_{TT} | $V_{TT} + 0.1$ | V | 2 |
| I_{OL} | Output Low Current | 1.70 | N/A | 4.70 | mA | 4 |
| I_{OH} | Output High Current | 1.70 | N/A | 4.70 | mA | 5 |
| I_{LI} | Input Leakage Current | N/A | N/A | +/- 200 | μ A | 6,7 |

Notes:

1. Unless otherwise noted, all specifications in this table apply to all processor frequencies.
2. The V_{TT} referred to in these specifications refers to instantaneous V_{TT} .
3. Refer to the processor I/O Buffer Models for I/V characteristics.
4. Measured at $0.1 * V_{TT}$.
5. Measured at $0.9 * V_{TT}$.
6. For V_{IN} between 0 V and V_{TT} . Measured when the driver is tristated.
7. This is the measurement at the pin.

Table 2-16. Open Drain Output Signal Group DC Specifications

| Symbol | Parameter | Min | Typ | Max | Units | Notes ¹ |
|----------|---------------------|-----------------|----------|-----------------|---------|--------------------|
| V_{OL} | Output Low Voltage | | N/A | 0.20 | V | 3 |
| V_{OH} | Output High Voltage | $0.95 * V_{TT}$ | V_{TT} | $1.05 * V_{TT}$ | V | |
| I_{OL} | Output Low Current | 16 | N/A | 50 | mA | 2 |
| I_{LO} | Leakage Current | N/A | N/A | +/- 400 | μ A | 4,5 |

Notes:

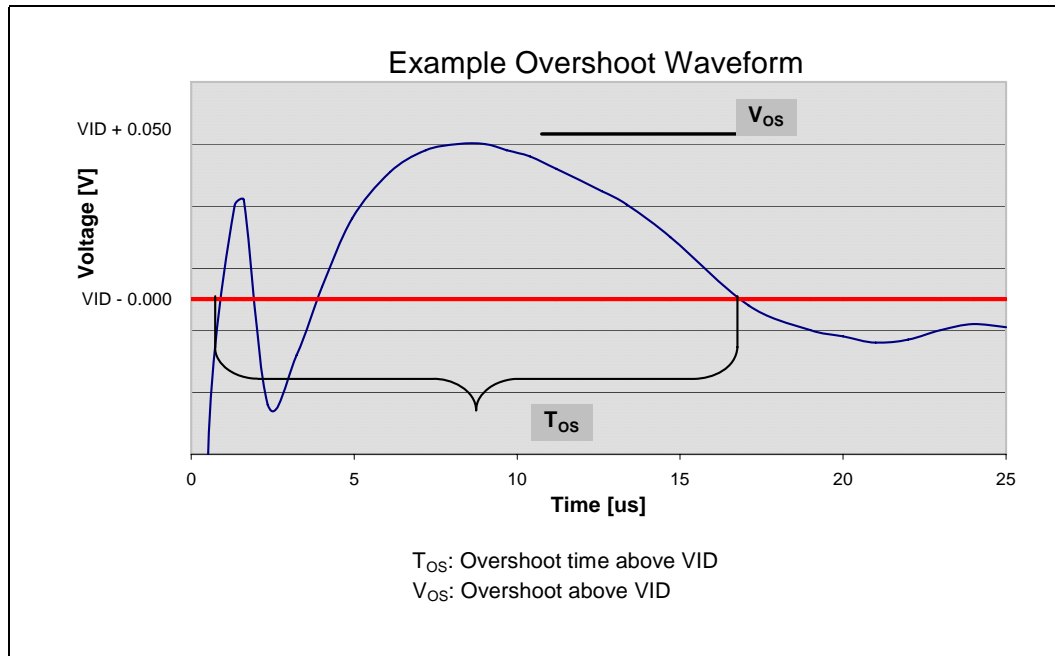
1. Unless otherwise noted, all specifications in this table apply to all processor frequencies.
2. Measured at $0.2 * V_{TT}$.
3. V_{OH} is determined by value of the external pullup resistor to V_{TT} . Please refer to platform design guide for details.
4. For V_{IN} between 0 V and V_{OH} .
5. This is the measurement at the pin.

2.13.2 V_{CC} Overshoot Specification

Processors can tolerate short transient overshoot events where V_{CC} exceeds the VID voltage when transitioning from a high-to-low current load condition. This overshoot cannot exceed $VID + V_{OS_MAX}$ (V_{OS_MAX} is the maximum allowable overshoot above VID). These specifications apply to the processor die voltage as measured across the VCC_DIE_SENSE and VSS_DIE_SENSE lands and across the VCC_DIE_SENSE2 and VSS_DIE_SENSE2 lands.

Table 2-17. V_{CC} Overshoot Specifications

| Symbol | Parameter | Min | Max | Units | Figure | Notes |
|---------------|---|-----|-----|---------|--------|-------|
| V_{OS_MAX} | Magnitude of V_{CC} overshoot above VID | | 50 | mV | 2-8 | |
| T_{OS_MAX} | Time duration of V_{CC} overshoot above VID | | 25 | μ s | 2-8 | |

Figure 2-8. V_{CC} Overshoot Example Waveform

Notes:

1. V_{OS} is the measured overshoot voltage.
2. T_{OS} is the measured time duration above VID.

2.13.3 Die Voltage Validation

Core voltage (V_{CC}) overshoot events at the processor must meet the specifications in [Table 2-17](#) when measured across the $V_{CC_DIE_SENSE}$ and $V_{SS_DIE_SENSE}$ lands and across the $V_{CC_DIE_SENSE2}$ and $V_{SS_DIE_SENSE2}$ lands. Overshoot events that are < 10 ns in duration may be ignored. These measurements of processor die level overshoot should be taken with a 100 MHz bandwidth limited oscilloscope.

2.14 AGTL+ FSB Specifications

Routing topologies are dependent on the processors supported and the chipset used in the design. Please refer to the appropriate platform design guidelines for specific implementation details. In most cases, termination resistors are not required as these are integrated into the processor silicon. See [Table 2-7](#) for details on which signals do not include on-die termination. Please refer to [Table 2-18](#) for R_{TT} values.

Valid high and low levels are determined by the input buffers via comparing with a reference voltage called $GTLREF_DATA_MID$, $GTLREF_DATA_END$, $GTLREF_ADD_MID$, and $GTLREF_ADD_END$. $GTLREF_DATA_MID$ and $GTLREF_DATA_END$ are the reference voltage for the FSB 4X data signals, $GTLREF_ADD_MID$ and $GTLREF_ADD_END$ are the reference voltage for the FSB 2X address signals and common clock signals. [Table 2-18](#) lists the $GTLREF_DATA_MID$, $GTLREF_DATA_END$, $GTLREF_ADD_MID$, and $GTLREF_ADD_END$ specifications.

The AGTL+ reference voltages ($GTLREF_DATA_MID$, $GTLREF_DATA_END$, $GTLREF_ADD_MID$, and $GTLREF_ADD_END$) must be generated on the baseboard using high precision voltage divider circuits. Refer to the appropriate platform design guidelines for implementation details.



Table 2-18. AGTL+ Bus Voltage Definitions

| Symbol | Parameter | Min | Typ | Max | Unit | Notes ¹ |
|------------------------------------|----------------------------------|------------------------|-----------------|------------------------|----------|--------------------|
| GTLREF_DATA_MID GTLREF_DATA_END | Data Bus Reference Voltage | $0.98 * 0.67 * V_{TT}$ | $0.67 * V_{TT}$ | $1.02 * 0.67 * V_{TT}$ | V | 2, 3 |
| GTLREF_ADD_MID GTLREF_ADD_END | Address Bus Reference Voltage | $0.98 * 0.67 * V_{TT}$ | $0.67 * V_{TT}$ | $1.02 * 0.67 * V_{TT}$ | V | 2, 3 |
| R_{TT} | Termination Resistance (pull up) | 45 | 50 | 55 | Ω | 4 |
| COMP | COMP Resistance | 49.4 | 49.9 | 50.4 | Ω | 5 |

Note:

- Unless otherwise noted, all specifications in this table apply to all processor frequencies.
- The tolerances for this specification have been stated generically to enable system designer to calculate the minimum values across the range of V_{TT} .
- GTLREF_DATA_MID, GTLREF_DATA_END, GTLREF_ADD_MID, and GTLREF_ADD_END is generated from V_{TT} on the baseboard by a voltage divider of 1% resistors. The minimum and maximum specifications account for this resistor tolerance. Refer to the appropriate platform design guidelines for implementation details. The V_{TT} referred to in these specifications is the instantaneous V_{TT} .
- R_{TT} is the on-die termination resistance measured at V_{OL} of the AGTL+ output driver. Measured at $0.31 * V_{TT}$. R_{TT} is connected to V_{TT} on die. Refer to processor I/O Buffer Models for I/V characteristics.
- COMP resistance must be provided on the system board with +/- 1% resistors. See the applicable platform design guide for implementation details.

Table 2-19. FSB Differential BCLK Specifications

| Symbol | Parameter | Min | Typ | Max | Unit | Figure | Notes ^{1,2} |
|--------------------|--------------------------|------------------------------------|-------|------------------------------------|---------|------------|----------------------|
| V_L | Input Low Voltage | -0.150 | 0.0 | N/A | V | 2-10 | |
| V_H | Input High Voltage | 0.660 | 0.710 | 0.850 | V | 2-10 | |
| $V_{CROSS(ABS)}$ | Absolute Crossing Point | 0.250 | 0.350 | 0.550 | V | 2-10, 2-11 | 3,9 |
| $V_{CROSS(REL)}$ | Relative Crossing Point | $0.250 + 0.5 * (V_{Havg} - 0.700)$ | N/A | $0.550 + 0.5 * (V_{Havg} - 0.700)$ | V | 2-10, 2-11 | 4,9,10 |
| ΔV_{CROSS} | Range of Crossing Points | N/A | N/A | 0.140 | V | 2-10, 2-11 | 12 |
| V_{OS} | Overshoot | N/A | N/A | $V_H + 0.300$ | V | 2-10 | 5 |
| V_{US} | Undershoot | -0.300 | N/A | N/A | V | 2-10 | 6 |
| V_{RBM} | Ringback Margin | 0.200 | N/A | N/A | V | 2-10 | 7 |
| V_{TR} | Threshold Region | $V_{CROSS} - 0.100$ | N/A | $V_{CROSS} + 0.100$ | V | 2-10 | 8 |
| I_{LI} | Input Leakage Current | N/A | N/A | +/- 100 | μA | | 11 |

Note:

- Unless otherwise noted, all specifications in this table apply to all processor frequencies.
- Rise and fall times are measured single-ended between 245 mV and 455 mV of the clock swing.
- Crossing Voltage is defined as the instantaneous voltage value when the rising edge of BCLK0 is equal to the falling edge of BCLK1.
- V_{Havg} is the statistical average of the V_H measured by the oscilloscope.
- Overshoot is defined as the absolute value of the maximum voltage.
- Undershoot is defined as the absolute value of the minimum voltage.
- Ringback Margin is defined as the absolute voltage difference between the maximum Rising Edge Ringback and the maximum Falling Edge Ringback.

8. Threshold Region is defined as a region entered around the crossing point voltage in which the differential receiver switches. It includes input threshold hysteresis.
9. The crossing point must meet the absolute and relative crossing point specifications simultaneously.
10. V_{Havg} can be measured directly using "Vtop" on Agilent and "High" on Tektronix oscilloscopes.
11. For V_{IN} between 0 V and V_H .
12. ΔV_{CROSS} is defined as the total variation of all crossing voltages as defined in Note 3.

Figure 2-9. Electrical Test Circuit

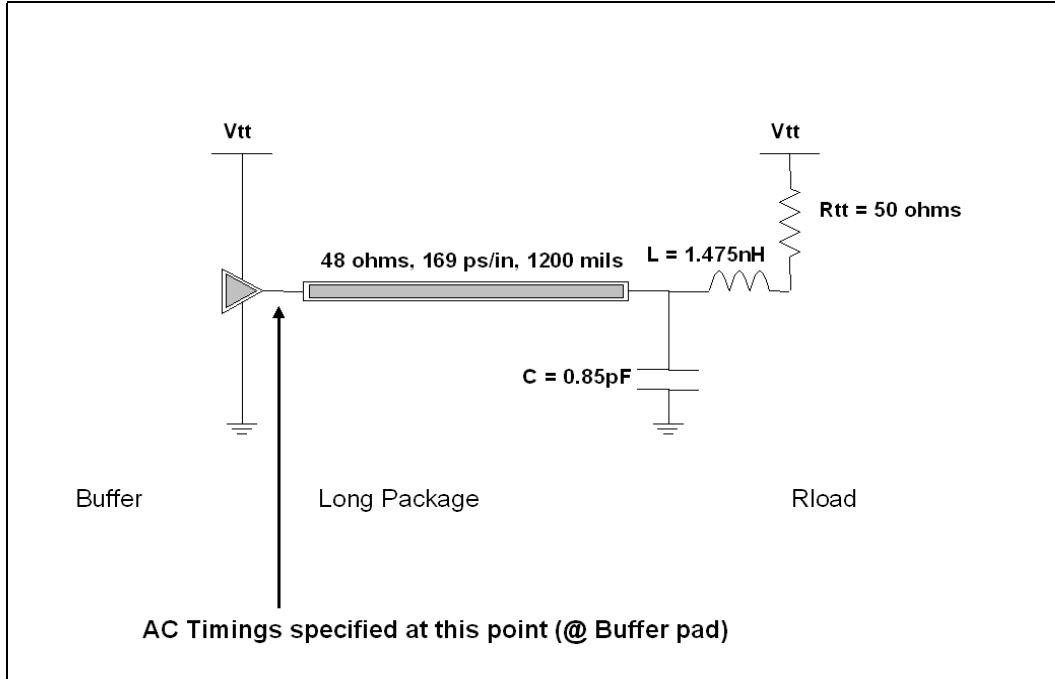


Figure 2-10. Differential Clock Waveform

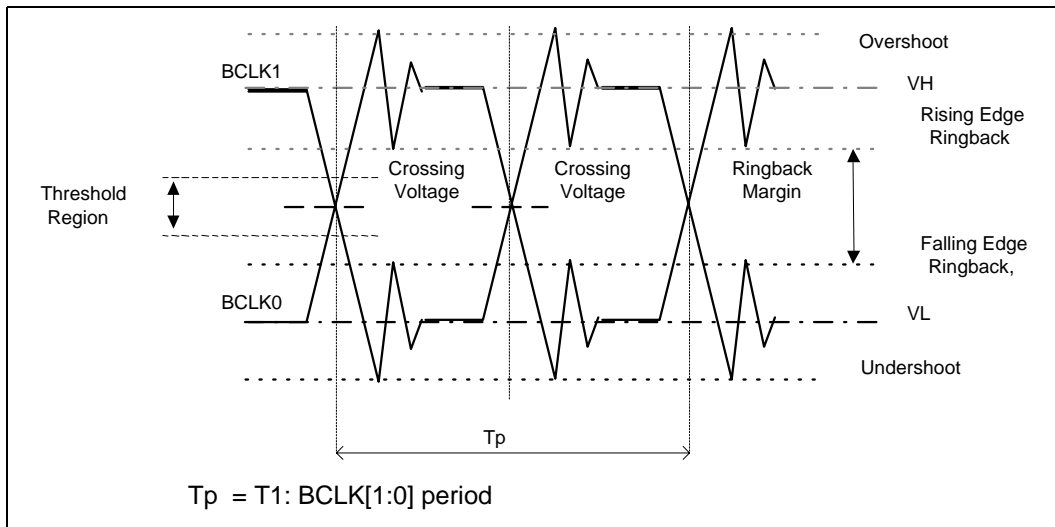
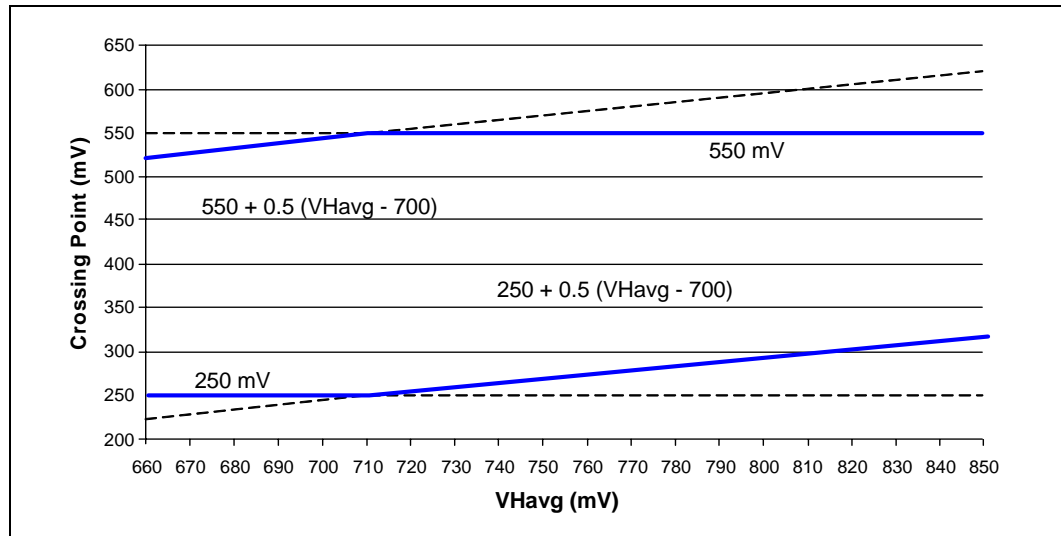




Figure 2-11. Differential Clock Crosspoint Specification



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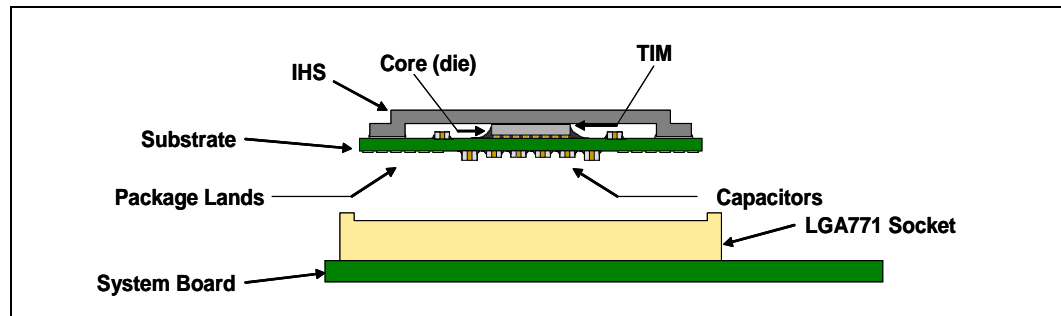
3 Mechanical Specifications

The Quad-Core Intel® Xeon® Processor 5300 Series are packaged in a Flip Chip Land Grid Array (FC-LGA6) package that interfaces to the baseboard via a LGA771 socket. The package consists of two processor dies mounted on a pinless substrate with 771 lands. An integrated heat spreader (IHS) is attached to the package substrate and core and serves as the interface for processor component thermal solutions such as a heatsink. [Figure 3-1](#) shows a sketch of the processor package components and how they are assembled together. Refer to the *LGA771 Socket Design Guidelines* for complete details on the LGA771 socket.

The package components shown in [Figure 3-1](#) include the following:

- Integrated Heat Spreader (IHS)
- Thermal Interface Material (TIM)
- Processor Die
- Package Substrate
- Landside capacitors
- Package Lands

Figure 3-1. Processor Package Assembly Sketch



Note: This drawing is not to scale and is for reference only.

3.1 Package Mechanical Drawings

The package mechanical drawings are shown in [Figure 3-2](#) through [Figure 3-4](#). The drawings include dimensions necessary to design a thermal solution for the processor including:

- Package reference and tolerance dimensions (total height, length, width, and so forth)
- IHS parallelism and tilt
- Land dimensions
- Top-side and back-side component keepout dimensions
- Reference datums

Note: All drawing dimensions are in mm [in.].



Figure 3-3. Processor Package Drawing (Sheet 2 of 3)

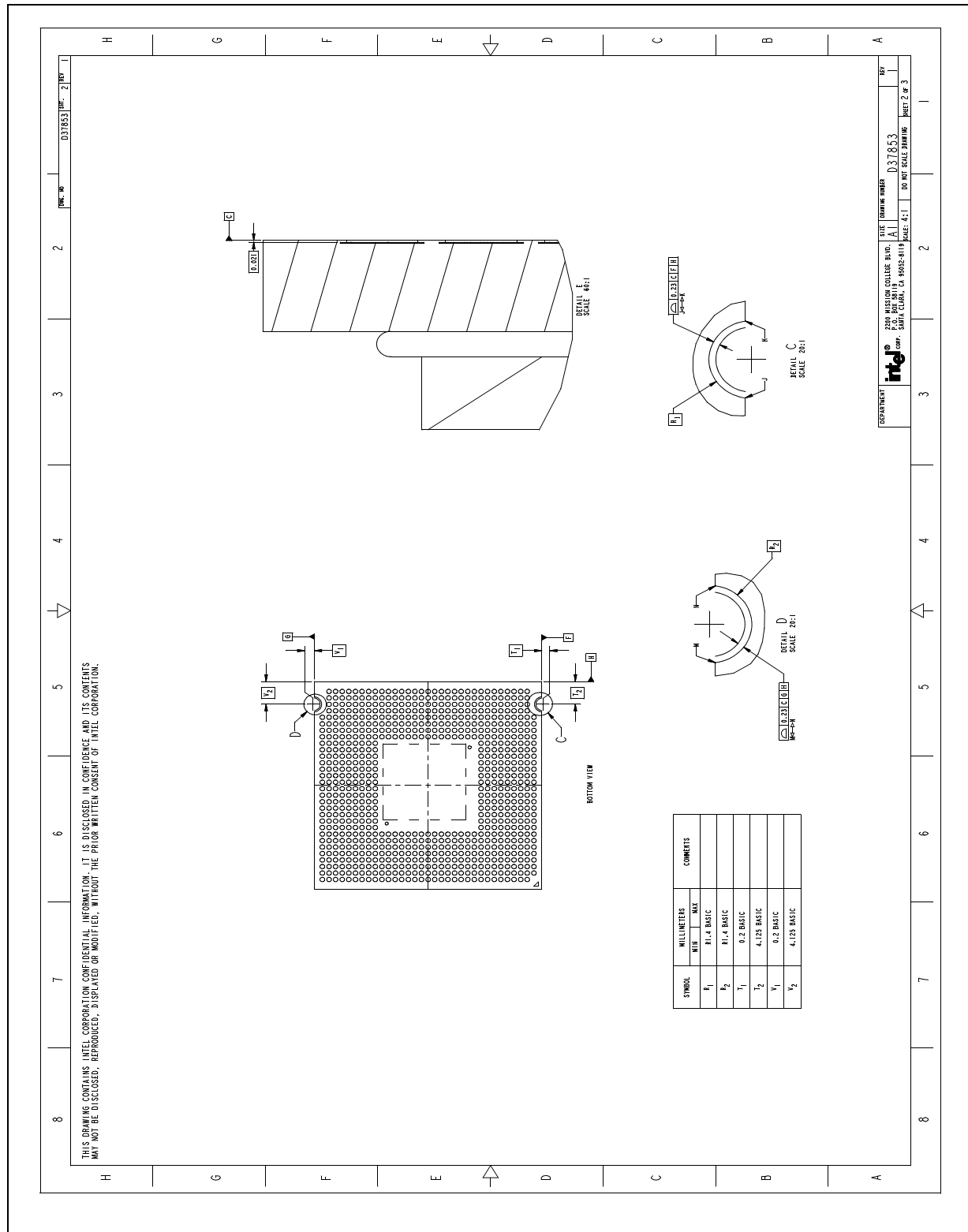
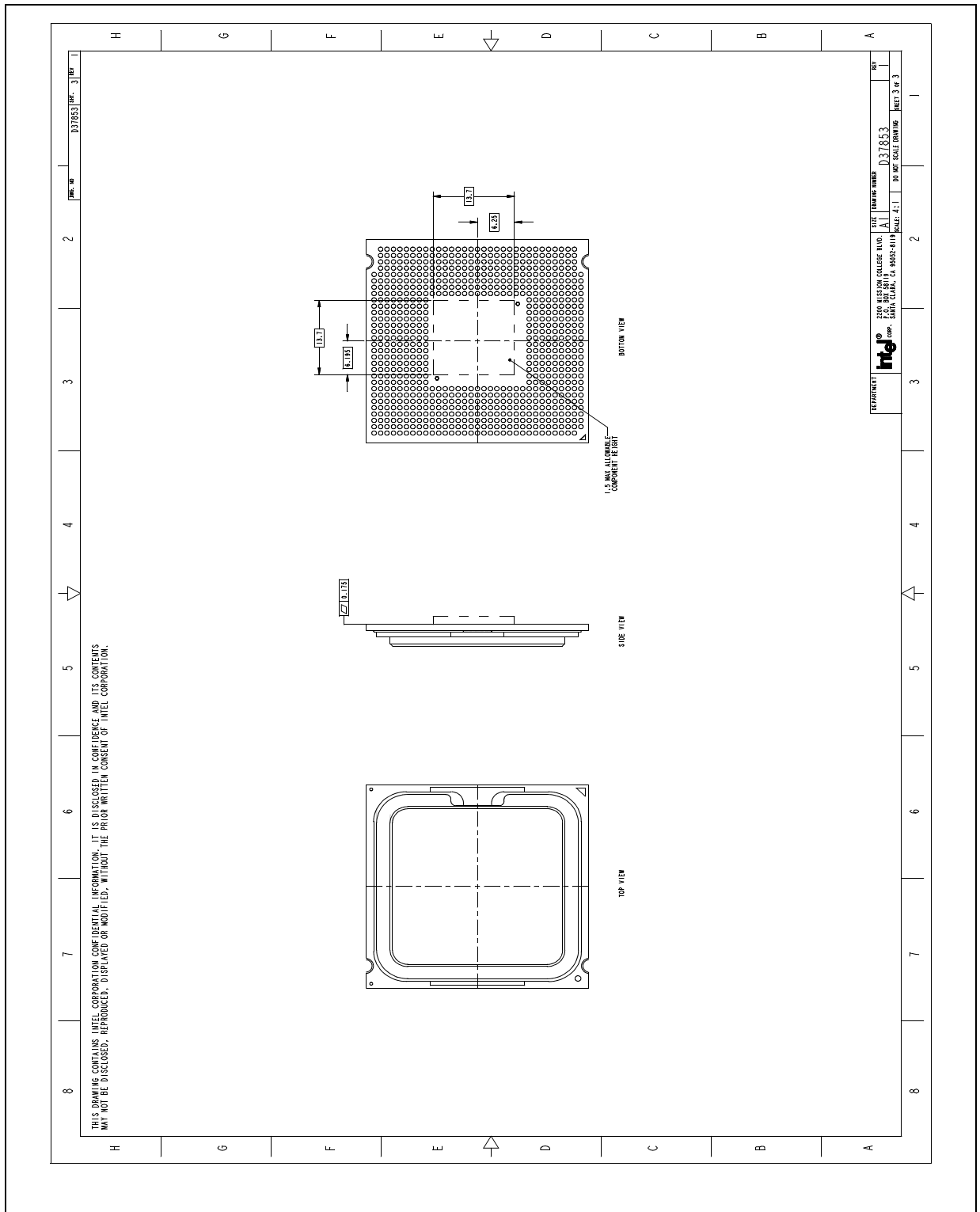


Figure 3-4. Processor Package Drawing (Sheet 3 of 3)





3.2 Processor Component Keepout Zones

The processor may contain components on the substrate that define component keepout zone requirements. A thermal and mechanical solution design must not intrude into the required keepout zones. Decoupling capacitors are typically mounted to either the topside or landside of the package substrate. See [Figure 3-4](#) for keepout zones.

3.3 Package Loading Specifications

[Table 3-1](#) provides dynamic and static load specifications for the processor package. These mechanical load limits should not be exceeded during heatsink assembly, mechanical stress testing or standard drop and shipping conditions. The heatsink attach solutions must not include continuous stress onto the processor with the exception of a uniform load to maintain the heatsink-to-processor thermal interface. Also, any mechanical system or component testing should not exceed these limits. The processor package substrate should not be used as a mechanical reference or load-bearing surface for thermal or mechanical solutions.

Table 3-1. Package Loading Specifications

| Parameter | Board Thickness | Min | Max | Unit | Notes |
|--------------------------|-------------------|-----------|---|----------|-----------|
| Static Compressive Load | 1.57 mm 0.062" | 80 18 | 311 70 | N lbf | 1,2,3,9 |
| | 2.16 mm 0.085" | 111 25 | 311 70 | N lbf | |
| | 2.54 mm 0.100" | 133 30 | 311 70 | N lbf | |
| Dynamic Compressive Load | NA | NA | 311 N (max static compressive load) + 222 N dynamic loading | N | 1,3,4,5,6 |
| | | | 70 lbf (max static compressive load) + 50 lbf dynamic loading | lbf | |
| Transient Bend Limits | 1.57 mm 0.062" | NA | 750 | me | 1,3,7,8 |

Notes:

1. These specifications apply to uniform compressive loading in a direction perpendicular to the IHS top surface.
2. This is the minimum and maximum static force that can be applied by the heatsink and retention solution to maintain the heatsink and processor interface.
3. These specifications are based on limited testing for design characterization. Loading limits are for the LGA771 socket.
4. Dynamic compressive load applies to all board thickness.
5. Dynamic loading is defined as an 11 ms duration average load superimposed on the static load requirement.
6. Test condition used a heatsink mass of 1 lbm with 50 g acceleration measured at heatsink mass. The dynamic portion of this specification in the product application can have flexibility in specific values, but the ultimate product of mass times acceleration should not exceed this dynamic load.
7. Transient bend is defined as the transient board deflection during manufacturing such as board assembly and system integration. It is a relatively slow bending event compared to shock and vibration tests.
8. For more information on the transient bend limits, please refer to the MAS document entitled *Manufacturing with Intel® Components using 771-land LGA Package that Interfaces with the Motherboard via a LGA771 Socket*.
9. Refer to the *Clovertown Processor Thermal/Mechanical Design Guidelines* for information on heatsink clip load metrology.



3.4 Package Handling Guidelines

Table 3-2 includes a list of guidelines on a package handling in terms of recommended maximum loading on the processor IHS relative to a fixed substrate. These package handling loads may be experienced during heatsink removal.

Table 3-2. Package Handling Guidelines

| Parameter | Maximum Recommended | Units | Notes |
|-----------|---------------------|---------------|-------|
| Shear | 311 70 | N lbf | 1,4,5 |
| Tensile | 111 25 | N lbf | 2,4,5 |
| Torque | 3.95 35 | N-m LBF-in | 3,4,5 |

Notes:

1. A shear load is defined as a load applied to the IHS in a direction parallel to the IHS top surface.
2. A tensile load is defined as a pulling load applied to the IHS in a direction normal to the IHS surface.
3. A torque load is defined as a twisting load applied to the IHS in an axis of rotation normal to the IHS top surface.
4. These guidelines are based on limited testing for design characterization and incidental applications (one time only).
5. Handling guidelines are for the package only and do not include the limits of the processor socket.

3.5 Package Insertion Specifications

The Quad-Core Intel® Xeon® Processor 5300 Series can be inserted and removed 15 times from an LGA771 socket, which meets the criteria outlined in the *LGA771 Socket Design Guidelines*.

3.6 Processor Mass Specifications

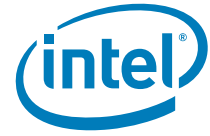
The typical mass of the Quad-Core Intel® Xeon® Processor 5300 Series is 21.5 g (0.76 oz). This includes all components which make up the entire processor product.

3.7 Processor Materials

The Quad-Core Intel® Xeon® Processor 5300 Series are assembled from several components. The basic material properties are described in Table 3-3.

Table 3-3. Processor Materials

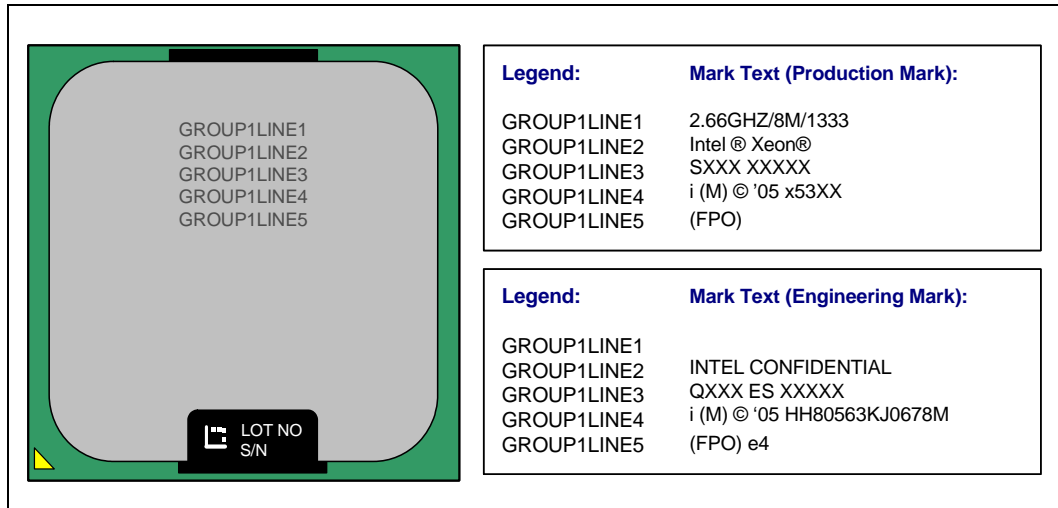
| Component | Material |
|--------------------------------|------------------------|
| Integrated Heat Spreader (IHS) | Nickel over copper |
| Substrate | Fiber-reinforced resin |
| Substrate Lands | Gold over nickel |



3.8 Processor Markings

Figure 3-5 shows the topside markings on the processor. This diagram aids in the identification of the Quad-Core Intel® Xeon® Processor 5300 Series.

Figure 3-5. Processor Top-side Markings (Example)



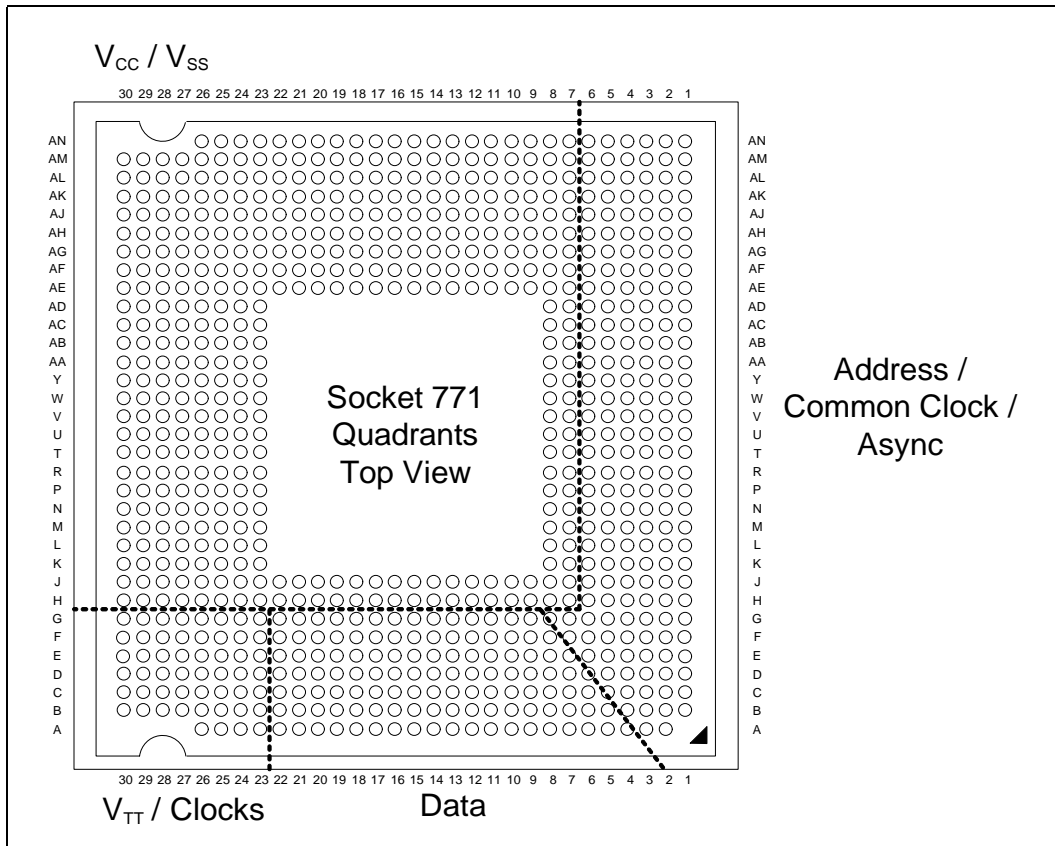
Notes:

1. 2D matrix is required for engineering samples only (encoded with ATPO-S/N)

3.9 Processor Land Coordinates

Figure 3-6 and Figure 3-7 show the top and bottom view of the processor land coordinates, respectively. The coordinates are referred to throughout the document to identify processor lands.

Figure 3-6. Processor Land Coordinates, Top View



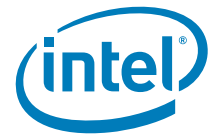
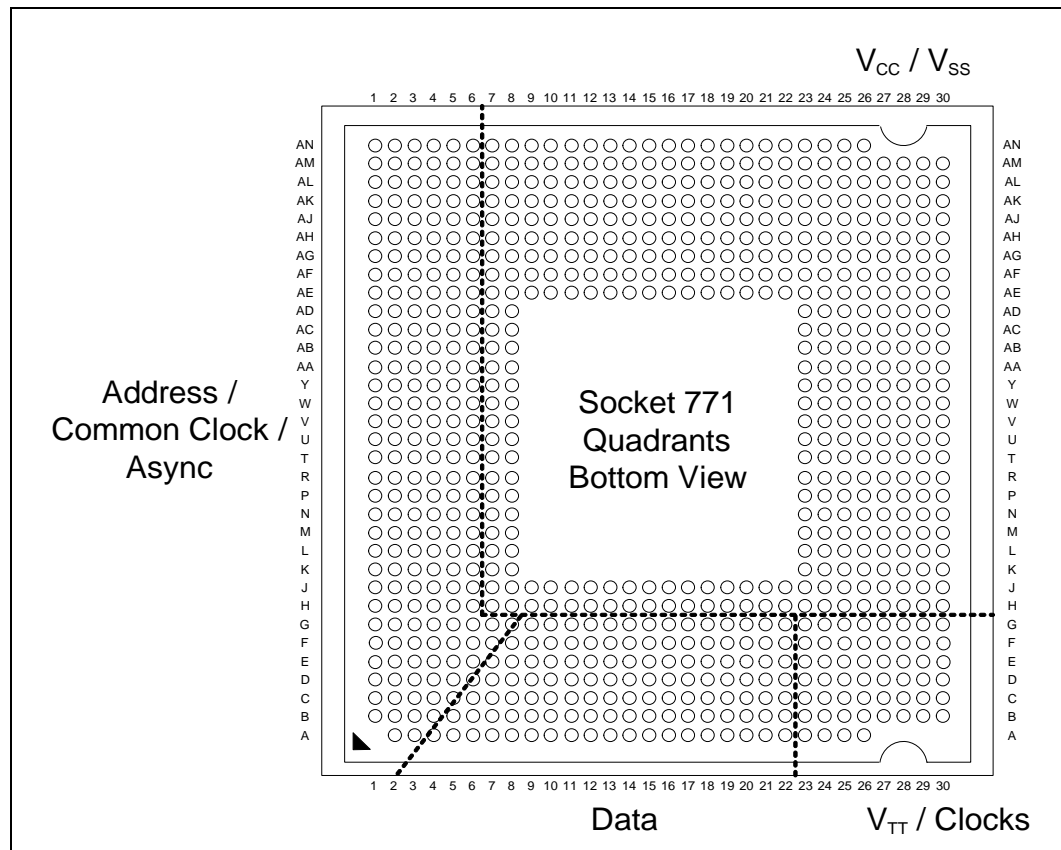


Figure 3-7. Processor Land Coordinates, Bottom View



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4 Land Listing

4.1 Quad-Core Intel® Xeon® Processor 5300 Series Pin Assignments

This section provides sorted land list in [Table 4-1](#) and [Table 4-2](#). [Table 4-1](#) is a listing of all processor lands ordered alphabetically by land name. [Table 4-2](#) is a listing of all processor lands ordered by land number.

4.1.1 Land Listing by Land Name

Table 4-1. Land Listing by Land Name (Sheet 1 of 22)

| Pin Name | Pin No. | Signal Buffer Type | Direction |
|----------|---------|--------------------|--------------|
| A03# | M5 | Source Sync | Input/Output |
| A04# | P6 | Source Sync | Input/Output |
| A05# | L5 | Source Sync | Input/Output |
| A06# | L4 | Source Sync | Input/Output |
| A07# | M4 | Source Sync | Input/Output |
| A08# | R4 | Source Sync | Input/Output |
| A09# | T5 | Source Sync | Input/Output |
| A10# | U6 | Source Sync | Input/Output |
| A11# | T4 | Source Sync | Input/Output |
| A12# | U5 | Source Sync | Input/Output |
| A13# | U4 | Source Sync | Input/Output |
| A14# | V5 | Source Sync | Input/Output |
| A15# | V4 | Source Sync | Input/Output |
| A16# | W5 | Source Sync | Input/Output |
| A17# | AB6 | Source Sync | Input/Output |
| A18# | W6 | Source Sync | Input/Output |
| A19# | Y6 | Source Sync | Input/Output |
| A20# | Y4 | Source Sync | Input/Output |



Table 4-1. Land Listing by Land Name (Sheet 2 of 22)

| Pin Name | Pin No. | Signal Buffer Type | Direction |
|----------|---------|--------------------|--------------|
| A20M# | K3 | ASync GTL+ | Input |
| A21# | AA4 | Source Sync | Input/Output |
| A22# | AD6 | Source Sync | Input/Output |
| A23# | AA5 | Source Sync | Input/Output |
| A24# | AB5 | Source Sync | Input/Output |
| A25# | AC5 | Source Sync | Input/Output |
| A26# | AB4 | Source Sync | Input/Output |
| A27# | AF5 | Source Sync | Input/Output |
| A28# | AF4 | Source Sync | Input/Output |
| A29# | AG6 | Source Sync | Input/Output |
| A30# | AG4 | Source Sync | Input/Output |
| A31# | AG5 | Source Sync | Input/Output |
| A32# | AH4 | Source Sync | Input/Output |
| A33# | AH5 | Source Sync | Input/Output |
| A34# | AJ5 | Source Sync | Input/Output |
| A35# | AJ6 | Source Sync | Input/Output |
| A36# | N4 | Source Sync | Input/Output |
| A37# | P5 | Source Sync | Input/Output |
| ADS# | D2 | Common Clk | Input/Output |
| ADSTB0# | R6 | Source Sync | Input/Output |
| ADSTB1# | AD5 | Source Sync | Input/Output |
| AP0# | U2 | Common Clk | Input/Output |
| AP1# | U3 | Common Clk | Input/Output |
| BCLK0 | F28 | Clk | Input |
| BCLK1 | G28 | Clk | Input |
| BINIT# | AD3 | Common Clk | Input/Output |
| BNR# | C2 | Common Clk | Input/Output |



Table 4-1. Land Listing by Land Name (Sheet 3 of 22)

| Pin Name | Pin No. | Signal Buffer Type | Direction |
|----------|---------|--------------------|--------------|
| BPM0# | AJ2 | Common Clk | Input/Output |
| BPM1# | AJ1 | Common Clk | Output |
| BPM2# | AD2 | Common Clk | Output |
| BPM3# | AG2 | Common Clk | Input/Output |
| BPM4# | AF2 | Common Clk | Output |
| BPM5# | AG3 | Common Clk | Input/Output |
| BPMb0# | G1 | Common Clk | Input/Output |
| BPMb1# | C9 | Common Clk | Output |
| BPMb2# | G4 | Common Clk | Output |
| BPMb3# | G3 | Common Clk | Input/Output |
| BPRI# | G8 | Common Clk | Input |
| BR0# | F3 | Common Clk | Input/Output |
| BR1# | H5 | Common Clk | Input |
| BSEL0 | G29 | Power/Other | Output |
| BSEL1 | H30 | Power/Other | Output |
| BSEL2 | G30 | Power/Other | Output |
| COMP0 | A13 | Power/Other | Input |
| COMP1 | T1 | Power/Other | Input |
| COMP2 | G2 | Power/Other | Input |
| COMP3 | R1 | Power/Other | Input |
| D00# | B4 | Source Sync | Input/Output |
| D01# | C5 | Source Sync | Input/Output |
| D02# | A4 | Source Sync | Input/Output |
| D03# | C6 | Source Sync | Input/Output |
| D04# | A5 | Source Sync | Input/Output |
| D05# | B6 | Source Sync | Input/Output |
| D06# | B7 | Source Sync | Input/Output |
| D07# | A7 | Source Sync | Input/Output |
| D08# | A10 | Source Sync | Input/Output |
| D09# | A11 | Source Sync | Input/Output |
| D10# | B10 | Source Sync | Input/Output |



Table 4-1. Land Listing by Land Name (Sheet 4 of 22)

| Pin Name | Pin No. | Signal Buffer Type | Direction |
|----------|---------|--------------------|--------------|
| D11# | C11 | Source Sync | Input/Output |
| D12# | D8 | Source Sync | Input/Output |
| D13# | B12 | Source Sync | Input/Output |
| D14# | C12 | Source Sync | Input/Output |
| D15# | D11 | Source Sync | Input/Output |
| D16# | G9 | Source Sync | Input/Output |
| D17# | F8 | Source Sync | Input/Output |
| D18# | F9 | Source Sync | Input/Output |
| D19# | E9 | Source Sync | Input/Output |
| D20# | D7 | Source Sync | Input/Output |
| D21# | E10 | Source Sync | Input/Output |
| D22# | D10 | Source Sync | Input/Output |
| D23# | F11 | Source Sync | Input/Output |
| D24# | F12 | Source Sync | Input/Output |
| D25# | D13 | Source Sync | Input/Output |
| D26# | E13 | Source Sync | Input/Output |
| D27# | G13 | Source Sync | Input/Output |
| D28# | F14 | Source Sync | Input/Output |
| D29# | G14 | Source Sync | Input/Output |
| D30# | F15 | Source Sync | Input/Output |
| D31# | G15 | Source Sync | Input/Output |
| D32# | G16 | Source Sync | Input/Output |
| D33# | E15 | Source Sync | Input/Output |
| D34# | E16 | Source Sync | Input/Output |
| D35# | G18 | Source Sync | Input/Output |
| D36# | G17 | Source Sync | Input/Output |



Table 4-1. Land Listing by Land Name (Sheet 5 of 22)

| Pin Name | Pin No. | Signal Buffer Type | Direction |
|----------|---------|--------------------|--------------|
| D37# | F17 | Source Sync | Input/Output |
| D38# | F18 | Source Sync | Input/Output |
| D39# | E18 | Source Sync | Input/Output |
| D40# | E19 | Source Sync | Input/Output |
| D41# | F20 | Source Sync | Input/Output |
| D42# | E21 | Source Sync | Input/Output |
| D43# | F21 | Source Sync | Input/Output |
| D44# | G21 | Source Sync | Input/Output |
| D45# | E22 | Source Sync | Input/Output |
| D46# | D22 | Source Sync | Input/Output |
| D47# | G22 | Source Sync | Input/Output |
| D48# | D20 | Source Sync | Input/Output |
| D49# | D17 | Source Sync | Input/Output |
| D50# | A14 | Source Sync | Input/Output |
| D51# | C15 | Source Sync | Input/Output |
| D52# | C14 | Source Sync | Input/Output |
| D53# | B15 | Source Sync | Input/Output |
| D54# | C18 | Source Sync | Input/Output |
| D55# | B16 | Source Sync | Input/Output |
| D56# | A17 | Source Sync | Input/Output |
| D57# | B18 | Source Sync | Input/Output |
| D58# | C21 | Source Sync | Input/Output |
| D59# | B21 | Source Sync | Input/Output |
| D60# | B19 | Source Sync | Input/Output |
| D61# | A19 | Source Sync | Input/Output |
| D62# | A22 | Source Sync | Input/Output |



Table 4-1. Land Listing by Land Name (Sheet 6 of 22)

| Pin Name | Pin No. | Signal Buffer Type | Direction |
|-----------------|---------|--------------------|--------------|
| D63# | B22 | Source Sync | Input/Output |
| DBIO# | A8 | Source Sync | Input/Output |
| DBI1# | G11 | Source Sync | Input/Output |
| DBI2# | D19 | Source Sync | Input/Output |
| DBI3# | C20 | Source Sync | Input/Output |
| DBR# | AC2 | Power/Other | Output |
| DBSY# | B2 | Common Clk | Input/Output |
| DEFER# | G7 | Common Clk | Input |
| DP0# | J16 | Common Clk | Input/Output |
| DP1# | H15 | Common Clk | Input/Output |
| DP2# | H16 | Common Clk | Input/Output |
| DP3# | J17 | Common Clk | Input/Output |
| DRDY# | C1 | Common Clk | Input/Output |
| DSTBN0# | C8 | Source Sync | Input/Output |
| DSTBN1# | G12 | Source Sync | Input/Output |
| DSTBN2# | G20 | Source Sync | Input/Output |
| DSTBN3# | A16 | Source Sync | Input/Output |
| DSTBP0# | B9 | Source Sync | Input/Output |
| DSTBP1# | E12 | Source Sync | Input/Output |
| DSTBP2# | G19 | Source Sync | Input/Output |
| DSTBP3# | C17 | Source Sync | Input/Output |
| FERR#/PBE# | R3 | ASync GTL+ | Output |
| FORCEPR# | AK6 | ASync GTL+ | Input |
| GTLREF_ADD_END | G10 | Power/Other | Input |
| GTLREF_ADD_MID | F2 | Power/Other | Input |
| GTLREF_DATA_END | H1 | Power/Other | Input |
| GTLREF_DATA_MID | H2 | Power/Other | Input |
| HIT# | D4 | Common Clk | Input/Output |
| HITM# | E4 | Common Clk | Input/Output |



Table 4-1. Land Listing by Land Name (Sheet 7 of 22)

| Pin Name | Pin No. | Signal Buffer Type | Direction |
|----------|---------|--------------------|------------------|
| IERR# | AB2 | ASync GTL+ | Output |
| IGNNE# | N2 | ASync GTL+ | Input |
| INIT# | P3 | ASync GTL+ | Input |
| LINT0 | K1 | ASync GTL+ | Input |
| LINT1 | L1 | ASync GTL+ | Input |
| LL_ID0 | V2 | Power/Other | Output |
| LL_ID1 | AA2 | Power/Other | Output |
| LOCK# | C3 | Common Clk | Input/ Output |
| MCERR# | AB3 | Common Clk | Input/ Output |
| MS_ID0 | W1 | Power/Other | Output |
| MS_ID1 | V1 | Power/Other | Output |
| PECI | G5 | Power/Other | Input/ Output |
| PROCHOT# | AL2 | ASync GTL+ | Output |
| PWRGOOD | N1 | Power/Other | Input |
| REQ0# | K4 | Source Sync | Input/ Output |
| REQ1# | J5 | Source Sync | Input/ Output |
| REQ2# | M6 | Source Sync | Input/ Output |
| REQ3# | K6 | Source Sync | Input/ Output |
| REQ4# | J6 | Source Sync | Input/ Output |
| RESERVED | A20 | | |
| RESERVED | A23 | | |
| RESERVED | A24 | | |
| RESERVED | AC4 | | |
| RESERVED | AE3 | | |
| RESERVED | AE4 | | |
| RESERVED | AE6 | | |
| RESERVED | AH2 | | |
| RESERVED | AH7 | | |
| RESERVED | AJ3 | | |
| RESERVED | AJ7 | | |
| RESERVED | AK1 | | |
| RESERVED | AK3 | | |
| RESERVED | AL1 | | |
| RESERVED | AM2 | | |
| RESERVED | AM6 | | |
| RESERVED | AN5 | | |
| RESERVED | AN6 | | |



Table 4-1. Land Listing by Land Name (Sheet 8 of 22)

| Pin Name | Pin No. | Signal Buffer Type | Direction |
|----------|---------|--------------------|-----------|
| RESERVED | B13 | | |
| RESERVED | B23 | | |
| RESERVED | C23 | | |
| RESERVED | D1 | | |
| RESERVED | D14 | | |
| RESERVED | D16 | | |
| RESERVED | E1 | | |
| RESERVED | E23 | | |
| RESERVED | E24 | | |
| RESERVED | E29 | | |
| RESERVED | E5 | | |
| RESERVED | E6 | | |
| RESERVED | E7 | | |
| RESERVED | F23 | | |
| RESERVED | F29 | | |
| RESERVED | F6 | | |
| RESERVED | G6 | | |
| RESERVED | J2 | | |
| RESERVED | J3 | | |
| RESERVED | N5 | | |
| RESERVED | T2 | | |
| RESERVED | Y1 | | |
| RESERVED | Y3 | | |
| RESET# | G23 | Common Clk | Input |
| RS0# | B3 | Common Clk | Input |
| RS1# | F5 | Common Clk | Input |
| RS2# | A3 | Common Clk | Input |
| RSP# | H4 | Common Clk | Input |
| SKTOCC# | AE8 | Power/Other | Output |
| SMI# | P2 | ASync GTL+ | Input |
| STPCLK# | M3 | ASync GTL+ | Input |
| TCK | AE1 | TAP | Input |
| TDI | AD1 | TAP | Input |
| TDO | AF1 | TAP | Output |
| TESTHI00 | F26 | Power/Other | Input |
| TESTHI01 | W3 | Power/Other | Input |
| TESTHI02 | F25 | Power/Other | Input |
| TESTHI03 | G25 | Power/Other | Input |
| TESTHI04 | G27 | Power/Other | Input |
| TESTHI05 | G26 | Power/Other | Input |
| TESTHI06 | G24 | Power/Other | Input |



Table 4-1. Land Listing by Land Name (Sheet 9 of 22)

| Pin Name | Pin No. | Signal Buffer Type | Direction |
|------------|---------|--------------------|-----------|
| TESTHI07 | F24 | Power/Other | Input |
| TESTHI10 | P1 | Power/Other | Input |
| TESTHI11 | L2 | Power/Other | Input |
| TESTIN1 | W2 | Power/Other | Input |
| TESTIN2 | U1 | Power/Other | Input |
| THERMTRIP# | M2 | ASync GTL+ | Output |
| TMS | AC1 | TAP | Input |
| TRDY# | E3 | Common Clk | Input |
| TRST# | AG1 | TAP | Input |
| VCC | AA8 | Power/Other | |
| VCC | AB8 | Power/Other | |
| VCC | AC23 | Power/Other | |
| VCC | AC24 | Power/Other | |
| VCC | AC25 | Power/Other | |
| VCC | AC26 | Power/Other | |
| VCC | AC27 | Power/Other | |
| VCC | AC28 | Power/Other | |
| VCC | AC29 | Power/Other | |
| VCC | AC30 | Power/Other | |
| VCC | AC8 | Power/Other | |
| VCC | AD23 | Power/Other | |
| VCC | AD24 | Power/Other | |
| VCC | AD25 | Power/Other | |
| VCC | AD26 | Power/Other | |
| VCC | AD27 | Power/Other | |
| VCC | AD28 | Power/Other | |
| VCC | AD29 | Power/Other | |
| VCC | AD30 | Power/Other | |
| VCC | AD8 | Power/Other | |
| VCC | AE11 | Power/Other | |
| VCC | AE12 | Power/Other | |
| VCC | AE14 | Power/Other | |
| VCC | AE15 | Power/Other | |
| VCC | AE18 | Power/Other | |
| VCC | AE19 | Power/Other | |
| VCC | AE21 | Power/Other | |
| VCC | AE22 | Power/Other | |
| VCC | AE23 | Power/Other | |
| VCC | AE9 | Power/Other | |
| VCC | AF11 | Power/Other | |
| VCC | AF12 | Power/Other | |



Table 4-1. Land Listing by Land Name (Sheet 10 of 22)

| Pin Name | Pin No. | Signal Buffer Type | Direction |
|----------|---------|--------------------|-----------|
| VCC | AF14 | Power/Other | |
| VCC | AF15 | Power/Other | |
| VCC | AF18 | Power/Other | |
| VCC | AF19 | Power/Other | |
| VCC | AF21 | Power/Other | |
| VCC | AF22 | Power/Other | |
| VCC | AF8 | Power/Other | |
| VCC | AF9 | Power/Other | |
| VCC | AG11 | Power/Other | |
| VCC | AG12 | Power/Other | |
| VCC | AG14 | Power/Other | |
| VCC | AG15 | Power/Other | |
| VCC | AG18 | Power/Other | |
| VCC | AG19 | Power/Other | |
| VCC | AG21 | Power/Other | |
| VCC | AG22 | Power/Other | |
| VCC | AG25 | Power/Other | |
| VCC | AG26 | Power/Other | |
| VCC | AG27 | Power/Other | |
| VCC | AG28 | Power/Other | |
| VCC | AG29 | Power/Other | |
| VCC | AG30 | Power/Other | |
| VCC | AG8 | Power/Other | |
| VCC | AG9 | Power/Other | |
| VCC | AH11 | Power/Other | |
| VCC | AH12 | Power/Other | |
| VCC | AH14 | Power/Other | |
| VCC | AH15 | Power/Other | |
| VCC | AH18 | Power/Other | |
| VCC | AH19 | Power/Other | |
| VCC | AH21 | Power/Other | |
| VCC | AH22 | Power/Other | |
| VCC | AH25 | Power/Other | |
| VCC | AH26 | Power/Other | |
| VCC | AH27 | Power/Other | |
| VCC | AH28 | Power/Other | |
| VCC | AH29 | Power/Other | |
| VCC | AH30 | Power/Other | |
| VCC | AH8 | Power/Other | |
| VCC | AH9 | Power/Other | |
| VCC | AJ11 | Power/Other | |



Table 4-1. Land Listing by Land Name (Sheet 11 of 22)

| Pin Name | Pin No. | Signal Buffer Type | Direction |
|----------|---------|--------------------|-----------|
| VCC | AJ12 | Power/Other | |
| VCC | AJ14 | Power/Other | |
| VCC | AJ15 | Power/Other | |
| VCC | AJ18 | Power/Other | |
| VCC | AJ19 | Power/Other | |
| VCC | AJ21 | Power/Other | |
| VCC | AJ22 | Power/Other | |
| VCC | AJ25 | Power/Other | |
| VCC | AJ26 | Power/Other | |
| VCC | AJ8 | Power/Other | |
| VCC | AJ9 | Power/Other | |
| VCC | AK11 | Power/Other | |
| VCC | AK12 | Power/Other | |
| VCC | AK14 | Power/Other | |
| VCC | AK15 | Power/Other | |
| VCC | AK18 | Power/Other | |
| VCC | AK19 | Power/Other | |
| VCC | AK21 | Power/Other | |
| VCC | AK22 | Power/Other | |
| VCC | AK25 | Power/Other | |
| VCC | AK26 | Power/Other | |
| VCC | AK8 | Power/Other | |
| VCC | AK9 | Power/Other | |
| VCC | AL11 | Power/Other | |
| VCC | AL12 | Power/Other | |
| VCC | AL14 | Power/Other | |
| VCC | AL15 | Power/Other | |
| VCC | AL18 | Power/Other | |
| VCC | AL19 | Power/Other | |
| VCC | AL21 | Power/Other | |
| VCC | AL22 | Power/Other | |
| VCC | AL25 | Power/Other | |
| VCC | AL26 | Power/Other | |
| VCC | AL29 | Power/Other | |
| VCC | AL30 | Power/Other | |
| VCC | AL9 | Power/Other | |
| VCC | AM11 | Power/Other | |
| VCC | AM12 | Power/Other | |
| VCC | AM14 | Power/Other | |
| VCC | AM15 | Power/Other | |
| VCC | AM18 | Power/Other | |



Table 4-1. Land Listing by Land Name (Sheet 12 of 22)

| Pin Name | Pin No. | Signal Buffer Type | Direction |
|----------|---------|--------------------|-----------|
| VCC | AM19 | Power/Other | |
| VCC | AM21 | Power/Other | |
| VCC | AM22 | Power/Other | |
| VCC | AM25 | Power/Other | |
| VCC | AM26 | Power/Other | |
| VCC | AM29 | Power/Other | |
| VCC | AM30 | Power/Other | |
| VCC | AM8 | Power/Other | |
| VCC | AM9 | Power/Other | |
| VCC | AN11 | Power/Other | |
| VCC | AN12 | Power/Other | |
| VCC | AN14 | Power/Other | |
| VCC | AN15 | Power/Other | |
| VCC | AN18 | Power/Other | |
| VCC | AN19 | Power/Other | |
| VCC | AN21 | Power/Other | |
| VCC | AN22 | Power/Other | |
| VCC | AN25 | Power/Other | |
| VCC | AN26 | Power/Other | |
| VCC | AN8 | Power/Other | |
| VCC | AN9 | Power/Other | |
| VCC | J10 | Power/Other | |
| VCC | J11 | Power/Other | |
| VCC | J12 | Power/Other | |
| VCC | J13 | Power/Other | |
| VCC | J14 | Power/Other | |
| VCC | J15 | Power/Other | |
| VCC | J18 | Power/Other | |
| VCC | J19 | Power/Other | |
| VCC | J20 | Power/Other | |
| VCC | J21 | Power/Other | |
| VCC | J22 | Power/Other | |
| VCC | J23 | Power/Other | |
| VCC | J24 | Power/Other | |
| VCC | J25 | Power/Other | |
| VCC | J26 | Power/Other | |
| VCC | J27 | Power/Other | |
| VCC | J28 | Power/Other | |
| VCC | J29 | Power/Other | |
| VCC | J30 | Power/Other | |
| VCC | J8 | Power/Other | |



Table 4-1. Land Listing by Land Name (Sheet 13 of 22)

| Pin Name | Pin No. | Signal Buffer Type | Direction |
|----------|---------|--------------------|-----------|
| VCC | J9 | Power/Other | |
| VCC | K23 | Power/Other | |
| VCC | K24 | Power/Other | |
| VCC | K25 | Power/Other | |
| VCC | K26 | Power/Other | |
| VCC | K27 | Power/Other | |
| VCC | K28 | Power/Other | |
| VCC | K29 | Power/Other | |
| VCC | K30 | Power/Other | |
| VCC | K8 | Power/Other | |
| VCC | L8 | Power/Other | |
| VCC | M23 | Power/Other | |
| VCC | M24 | Power/Other | |
| VCC | M25 | Power/Other | |
| VCC | M26 | Power/Other | |
| VCC | M27 | Power/Other | |
| VCC | M28 | Power/Other | |
| VCC | M29 | Power/Other | |
| VCC | M30 | Power/Other | |
| VCC | M8 | Power/Other | |
| VCC | N23 | Power/Other | |
| VCC | N24 | Power/Other | |
| VCC | N25 | Power/Other | |
| VCC | N26 | Power/Other | |
| VCC | N27 | Power/Other | |
| VCC | N28 | Power/Other | |
| VCC | N29 | Power/Other | |
| VCC | N30 | Power/Other | |
| VCC | N8 | Power/Other | |
| VCC | P8 | Power/Other | |
| VCC | R8 | Power/Other | |
| VCC | T23 | Power/Other | |
| VCC | T24 | Power/Other | |
| VCC | T25 | Power/Other | |
| VCC | T26 | Power/Other | |
| VCC | T27 | Power/Other | |
| VCC | T28 | Power/Other | |
| VCC | T29 | Power/Other | |
| VCC | T30 | Power/Other | |
| VCC | T8 | Power/Other | |
| VCC | U23 | Power/Other | |



Table 4-1. Land Listing by Land Name (Sheet 14 of 22)

| Pin Name | Pin No. | Signal Buffer Type | Direction |
|----------------|---------|--------------------|-----------|
| VCC | U24 | Power/Other | |
| VCC | U25 | Power/Other | |
| VCC | U26 | Power/Other | |
| VCC | U27 | Power/Other | |
| VCC | U28 | Power/Other | |
| VCC | U29 | Power/Other | |
| VCC | U30 | Power/Other | |
| VCC | U8 | Power/Other | |
| VCC | V8 | Power/Other | |
| VCC | W23 | Power/Other | |
| VCC | W24 | Power/Other | |
| VCC | W25 | Power/Other | |
| VCC | W26 | Power/Other | |
| VCC | W27 | Power/Other | |
| VCC | W28 | Power/Other | |
| VCC | W29 | Power/Other | |
| VCC | W30 | Power/Other | |
| VCC | W8 | Power/Other | |
| VCC | Y23 | Power/Other | |
| VCC | Y24 | Power/Other | |
| VCC | Y25 | Power/Other | |
| VCC | Y26 | Power/Other | |
| VCC | Y27 | Power/Other | |
| VCC | Y28 | Power/Other | |
| VCC | Y29 | Power/Other | |
| VCC | Y30 | Power/Other | |
| VCC | Y8 | Power/Other | |
| VCC_DIE_SENSE | AN3 | Power/Other | Output |
| VCC_DIE_SENSE2 | AL8 | Power/Other | Output |
| VCCPLL | D23 | Power/Other | Input |
| VID_SELECT | AN7 | Power/Other | Output |
| VID1 | AL5 | Power/Other | Output |
| VID2 | AM3 | Power/Other | Output |
| VID3 | AL6 | Power/Other | Output |
| VID4 | AK4 | Power/Other | Output |
| VID5 | AL4 | Power/Other | Output |
| VID6 | AM5 | Power/Other | Output |
| VSS | A12 | Power/Other | |
| VSS | A15 | Power/Other | |
| VSS | A18 | Power/Other | |
| VSS | A2 | Power/Other | |



Table 4-1. Land Listing by Land Name (Sheet 15 of 22)

| Pin Name | Pin No. | Signal Buffer Type | Direction |
|----------|---------|--------------------|-----------|
| VSS | A21 | Power/Other | |
| VSS | A6 | Power/Other | |
| VSS | A9 | Power/Other | |
| VSS | AA23 | Power/Other | |
| VSS | AA24 | Power/Other | |
| VSS | AA25 | Power/Other | |
| VSS | AA26 | Power/Other | |
| VSS | AA27 | Power/Other | |
| VSS | AA28 | Power/Other | |
| VSS | AA29 | Power/Other | |
| VSS | AA3 | Power/Other | |
| VSS | AA30 | Power/Other | |
| VSS | AA6 | Power/Other | |
| VSS | AA7 | Power/Other | |
| VSS | AB1 | Power/Other | |
| VSS | AB23 | Power/Other | |
| VSS | AB24 | Power/Other | |
| VSS | AB25 | Power/Other | |
| VSS | AB26 | Power/Other | |
| VSS | AB27 | Power/Other | |
| VSS | AB28 | Power/Other | |
| VSS | AB29 | Power/Other | |
| VSS | AB30 | Power/Other | |
| VSS | AB7 | Power/Other | |
| VSS | AC3 | Power/Other | |
| VSS | AC6 | Power/Other | |
| VSS | AC7 | Power/Other | |
| VSS | AD4 | Power/Other | |
| VSS | AD7 | Power/Other | |
| VSS | AE10 | Power/Other | |
| VSS | AE13 | Power/Other | |
| VSS | AE16 | Power/Other | |
| VSS | AE17 | Power/Other | |
| VSS | AE2 | Power/Other | |
| VSS | AE20 | Power/Other | |
| VSS | AE24 | Power/Other | |
| VSS | AE25 | Power/Other | |
| VSS | AE26 | Power/Other | |
| VSS | AE27 | Power/Other | |
| VSS | AE28 | Power/Other | |
| VSS | AE29 | Power/Other | |



Table 4-1. Land Listing by Land Name (Sheet 16 of 22)

| Pin Name | Pin No. | Signal Buffer Type | Direction |
|----------|---------|--------------------|-----------|
| VSS | AE30 | Power/Other | |
| VSS | AE5 | Power/Other | |
| VSS | AE7 | Power/Other | |
| VSS | AF10 | Power/Other | |
| VSS | AF13 | Power/Other | |
| VSS | AF16 | Power/Other | |
| VSS | AF17 | Power/Other | |
| VSS | AF20 | Power/Other | |
| VSS | AF23 | Power/Other | |
| VSS | AF24 | Power/Other | |
| VSS | AF25 | Power/Other | |
| VSS | AF26 | Power/Other | |
| VSS | AF27 | Power/Other | |
| VSS | AF28 | Power/Other | |
| VSS | AF29 | Power/Other | |
| VSS | AF3 | Power/Other | |
| VSS | AF30 | Power/Other | |
| VSS | AF6 | Power/Other | |
| VSS | AF7 | Power/Other | |
| VSS | AG10 | Power/Other | |
| VSS | AG13 | Power/Other | |
| VSS | AG16 | Power/Other | |
| VSS | AG17 | Power/Other | |
| VSS | AG20 | Power/Other | |
| VSS | AG23 | Power/Other | |
| VSS | AG24 | Power/Other | |
| VSS | AG7 | Power/Other | |
| VSS | AH1 | Power/Other | |
| VSS | AH10 | Power/Other | |
| VSS | AH13 | Power/Other | |
| VSS | AH16 | Power/Other | |
| VSS | AH17 | Power/Other | |
| VSS | AH20 | Power/Other | |
| VSS | AH23 | Power/Other | |
| VSS | AH24 | Power/Other | |
| VSS | AH3 | Power/Other | |
| VSS | AH6 | Power/Other | |
| VSS | AJ10 | Power/Other | |
| VSS | AJ13 | Power/Other | |
| VSS | AJ16 | Power/Other | |
| VSS | AJ17 | Power/Other | |



Table 4-1. Land Listing by Land Name (Sheet 17 of 22)

| Pin Name | Pin No. | Signal Buffer Type | Direction |
|----------|---------|--------------------|-----------|
| VSS | AJ20 | Power/Other | |
| VSS | AJ23 | Power/Other | |
| VSS | AJ24 | Power/Other | |
| VSS | AJ27 | Power/Other | |
| VSS | AJ28 | Power/Other | |
| VSS | AJ29 | Power/Other | |
| VSS | AJ30 | Power/Other | |
| VSS | AJ4 | Power/Other | |
| VSS | AK10 | Power/Other | |
| VSS | AK13 | Power/Other | |
| VSS | AK16 | Power/Other | |
| VSS | AK17 | Power/Other | |
| VSS | AK2 | Power/Other | |
| VSS | AK20 | Power/Other | |
| VSS | AK23 | Power/Other | |
| VSS | AK24 | Power/Other | |
| VSS | AK27 | Power/Other | |
| VSS | AK28 | Power/Other | |
| VSS | AK29 | Power/Other | |
| VSS | AK30 | Power/Other | |
| VSS | AK5 | Power/Other | |
| VSS | AK7 | Power/Other | |
| VSS | AL10 | Power/Other | |
| VSS | AL13 | Power/Other | |
| VSS | AL16 | Power/Other | |
| VSS | AL17 | Power/Other | |
| VSS | AL20 | Power/Other | |
| VSS | AL23 | Power/Other | |
| VSS | AL24 | Power/Other | |
| VSS | AL27 | Power/Other | |
| VSS | AL28 | Power/Other | |
| VSS | AL3 | Power/Other | |
| VSS | AM1 | Power/Other | |
| VSS | AM10 | Power/Other | |
| VSS | AM13 | Power/Other | |
| VSS | AM16 | Power/Other | |
| VSS | AM17 | Power/Other | |
| VSS | AM20 | Power/Other | |
| VSS | AM23 | Power/Other | |
| VSS | AM24 | Power/Other | |
| VSS | AM27 | Power/Other | |



Table 4-1. Land Listing by Land Name (Sheet 18 of 22)

| Pin Name | Pin No. | Signal Buffer Type | Direction |
|----------|---------|--------------------|-----------|
| VSS | AM28 | Power/Other | |
| VSS | AM4 | Power/Other | |
| VSS | AM7 | Power/Other | |
| VSS | AN1 | Power/Other | |
| VSS | AN10 | Power/Other | |
| VSS | AN13 | Power/Other | |
| VSS | AN16 | Power/Other | |
| VSS | AN17 | Power/Other | |
| VSS | AN2 | Power/Other | |
| VSS | AN20 | Power/Other | |
| VSS | AN23 | Power/Other | |
| VSS | AN24 | Power/Other | |
| VSS | B1 | Power/Other | |
| VSS | B11 | Power/Other | |
| VSS | B14 | Power/Other | |
| VSS | B17 | Power/Other | |
| VSS | B20 | Power/Other | |
| VSS | B24 | Power/Other | |
| VSS | B5 | Power/Other | |
| VSS | B8 | Power/Other | |
| VSS | C10 | Power/Other | |
| VSS | C13 | Power/Other | |
| VSS | C16 | Power/Other | |
| VSS | C19 | Power/Other | |
| VSS | C22 | Power/Other | |
| VSS | C24 | Power/Other | |
| VSS | C4 | Power/Other | |
| VSS | C7 | Power/Other | |
| VSS | D12 | Power/Other | |
| VSS | D15 | Power/Other | |
| VSS | D18 | Power/Other | |
| VSS | D21 | Power/Other | |
| VSS | D24 | Power/Other | |
| VSS | D3 | Power/Other | |
| VSS | D5 | Power/Other | |
| VSS | D6 | Power/Other | |
| VSS | D9 | Power/Other | |
| VSS | E11 | Power/Other | |
| VSS | E14 | Power/Other | |
| VSS | E17 | Power/Other | |
| VSS | E2 | Power/Other | |



Table 4-1. Land Listing by Land Name (Sheet 19 of 22)

| Pin Name | Pin No. | Signal Buffer Type | Direction |
|----------|---------|--------------------|-----------|
| VSS | E20 | Power/Other | |
| VSS | E25 | Power/Other | |
| VSS | E26 | Power/Other | |
| VSS | E27 | Power/Other | |
| VSS | E28 | Power/Other | |
| VSS | E8 | Power/Other | |
| VSS | F1 | Power/Other | |
| VSS | F10 | Power/Other | |
| VSS | F13 | Power/Other | |
| VSS | F16 | Power/Other | |
| VSS | F19 | Power/Other | |
| VSS | F22 | Power/Other | |
| VSS | F4 | Power/Other | |
| VSS | F7 | Power/Other | |
| VSS | H10 | Power/Other | |
| VSS | H11 | Power/Other | |
| VSS | H12 | Power/Other | |
| VSS | H13 | Power/Other | |
| VSS | H14 | Power/Other | |
| VSS | H17 | Power/Other | |
| VSS | H18 | Power/Other | |
| VSS | H19 | Power/Other | |
| VSS | H20 | Power/Other | |
| VSS | H21 | Power/Other | |
| VSS | H22 | Power/Other | |
| VSS | H23 | Power/Other | |
| VSS | H24 | Power/Other | |
| VSS | H25 | Power/Other | |
| VSS | H26 | Power/Other | |
| VSS | H27 | Power/Other | |
| VSS | H28 | Power/Other | |
| VSS | H29 | Power/Other | |
| VSS | H3 | Power/Other | |
| VSS | H6 | Power/Other | |
| VSS | H7 | Power/Other | |
| VSS | H8 | Power/Other | |
| VSS | H9 | Power/Other | |
| VSS | J4 | Power/Other | |
| VSS | J7 | Power/Other | |
| VSS | K2 | Power/Other | |
| VSS | K5 | Power/Other | |



Table 4-1. Land Listing by Land Name (Sheet 20 of 22)

| Pin Name | Pin No. | Signal Buffer Type | Direction |
|----------|---------|--------------------|-----------|
| VSS | K7 | Power/Other | |
| VSS | L23 | Power/Other | |
| VSS | L24 | Power/Other | |
| VSS | L25 | Power/Other | |
| VSS | L26 | Power/Other | |
| VSS | L27 | Power/Other | |
| VSS | L28 | Power/Other | |
| VSS | L29 | Power/Other | |
| VSS | L3 | Power/Other | |
| VSS | L30 | Power/Other | |
| VSS | L6 | Power/Other | |
| VSS | L7 | Power/Other | |
| VSS | M1 | Power/Other | |
| VSS | M7 | Power/Other | |
| VSS | N3 | Power/Other | |
| VSS | N6 | Power/Other | |
| VSS | N7 | Power/Other | |
| VSS | P23 | Power/Other | |
| VSS | P24 | Power/Other | |
| VSS | P25 | Power/Other | |
| VSS | P26 | Power/Other | |
| VSS | P27 | Power/Other | |
| VSS | P28 | Power/Other | |
| VSS | P29 | Power/Other | |
| VSS | P30 | Power/Other | |
| VSS | P4 | Power/Other | |
| VSS | P7 | Power/Other | |
| VSS | R2 | Power/Other | |
| VSS | R23 | Power/Other | |
| VSS | R24 | Power/Other | |
| VSS | R25 | Power/Other | |
| VSS | R26 | Power/Other | |
| VSS | R27 | Power/Other | |
| VSS | R28 | Power/Other | |
| VSS | R29 | Power/Other | |
| VSS | R30 | Power/Other | |
| VSS | R5 | Power/Other | |
| VSS | R7 | Power/Other | |
| VSS | T3 | Power/Other | |
| VSS | T6 | Power/Other | |
| VSS | T7 | Power/Other | |



Table 4-1. Land Listing by Land Name (Sheet 21 of 22)

| Pin Name | Pin No. | Signal Buffer Type | Direction |
|----------------|---------|--------------------|-----------|
| VSS | U7 | Power/Other | |
| VSS | V23 | Power/Other | |
| VSS | V24 | Power/Other | |
| VSS | V25 | Power/Other | |
| VSS | V26 | Power/Other | |
| VSS | V27 | Power/Other | |
| VSS | V28 | Power/Other | |
| VSS | V29 | Power/Other | |
| VSS | V3 | Power/Other | |
| VSS | V30 | Power/Other | |
| VSS | V6 | Power/Other | |
| VSS | V7 | Power/Other | |
| VSS | W4 | Power/Other | |
| VSS | W7 | Power/Other | |
| VSS | Y2 | Power/Other | |
| VSS | Y5 | Power/Other | |
| VSS | Y7 | Power/Other | |
| VSS_DIE_SENSE | AN4 | Power/Other | Output |
| VSS_DIE_SENSE2 | AL7 | Power/Other | Output |
| VTT | A25 | Power/Other | |
| VTT | A26 | Power/Other | |
| VTT | B25 | Power/Other | |
| VTT | B26 | Power/Other | |
| VTT | B27 | Power/Other | |
| VTT | B28 | Power/Other | |
| VTT | B29 | Power/Other | |
| VTT | B30 | Power/Other | |
| VTT | C25 | Power/Other | |
| VTT | C26 | Power/Other | |
| VTT | C27 | Power/Other | |
| VTT | C28 | Power/Other | |
| VTT | C29 | Power/Other | |
| VTT | C30 | Power/Other | |
| VTT | D25 | Power/Other | |
| VTT | D26 | Power/Other | |
| VTT | D27 | Power/Other | |
| VTT | D28 | Power/Other | |
| VTT | D29 | Power/Other | |
| VTT | D30 | Power/Other | |
| VTT | E30 | Power/Other | |
| VTT | F30 | Power/Other | |



Table 4-1. Land Listing by Land Name (Sheet 22 of 22)

| Pin Name | Pin No. | Signal Buffer Type | Direction |
|----------|---------|--------------------|-----------|
| VTT_OUT | AA1 | Power/Other | Output |
| VTT_OUT | J1 | Power/Other | Output |
| VTT_SEL | F27 | Power/Other | Output |



4.1.2 Land Listing by Land Number

Table 4-2. Land Listing by Land Number (Sheet 1 of 20)

| Pin No. | Pin Name | Signal Buffer Type | Direction |
|---------|----------|--------------------|--------------|
| A10 | D08# | Source Sync | Input/Output |
| A11 | D09# | Source Sync | Input/Output |
| A12 | VSS | Power/Other | |
| A13 | COMPO | Power/Other | Input |
| A14 | D50# | Source Sync | Input/Output |
| A15 | VSS | Power/Other | |
| A16 | DSTBN3# | Source Sync | Input/Output |
| A17 | D56# | Source Sync | Input/Output |
| A18 | VSS | Power/Other | |
| A19 | D61# | Source Sync | Input/Output |
| A2 | VSS | Power/Other | |
| A20 | RESERVED | | |
| A21 | VSS | Power/Other | |
| A22 | D62# | Source Sync | Input/Output |
| A23 | RESERVED | | |
| A24 | RESERVED | | |
| A25 | VTT | Power/Other | |
| A26 | VTT | Power/Other | |
| A3 | RS2# | Common Clk | Input |
| A4 | D02# | Source Sync | Input/Output |
| A5 | D04# | Source Sync | Input/Output |
| A6 | VSS | Power/Other | |
| A7 | D07# | Source Sync | Input/Output |
| A8 | DBIO# | Source Sync | Input/Output |
| A9 | VSS | Power/Other | |
| AA1 | VTT_OUT | Power/Other | Output |
| AA2 | LL_ID1 | Power/Other | Output |
| AA23 | VSS | Power/Other | |
| AA24 | VSS | Power/Other | |
| AA25 | VSS | Power/Other | |
| AA26 | VSS | Power/Other | |
| AA27 | VSS | Power/Other | |
| AA28 | VSS | Power/Other | |
| AA29 | VSS | Power/Other | |
| AA3 | VSS | Power/Other | |
| AA30 | VSS | Power/Other | |
| AA4 | A21# | Source Sync | Input/Output |
| AA5 | A23# | Source Sync | Input/Output |
| AA6 | VSS | Power/Other | |



Table 4-2. Land Listing by Land Number (Sheet 2 of 20)

| Pin No. | Pin Name | Signal Buffer Type | Direction |
|---------|----------|--------------------|--------------|
| AA7 | VSS | Power/Other | |
| AA8 | VCC | Power/Other | |
| AB1 | VSS | Power/Other | |
| AB2 | IERR# | ASync GTL+ | Output |
| AB23 | VSS | Power/Other | |
| AB24 | VSS | Power/Other | |
| AB25 | VSS | Power/Other | |
| AB26 | VSS | Power/Other | |
| AB27 | VSS | Power/Other | |
| AB28 | VSS | Power/Other | |
| AB29 | VSS | Power/Other | |
| AB3 | MCERR# | Common Clk | Input/Output |
| AB30 | VSS | Power/Other | |
| AB4 | A26# | Source Sync | Input/Output |
| AB5 | A24# | Source Sync | Input/Output |
| AB6 | A17# | Source Sync | Input/Output |
| AB7 | VSS | Power/Other | |
| AB8 | VCC | Power/Other | |
| AC1 | TMS | TAP | Input |
| AC2 | DBR# | Power/Other | Output |
| AC23 | VCC | Power/Other | |
| AC24 | VCC | Power/Other | |
| AC25 | VCC | Power/Other | |
| AC26 | VCC | Power/Other | |
| AC27 | VCC | Power/Other | |
| AC28 | VCC | Power/Other | |
| AC29 | VCC | Power/Other | |
| AC3 | VSS | Power/Other | |
| AC30 | VCC | Power/Other | |
| AC4 | RESERVED | | |
| AC5 | A25# | Source Sync | Input/Output |
| AC6 | VSS | Power/Other | |
| AC7 | VSS | Power/Other | |
| AC8 | VCC | Power/Other | |
| AD1 | TDI | TAP | Input |
| AD2 | BPM2# | Common Clk | Output |
| AD23 | VCC | Power/Other | |
| AD24 | VCC | Power/Other | |
| AD25 | VCC | Power/Other | |
| AD26 | VCC | Power/Other | |
| AD27 | VCC | Power/Other | |



Table 4-2. Land Listing by Land Number (Sheet 3 of 20)

| Pin No. | Pin Name | Signal Buffer Type | Direction |
|---------|----------|--------------------|--------------|
| AD28 | VCC | Power/Other | |
| AD29 | VCC | Power/Other | |
| AD3 | BINIT# | Common Clk | Input/Output |
| AD30 | VCC | Power/Other | |
| AD4 | VSS | Power/Other | |
| AD5 | ADSTB1# | Source Sync | Input/Output |
| AD6 | A22# | Source Sync | Input/Output |
| AD7 | VSS | Power/Other | |
| AD8 | VCC | Power/Other | |
| AE1 | TCK | TAP | Input |
| AE10 | VSS | Power/Other | |
| AE11 | VCC | Power/Other | |
| AE12 | VCC | Power/Other | |
| AE13 | VSS | Power/Other | |
| AE14 | VCC | Power/Other | |
| AE15 | VCC | Power/Other | |
| AE16 | VSS | Power/Other | |
| AE17 | VSS | Power/Other | |
| AE18 | VCC | Power/Other | |
| AE19 | VCC | Power/Other | |
| AE2 | VSS | Power/Other | |
| AE20 | VSS | Power/Other | |
| AE21 | VCC | Power/Other | |
| AE22 | VCC | Power/Other | |
| AE23 | VCC | Power/Other | |
| AE24 | VSS | Power/Other | |
| AE25 | VSS | Power/Other | |
| AE26 | VSS | Power/Other | |
| AE27 | VSS | Power/Other | |
| AE28 | VSS | Power/Other | |
| AE29 | VSS | Power/Other | |
| AE3 | RESERVED | | |
| AE30 | VSS | Power/Other | |
| AE4 | RESERVED | | |
| AE5 | VSS | Power/Other | |
| AE6 | RESERVED | | |
| AE7 | VSS | Power/Other | |
| AE8 | SKTOCC# | Power/Other | Output |
| AE9 | VCC | Power/Other | |
| AF1 | TDO | TAP | Output |
| AF10 | VSS | Power/Other | |



Table 4-2. Land Listing by Land Number (Sheet 4 of 20)

| Pin No. | Pin Name | Signal Buffer Type | Direction |
|---------|----------|--------------------|--------------|
| AF11 | VCC | Power/Other | |
| AF12 | VCC | Power/Other | |
| AF13 | VSS | Power/Other | |
| AF14 | VCC | Power/Other | |
| AF15 | VCC | Power/Other | |
| AF16 | VSS | Power/Other | |
| AF17 | VSS | Power/Other | |
| AF18 | VCC | Power/Other | |
| AF19 | VCC | Power/Other | |
| AF2 | BPM4# | Common Clk | Output |
| AF20 | VSS | Power/Other | |
| AF21 | VCC | Power/Other | |
| AF22 | VCC | Power/Other | |
| AF23 | VSS | Power/Other | |
| AF24 | VSS | Power/Other | |
| AF25 | VSS | Power/Other | |
| AF26 | VSS | Power/Other | |
| AF27 | VSS | Power/Other | |
| AF28 | VSS | Power/Other | |
| AF29 | VSS | Power/Other | |
| AF3 | VSS | Power/Other | |
| AF30 | VSS | Power/Other | |
| AF4 | A28# | Source Sync | Input/Output |
| AF5 | A27# | Source Sync | Input/Output |
| AF6 | VSS | Power/Other | |
| AF7 | VSS | Power/Other | |
| AF8 | VCC | Power/Other | |
| AF9 | VCC | Power/Other | |
| AG1 | TRST# | TAP | Input |
| AG10 | VSS | Power/Other | |
| AG11 | VCC | Power/Other | |
| AG12 | VCC | Power/Other | |
| AG13 | VSS | Power/Other | |
| AG14 | VCC | Power/Other | |
| AG15 | VCC | Power/Other | |
| AG16 | VSS | Power/Other | |
| AG17 | VSS | Power/Other | |
| AG18 | VCC | Power/Other | |
| AG19 | VCC | Power/Other | |
| AG2 | BPM3# | Common Clk | Input/Output |
| AG20 | VSS | Power/Other | |



Table 4-2. Land Listing by Land Number (Sheet 5 of 20)

| Pin No. | Pin Name | Signal Buffer Type | Direction |
|---------|----------|--------------------|--------------|
| AG21 | VCC | Power/Other | |
| AG22 | VCC | Power/Other | |
| AG23 | VSS | Power/Other | |
| AG24 | VSS | Power/Other | |
| AG25 | VCC | Power/Other | |
| AG26 | VCC | Power/Other | |
| AG27 | VCC | Power/Other | |
| AG28 | VCC | Power/Other | |
| AG29 | VCC | Power/Other | |
| AG3 | BPM5# | Common Clk | Input/Output |
| AG30 | VCC | Power/Other | |
| AG4 | A30# | Source Sync | Input/Output |
| AG5 | A31# | Source Sync | Input/Output |
| AG6 | A29# | Source Sync | Input/Output |
| AG7 | VSS | Power/Other | |
| AG8 | VCC | Power/Other | |
| AG9 | VCC | Power/Other | |
| AH1 | VSS | Power/Other | |
| AH10 | VSS | Power/Other | |
| AH11 | VCC | Power/Other | |
| AH12 | VCC | Power/Other | |
| AH13 | VSS | Power/Other | |
| AH14 | VCC | Power/Other | |
| AH15 | VCC | Power/Other | |
| AH16 | VSS | Power/Other | |
| AH17 | VSS | Power/Other | |
| AH18 | VCC | Power/Other | |
| AH19 | VCC | Power/Other | |
| AH2 | RESERVED | | |
| AH20 | VSS | Power/Other | |
| AH21 | VCC | Power/Other | |
| AH22 | VCC | Power/Other | |
| AH23 | VSS | Power/Other | |
| AH24 | VSS | Power/Other | |
| AH25 | VCC | Power/Other | |
| AH26 | VCC | Power/Other | |
| AH27 | VCC | Power/Other | |
| AH28 | VCC | Power/Other | |
| AH29 | VCC | Power/Other | |
| AH3 | VSS | Power/Other | |
| AH30 | VCC | Power/Other | |



Table 4-2. Land Listing by Land Number (Sheet 6 of 20)

| Pin No. | Pin Name | Signal Buffer Type | Direction |
|---------|----------|--------------------|--------------|
| AH4 | A32# | Source Sync | Input/Output |
| AH5 | A33# | Source Sync | Input/Output |
| AH6 | VSS | Power/Other | |
| AH7 | RESERVED | | |
| AH8 | VCC | Power/Other | |
| AH9 | VCC | Power/Other | |
| AJ1 | BPM1# | Common Clk | Output |
| AJ10 | VSS | Power/Other | |
| AJ11 | VCC | Power/Other | |
| AJ12 | VCC | Power/Other | |
| AJ13 | VSS | Power/Other | |
| AJ14 | VCC | Power/Other | |
| AJ15 | VCC | Power/Other | |
| AJ16 | VSS | Power/Other | |
| AJ17 | VSS | Power/Other | |
| AJ18 | VCC | Power/Other | |
| AJ19 | VCC | Power/Other | |
| AJ2 | BPM0# | Common Clk | Input/Output |
| AJ20 | VSS | Power/Other | |
| AJ21 | VCC | Power/Other | |
| AJ22 | VCC | Power/Other | |
| AJ23 | VSS | Power/Other | |
| AJ24 | VSS | Power/Other | |
| AJ25 | VCC | Power/Other | |
| AJ26 | VCC | Power/Other | |
| AJ27 | VSS | Power/Other | |
| AJ28 | VSS | Power/Other | |
| AJ29 | VSS | Power/Other | |
| AJ3 | RESERVED | | |
| AJ30 | VSS | Power/Other | |
| AJ4 | VSS | Power/Other | |
| AJ5 | A34# | Source Sync | Input/Output |
| AJ6 | A35# | Source Sync | Input/Output |
| AJ7 | RESERVED | | |
| AJ8 | VCC | Power/Other | |
| AJ9 | VCC | Power/Other | |
| AK1 | RESERVED | | |
| AK10 | VSS | Power/Other | |
| AK11 | VCC | Power/Other | |
| AK12 | VCC | Power/Other | |
| AK13 | VSS | Power/Other | |



Table 4-2. Land Listing by Land Number (Sheet 7 of 20)

| Pin No. | Pin Name | Signal Buffer Type | Direction |
|---------|----------|--------------------|-----------|
| AK14 | VCC | Power/Other | |
| AK15 | VCC | Power/Other | |
| AK16 | VSS | Power/Other | |
| AK17 | VSS | Power/Other | |
| AK18 | VCC | Power/Other | |
| AK19 | VCC | Power/Other | |
| AK2 | VSS | Power/Other | |
| AK20 | VSS | Power/Other | |
| AK21 | VCC | Power/Other | |
| AK22 | VCC | Power/Other | |
| AK23 | VSS | Power/Other | |
| AK24 | VSS | Power/Other | |
| AK25 | VCC | Power/Other | |
| AK26 | VCC | Power/Other | |
| AK27 | VSS | Power/Other | |
| AK28 | VSS | Power/Other | |
| AK29 | VSS | Power/Other | |
| AK3 | RESERVED | | |
| AK30 | VSS | Power/Other | |
| AK4 | VID4 | Power/Other | Output |
| AK5 | VSS | Power/Other | |
| AK6 | FORCEPR# | ASync GTL+ | Input |
| AK7 | VSS | Power/Other | |
| AK8 | VCC | Power/Other | |
| AK9 | VCC | Power/Other | |
| AL1 | RESERVED | | |
| AL10 | VSS | Power/Other | |
| AL11 | VCC | Power/Other | |
| AL12 | VCC | Power/Other | |
| AL13 | VSS | Power/Other | |
| AL14 | VCC | Power/Other | |
| AL15 | VCC | Power/Other | |
| AL16 | VSS | Power/Other | |
| AL17 | VSS | Power/Other | |
| AL18 | VCC | Power/Other | |
| AL19 | VCC | Power/Other | |
| AL2 | PROCHOT# | ASync GTL+ | Output |
| AL20 | VSS | Power/Other | |
| AL21 | VCC | Power/Other | |
| AL22 | VCC | Power/Other | |
| AL23 | VSS | Power/Other | |



Table 4-2. Land Listing by Land Number (Sheet 8 of 20)

| Pin No. | Pin Name | Signal Buffer Type | Direction |
|---------|----------------|--------------------|-----------|
| AL24 | VSS | Power/Other | |
| AL25 | VCC | Power/Other | |
| AL26 | VCC | Power/Other | |
| AL27 | VSS | Power/Other | |
| AL28 | VSS | Power/Other | |
| AL29 | VCC | Power/Other | |
| AL3 | VSS | Power/Other | |
| AL30 | VCC | Power/Other | |
| AL4 | VID5 | Power/Other | Output |
| AL5 | VID1 | Power/Other | Output |
| AL6 | VID3 | Power/Other | Output |
| AL7 | VSS_DIE_SENSE2 | Power/Other | |
| AL8 | VCC_DIE_SENSE2 | Power/Other | |
| AL9 | VCC | Power/Other | |
| AM1 | VSS | Power/Other | |
| AM10 | VSS | Power/Other | |
| AM11 | VCC | Power/Other | |
| AM12 | VCC | Power/Other | |
| AM13 | VSS | Power/Other | |
| AM14 | VCC | Power/Other | |
| AM15 | VCC | Power/Other | |
| AM16 | VSS | Power/Other | |
| AM17 | VSS | Power/Other | |
| AM18 | VCC | Power/Other | |
| AM19 | VCC | Power/Other | |
| AM2 | RESERVED | | |
| AM20 | VSS | Power/Other | |
| AM21 | VCC | Power/Other | |
| AM22 | VCC | Power/Other | |
| AM23 | VSS | Power/Other | |
| AM24 | VSS | Power/Other | |
| AM25 | VCC | Power/Other | |
| AM26 | VCC | Power/Other | |
| AM27 | VSS | Power/Other | |
| AM28 | VSS | Power/Other | |
| AM29 | VCC | Power/Other | |
| AM3 | VID2 | Power/Other | Output |
| AM30 | VCC | Power/Other | |
| AM4 | VSS | Power/Other | |
| AM5 | VID6 | Power/Other | Output |
| AM6 | RESERVED | | |



Table 4-2. Land Listing by Land Number (Sheet 9 of 20)

| Pin No. | Pin Name | Signal Buffer Type | Direction |
|---------|---------------|--------------------|--------------|
| AM7 | VSS | Power/Other | |
| AM8 | VCC | Power/Other | |
| AM9 | VCC | Power/Other | |
| AN1 | VSS | Power/Other | |
| AN10 | VSS | Power/Other | |
| AN11 | VCC | Power/Other | |
| AN12 | VCC | Power/Other | |
| AN13 | VSS | Power/Other | |
| AN14 | VCC | Power/Other | |
| AN15 | VCC | Power/Other | |
| AN16 | VSS | Power/Other | |
| AN17 | VSS | Power/Other | |
| AN18 | VCC | Power/Other | |
| AN19 | VCC | Power/Other | |
| AN2 | VSS | Power/Other | |
| AN20 | VSS | Power/Other | |
| AN21 | VCC | Power/Other | |
| AN22 | VCC | Power/Other | |
| AN23 | VSS | Power/Other | |
| AN24 | VSS | Power/Other | |
| AN25 | VCC | Power/Other | |
| AN26 | VCC | Power/Other | |
| AN3 | VCC_DIE_SENSE | Power/Other | Output |
| AN4 | VSS_DIE_SENSE | Power/Other | Output |
| AN5 | RESERVED | | |
| AN6 | RESERVED | | |
| AN7 | VID_SELECT | Power/Other | Output |
| AN8 | VCC | Power/Other | |
| AN9 | VCC | Power/Other | |
| B1 | VSS | Power/Other | |
| B10 | D10# | Source Sync | Input/Output |
| B11 | VSS | Power/Other | |
| B12 | D13# | Source Sync | Input/Output |
| B13 | RESERVED | | |
| B14 | VSS | Power/Other | |
| B15 | D53# | Source Sync | Input/Output |
| B16 | D55# | Source Sync | Input/Output |
| B17 | VSS | Power/Other | |
| B18 | D57# | Source Sync | Input/Output |
| B19 | D60# | Source Sync | Input/Output |
| B2 | DBSY# | Common Clk | Input/Output |



Table 4-2. Land Listing by Land Number (Sheet 10 of 20)

| Pin No. | Pin Name | Signal Buffer Type | Direction |
|---------|----------|--------------------|--------------|
| B20 | VSS | Power/Other | |
| B21 | D59# | Source Sync | Input/Output |
| B22 | D63# | Source Sync | Input/Output |
| B23 | RESERVED | | |
| B24 | VSS | Power/Other | |
| B25 | VTT | Power/Other | |
| B26 | VTT | Power/Other | |
| B27 | VTT | Power/Other | |
| B28 | VTT | Power/Other | |
| B29 | VTT | Power/Other | |
| B3 | RS0# | Common Clk | Input |
| B30 | VTT | Power/Other | |
| B4 | D00# | Source Sync | Input/Output |
| B5 | VSS | Power/Other | |
| B6 | D05# | Source Sync | Input/Output |
| B7 | D06# | Source Sync | Input/Output |
| B8 | VSS | Power/Other | |
| B9 | DSTBP0# | Source Sync | Input/Output |
| C1 | DRDY# | Common Clk | Input/Output |
| C10 | VSS | Power/Other | |
| C11 | D11# | Source Sync | Input/Output |
| C12 | D14# | Source Sync | Input/Output |
| C13 | VSS | Power/Other | |
| C14 | D52# | Source Sync | Input/Output |
| C15 | D51# | Source Sync | Input/Output |
| C16 | VSS | Power/Other | |
| C17 | DSTBP3# | Source Sync | Input/Output |
| C18 | D54# | Source Sync | Input/Output |
| C19 | VSS | Power/Other | |
| C2 | BNR# | Common Clk | Input/Output |
| C20 | DBI3# | Source Sync | Input/Output |
| C21 | D58# | Source Sync | Input/Output |
| C22 | VSS | Power/Other | |
| C23 | RESERVED | | |
| C24 | VSS | Power/Other | |
| C25 | VTT | Power/Other | |
| C26 | VTT | Power/Other | |
| C27 | VTT | Power/Other | |
| C28 | VTT | Power/Other | |
| C29 | VTT | Power/Other | |
| C3 | LOCK# | Common Clk | Input/Output |



Table 4-2. Land Listing by Land Number (Sheet 11 of 20)

| Pin No. | Pin Name | Signal Buffer Type | Direction |
|---------|----------|--------------------|--------------|
| C30 | VTT | Power/Other | |
| C4 | VSS | Power/Other | |
| C5 | D01# | Source Sync | Input/Output |
| C6 | D03# | Source Sync | Input/Output |
| C7 | VSS | Power/Other | |
| C8 | DSTBNO# | Source Sync | Input/Output |
| C9 | BPMb1# | Common Clk | Output |
| D1 | RESERVED | | |
| D10 | D22# | Source Sync | Input/Output |
| D11 | D15# | Source Sync | Input/Output |
| D12 | VSS | Power/Other | |
| D13 | D25# | Source Sync | Input/Output |
| D14 | RESERVED | | |
| D15 | VSS | Power/Other | |
| D16 | RESERVED | | |
| D17 | D49# | Source Sync | Input/Output |
| D18 | VSS | Power/Other | |
| D19 | DBI2# | Source Sync | Input/Output |
| D2 | ADS# | Common Clk | Input/Output |
| D20 | D48# | Source Sync | Input/Output |
| D21 | VSS | Power/Other | |
| D22 | D46# | Source Sync | Input/Output |
| D23 | VCCPLL | Power/Other | Input |
| D24 | VSS | Power/Other | |
| D25 | VTT | Power/Other | |
| D26 | VTT | Power/Other | |
| D27 | VTT | Power/Other | |
| D28 | VTT | Power/Other | |
| D29 | VTT | Power/Other | |
| D3 | VSS | Power/Other | |
| D30 | VTT | Power/Other | |
| D4 | HIT# | Common Clk | Input/Output |
| D5 | VSS | Power/Other | |
| D6 | VSS | Power/Other | |
| D7 | D20# | Source Sync | Input/Output |
| D8 | D12# | Source Sync | Input/Output |
| D9 | VSS | Power/Other | |
| E1 | RESERVED | Power/Other | |
| E10 | D21# | Source Sync | Input/Output |
| E11 | VSS | Power/Other | |
| E12 | DSTBP1# | Source Sync | Input/Output |



Table 4-2. Land Listing by Land Number (Sheet 12 of 20)

| Pin No. | Pin Name | Signal Buffer Type | Direction |
|---------|----------------|--------------------|--------------|
| E13 | D26# | Source Sync | Input/Output |
| E14 | VSS | Power/Other | |
| E15 | D33# | Source Sync | Input/Output |
| E16 | D34# | Source Sync | Input/Output |
| E17 | VSS | Power/Other | |
| E18 | D39# | Source Sync | Input/Output |
| E19 | D40# | Source Sync | Input/Output |
| E2 | VSS | Power/Other | |
| E20 | VSS | Power/Other | |
| E21 | D42# | Source Sync | Input/Output |
| E22 | D45# | Source Sync | Input/Output |
| E23 | RESERVED | | |
| E24 | RESERVED | | |
| E25 | VSS | Power/Other | |
| E26 | VSS | Power/Other | |
| E27 | VSS | Power/Other | |
| E28 | VSS | Power/Other | |
| E29 | RESERVED | | |
| E3 | TRDY# | Common Clk | Input |
| E30 | VTT | Power/Other | |
| E4 | HITM# | Common Clk | Input/Output |
| E5 | RESERVED | | |
| E6 | RESERVED | | |
| E7 | RESERVED | | |
| E8 | VSS | Power/Other | |
| E9 | D19# | Source Sync | Input/Output |
| F1 | VSS | Power/Other | |
| F10 | VSS | Power/Other | |
| F11 | D23# | Source Sync | Input/Output |
| F12 | D24# | Source Sync | Input/Output |
| F13 | VSS | Power/Other | |
| F14 | D28# | Source Sync | Input/Output |
| F15 | D30# | Source Sync | Input/Output |
| F16 | VSS | Power/Other | |
| F17 | D37# | Source Sync | Input/Output |
| F18 | D38# | Source Sync | Input/Output |
| F19 | VSS | Power/Other | |
| F2 | GTLREF_ADD_MID | Power/Other | Input |
| F20 | D41# | Source Sync | Input/Output |
| F21 | D43# | Source Sync | Input/Output |
| F22 | VSS | Power/Other | |



Table 4-2. Land Listing by Land Number (Sheet 13 of 20)

| Pin No. | Pin Name | Signal Buffer Type | Direction |
|---------|----------------|--------------------|--------------|
| F23 | RESERVED | | |
| F24 | TESTHI07 | Power/Other | Input |
| F25 | TESTHI02 | Power/Other | Input |
| F26 | TESTHI00 | Power/Other | Input |
| F27 | VTT_SEL | Power/Other | Output |
| F28 | BCLK0 | Clk | Input |
| F29 | RESERVED | | |
| F3 | BR0# | Common Clk | Input/Output |
| F30 | VTT | Power/Other | |
| F4 | VSS | Power/Other | |
| F5 | RS1# | Common Clk | Input |
| F6 | RESERVED | | |
| F7 | VSS | Power/Other | |
| F8 | D17# | Source Sync | Input/Output |
| F9 | D18# | Source Sync | Input/Output |
| G1 | BPMb0# | Power/Other | Input/Output |
| G10 | GTLREF_ADD_END | Power/Other | Input |
| G11 | DBI1# | Source Sync | Input/Output |
| G12 | DSTBN1# | Source Sync | Input/Output |
| G13 | D27# | Source Sync | Input/Output |
| G14 | D29# | Source Sync | Input/Output |
| G15 | D31# | Source Sync | Input/Output |
| G16 | D32# | Source Sync | Input/Output |
| G17 | D36# | Source Sync | Input/Output |
| G18 | D35# | Source Sync | Input/Output |
| G19 | DSTBP2# | Source Sync | Input/Output |
| G2 | COMP2 | Power/Other | Input |
| G20 | DSTBN2# | Source Sync | Input/Output |
| G21 | D44# | Source Sync | Input/Output |
| G22 | D47# | Source Sync | Input/Output |
| G23 | RESET# | Common Clk | Input |
| G24 | TESTHI06 | Power/Other | Input |
| G25 | TESTHI03 | Power/Other | Input |
| G26 | TESTHI05 | Power/Other | Input |
| G27 | TESTHI04 | Power/Other | Input |
| G28 | BCLK1 | Clk | Input |
| G29 | BSEL0 | Power/Other | Output |
| G3 | BPMb3# | Common Clk | Input/Output |
| G30 | BSEL2 | Power/Other | Output |
| G4 | BPMb2# | Common Clk | Output |
| G5 | PECI | Power/Other | Input/Output |



Table 4-2. Land Listing by Land Number (Sheet 14 of 20)

| Pin No. | Pin Name | Signal Buffer Type | Direction |
|---------|-----------------|--------------------|--------------|
| G6 | RESERVED | | |
| G7 | DEFER# | Common Clk | Input |
| G8 | BPRI# | Common Clk | Input |
| G9 | D16# | Source Sync | Input/Output |
| H1 | GTLREF_DATA_END | Power/Other | Input |
| H10 | VSS | Power/Other | |
| H11 | VSS | Power/Other | |
| H12 | VSS | Power/Other | |
| H13 | VSS | Power/Other | |
| H14 | VSS | Power/Other | |
| H15 | DP1# | Common Clk | Input/Output |
| H16 | DP2# | Common Clk | Input/Output |
| H17 | VSS | Power/Other | |
| H18 | VSS | Power/Other | |
| H19 | VSS | Power/Other | |
| H2 | GTLREF_DATA_MID | Power/Other | Input |
| H20 | VSS | Power/Other | |
| H21 | VSS | Power/Other | |
| H22 | VSS | Power/Other | |
| H23 | VSS | Power/Other | |
| H24 | VSS | Power/Other | |
| H25 | VSS | Power/Other | |
| H26 | VSS | Power/Other | |
| H27 | VSS | Power/Other | |
| H28 | VSS | Power/Other | |
| H29 | VSS | Power/Other | |
| H3 | VSS | Power/Other | |
| H30 | BSEL1 | Power/Other | Output |
| H4 | RSP# | Common Clk | Input |
| H5 | BR1# | Common Clk | Input |
| H6 | VSS | Power/Other | |
| H7 | VSS | Power/Other | |
| H8 | VSS | Power/Other | |
| H9 | VSS | Power/Other | |
| J1 | VTT_OUT | Power/Other | Output |
| J10 | VCC | Power/Other | |
| J11 | VCC | Power/Other | |
| J12 | VCC | Power/Other | |
| J13 | VCC | Power/Other | |
| J14 | VCC | Power/Other | |
| J15 | VCC | Power/Other | |



Table 4-2. Land Listing by Land Number (Sheet 15 of 20)

| Pin No. | Pin Name | Signal Buffer Type | Direction |
|---------|----------|--------------------|--------------|
| J16 | DP0# | Common Clk | Input/Output |
| J17 | DP3# | Common Clk | Input/Output |
| J18 | VCC | Power/Other | |
| J19 | VCC | Power/Other | |
| J2 | RESERVED | | |
| J20 | VCC | Power/Other | |
| J21 | VCC | Power/Other | |
| J22 | VCC | Power/Other | |
| J23 | VCC | Power/Other | |
| J24 | VCC | Power/Other | |
| J25 | VCC | Power/Other | |
| J26 | VCC | Power/Other | |
| J27 | VCC | Power/Other | |
| J28 | VCC | Power/Other | |
| J29 | VCC | Power/Other | |
| J3 | RESERVED | | |
| J30 | VCC | Power/Other | |
| J4 | VSS | Power/Other | |
| J5 | REQ1# | Source Sync | Input/Output |
| J6 | REQ4# | Source Sync | Input/Output |
| J7 | VSS | Power/Other | |
| J8 | VCC | Power/Other | |
| J9 | VCC | Power/Other | |
| K1 | LINT0 | ASync GTL+ | Input |
| K2 | VSS | Power/Other | |
| K23 | VCC | Power/Other | |
| K24 | VCC | Power/Other | |
| K25 | VCC | Power/Other | |
| K26 | VCC | Power/Other | |
| K27 | VCC | Power/Other | |
| K28 | VCC | Power/Other | |
| K29 | VCC | Power/Other | |
| K3 | A20M# | ASync GTL+ | Input |
| K30 | VCC | Power/Other | |
| K4 | REQ0# | Source Sync | Input/Output |
| K5 | VSS | Power/Other | |
| K6 | REQ3# | Source Sync | Input/Output |
| K7 | VSS | Power/Other | |
| K8 | VCC | Power/Other | |
| L1 | LINT1 | ASync GTL+ | Input |
| L2 | TESTHI11 | ASync GTL+ | Input |



Table 4-2. Land Listing by Land Number (Sheet 16 of 20)

| Pin No. | Pin Name | Signal Buffer Type | Direction |
|---------|------------|--------------------|--------------|
| L23 | VSS | Power/Other | |
| L24 | VSS | Power/Other | |
| L25 | VSS | Power/Other | |
| L26 | VSS | Power/Other | |
| L27 | VSS | Power/Other | |
| L28 | VSS | Power/Other | |
| L29 | VSS | Power/Other | |
| L3 | VSS | Power/Other | |
| L30 | VSS | Power/Other | |
| L4 | A06# | Source Sync | Input/Output |
| L5 | A05# | Source Sync | Input/Output |
| L6 | VSS | Power/Other | |
| L7 | VSS | Power/Other | |
| L8 | VCC | Power/Other | |
| M1 | VSS | Power/Other | |
| M2 | THERMTRIP# | ASync GTL+ | Output |
| M23 | VCC | Power/Other | |
| M24 | VCC | Power/Other | |
| M25 | VCC | Power/Other | |
| M26 | VCC | Power/Other | |
| M27 | VCC | Power/Other | |
| M28 | VCC | Power/Other | |
| M29 | VCC | Power/Other | |
| M3 | STPCLK# | ASync GTL+ | Input |
| M30 | VCC | Power/Other | |
| M4 | A07# | Source Sync | Input/Output |
| M5 | A03# | Source Sync | Input/Output |
| M6 | REQ2# | Source Sync | Input/Output |
| M7 | VSS | Power/Other | |
| M8 | VCC | Power/Other | |
| N1 | PWRGOOD | Power/Other | Input |
| N2 | IGNNE# | ASync GTL+ | Input |
| N23 | VCC | Power/Other | |
| N24 | VCC | Power/Other | |
| N25 | VCC | Power/Other | |
| N26 | VCC | Power/Other | |
| N27 | VCC | Power/Other | |
| N28 | VCC | Power/Other | |
| N29 | VCC | Power/Other | |
| N3 | VSS | Power/Other | |
| N30 | VCC | Power/Other | |



Table 4-2. Land Listing by Land Number (Sheet 17 of 20)

| Pin No. | Pin Name | Signal Buffer Type | Direction |
|---------|------------|--------------------|--------------|
| N4 | A36# | Source Sync | Input/Output |
| N5 | RESERVED | | |
| N6 | VSS | Power/Other | |
| N7 | VSS | Power/Other | |
| N8 | VCC | Power/Other | |
| P1 | TESTHI10 | Power/Other | Input |
| P2 | SMI# | ASync GTL+ | Input |
| P23 | VSS | Power/Other | |
| P24 | VSS | Power/Other | |
| P25 | VSS | Power/Other | |
| P26 | VSS | Power/Other | |
| P27 | VSS | Power/Other | |
| P28 | VSS | Power/Other | |
| P29 | VSS | Power/Other | |
| P3 | INIT# | ASync GTL+ | Input |
| P30 | VSS | Power/Other | |
| P4 | VSS | Power/Other | |
| P5 | A37# | Source Sync | Input/Output |
| P6 | A04# | Source Sync | Input/Output |
| P7 | VSS | Power/Other | |
| P8 | VCC | Power/Other | |
| R1 | COMP3 | Power/Other | Input |
| R2 | VSS | Power/Other | |
| R23 | VSS | Power/Other | |
| R24 | VSS | Power/Other | |
| R25 | VSS | Power/Other | |
| R26 | VSS | Power/Other | |
| R27 | VSS | Power/Other | |
| R28 | VSS | Power/Other | |
| R29 | VSS | Power/Other | |
| R3 | FERR#/PBE# | ASync GTL+ | Output |
| R30 | VSS | Power/Other | |
| R4 | A08# | Source Sync | Input/Output |
| R5 | VSS | Power/Other | |
| R6 | ADSTB0# | Source Sync | Input/Output |
| R7 | VSS | Power/Other | |
| R8 | VCC | Power/Other | |
| T1 | COMP1 | Power/Other | Input |
| T2 | RESERVED | | |
| T23 | VCC | Power/Other | |
| T24 | VCC | Power/Other | |



Table 4-2. Land Listing by Land Number (Sheet 18 of 20)

| Pin No. | Pin Name | Signal Buffer Type | Direction |
|---------|----------|--------------------|--------------|
| T25 | VCC | Power/Other | |
| T26 | VCC | Power/Other | |
| T27 | VCC | Power/Other | |
| T28 | VCC | Power/Other | |
| T29 | VCC | Power/Other | |
| T3 | VSS | Power/Other | |
| T30 | VCC | Power/Other | |
| T4 | A11# | Source Sync | Input/Output |
| T5 | A09# | Source Sync | Input/Output |
| T6 | VSS | Power/Other | |
| T7 | VSS | Power/Other | |
| T8 | VCC | Power/Other | |
| U1 | TESTIN2 | Power/Other | Input |
| U2 | AP0# | Common Clk | Input/Output |
| U23 | VCC | Power/Other | |
| U24 | VCC | Power/Other | |
| U25 | VCC | Power/Other | |
| U26 | VCC | Power/Other | |
| U27 | VCC | Power/Other | |
| U28 | VCC | Power/Other | |
| U29 | VCC | Power/Other | |
| U3 | AP1# | Common Clk | Input/Output |
| U30 | VCC | Power/Other | |
| U4 | A13# | Source Sync | Input/Output |
| U5 | A12# | Source Sync | Input/Output |
| U6 | A10# | Source Sync | Input/Output |
| U7 | VSS | Power/Other | |
| U8 | VCC | Power/Other | |
| V1 | MS_ID1 | Power/Other | Output |
| V2 | LL_ID0 | Power/Other | Output |
| V23 | VSS | Power/Other | |
| V24 | VSS | Power/Other | |
| V25 | VSS | Power/Other | |
| V26 | VSS | Power/Other | |
| V27 | VSS | Power/Other | |
| V28 | VSS | Power/Other | |
| V29 | VSS | Power/Other | |
| V3 | VSS | Power/Other | |
| V30 | VSS | Power/Other | |
| V4 | A15# | Source Sync | Input/Output |
| V5 | A14# | Source Sync | Input/Output |

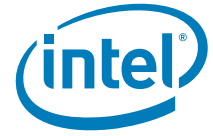


Table 4-2. Land Listing by Land Number (Sheet 19 of 20)

| Pin No. | Pin Name | Signal Buffer Type | Direction |
|---------|----------|--------------------|-----------|
| V6 | VSS | Power/Other | |
| V7 | VSS | Power/Other | |
| V8 | VCC | Power/Other | |
| W1 | MS_ID0 | Power/Other | Output |
| W2 | TESTIN1 | Power/Other | Input |
| W23 | VCC | Power/Other | |
| W24 | VCC | Power/Other | |
| W25 | VCC | Power/Other | |
| W26 | VCC | Power/Other | |



Table 4-2. Land Listing by Land Number (Sheet 20 of 20)

| Pin No. | Pin Name | Signal Buffer Type | Direction |
|---------|----------|--------------------|--------------|
| W27 | VCC | Power/Other | |
| W28 | VCC | Power/Other | |
| W29 | VCC | Power/Other | |
| W3 | TESTHI01 | Power/Other | Input |
| W30 | VCC | Power/Other | |
| W4 | VSS | Power/Other | |
| W5 | A16# | Source Sync | Input/Output |
| W6 | A18# | Source Sync | Input/Output |
| W7 | VSS | Power/Other | |
| W8 | VCC | Power/Other | |
| Y1 | RESERVED | | |
| Y2 | VSS | Power/Other | |
| Y23 | VCC | Power/Other | |
| Y24 | VCC | Power/Other | |
| Y25 | VCC | Power/Other | |
| Y26 | VCC | Power/Other | |
| Y27 | VCC | Power/Other | |
| Y28 | VCC | Power/Other | |
| Y29 | VCC | Power/Other | |
| Y3 | RESERVED | | |
| Y30 | VCC | Power/Other | |
| Y4 | A20# | Source Sync | Input/Output |
| Y5 | VSS | Power/Other | |
| Y6 | A19# | Source Sync | Input/Output |
| Y7 | VSS | Power/Other | |
| Y8 | VCC | Power/Other | |

§



5 Signal Definitions

5.1 Signal Definitions

Table 5-1. Signal Definitions (Sheet 1 of 7)

| Name | Type | Description | Notes | | | | | | | | | | | | |
|--|--------------------|---|-----------------|--------------------|--|------------------------|-----------|---------|----------|------|------|-----------|------|------|-----|
| A[37:3]# | I/O | <p>A[37:3]# (Address) define a 2³⁸-byte physical memory address space. In sub-phase 1 of the address phase, these signals transmit the address of a transaction. In sub-phase 2, these signals transmit transaction type information. These signals must connect the appropriate pins of all agents on the FSB. A[37:3]#⁴ are protected by parity signals AP[1:0]#. A[37:3]#⁴ are source synchronous signals and are latched into the receiving buffers by ADSTB[1:0]#.</p> <p>On the active-to-inactive transition of RESET#, the processors sample a subset of the A[37:3]#⁴ lands to determine their power-on configuration. See Section 7.1.</p> | 3,4 | | | | | | | | | | | | |
| A20M# | I | <p>If A20M# (Address-20 Mask) is asserted, the processor masks physical address bit 20 (A20#) before looking up a line in any internal cache and before driving a read/write transaction on the bus. Asserting A20M# emulates the 8086 processor's address wrap-around at the 1 MB boundary. Assertion of A20M# is only supported in real mode.</p> <p>A20M# is an asynchronous signal. However, to ensure recognition of this signal following an I/O write instruction, it must be valid along with the TRDY# assertion of the corresponding I/O write bus transaction.</p> | 2 | | | | | | | | | | | | |
| ADS# | I/O | <p>ADS# (Address Strobe) is asserted to indicate the validity of the transaction address on the A[37:3]#⁴ lands. All bus agents observe the ADS# activation to begin parity checking, protocol checking, address decode, internal snoop, or deferred reply ID match operations associated with the new transaction. This signal must be connected to the appropriate pins on all Quad-Core Intel® Xeon® Processor 5300 Series FSB agents.</p> | 3 | | | | | | | | | | | | |
| ADSTB[1:0]# | I/O | <p>Address strobes are used to latch A[37:3]#⁴ and REQ[4:0]# on their rising and falling edge. Strobes are associated with signals as shown below.</p> <table border="1" data-bbox="521 1178 1026 1320"> <thead> <tr> <th>Signals</th> <th>Associated Strobes</th> </tr> </thead> <tbody> <tr> <td>REQ[4:0], A[16:3]#, A[37:36]#⁴</td> <td>ADSTB0#</td> </tr> <tr> <td>A[35:17]#</td> <td>ADSTB1#</td> </tr> </tbody> </table> | Signals | Associated Strobes | REQ[4:0], A[16:3]#, A[37:36]# ⁴ | ADSTB0# | A[35:17]# | ADSTB1# | 3,4 | | | | | | |
| Signals | Associated Strobes | | | | | | | | | | | | | | |
| REQ[4:0], A[16:3]#, A[37:36]# ⁴ | ADSTB0# | | | | | | | | | | | | | | |
| A[35:17]# | ADSTB1# | | | | | | | | | | | | | | |
| AP[1:0]# | I/O | <p>AP[1:0]# (Address Parity) are driven by the request initiator along with ADS#, A[37:3]#⁴, and the transaction type on the REQ[4:0]# signals. A correct parity signal is high if an even number of covered signals are low and low if an odd number of covered signals are low. This allows parity to be high when all the covered signals are high. AP[1:0]# must be connected to the appropriate pins of all Quad-Core Intel® Xeon® Processor 5300 Series FSB agents. The following table defines the coverage model of these signals.</p> <table border="1" data-bbox="521 1535 1107 1694"> <thead> <tr> <th>Request Signals</th> <th>Subphase 1</th> <th>Subphase 2</th> </tr> </thead> <tbody> <tr> <td>A[37:24]#⁴</td> <td>AP0#</td> <td>AP1#</td> </tr> <tr> <td>A[23:3]#</td> <td>AP1#</td> <td>AP0#</td> </tr> <tr> <td>REQ[4:0]#</td> <td>AP1#</td> <td>AP0#</td> </tr> </tbody> </table> | Request Signals | Subphase 1 | Subphase 2 | A[37:24]# ⁴ | AP0# | AP1# | A[23:3]# | AP1# | AP0# | REQ[4:0]# | AP1# | AP0# | 3,4 |
| Request Signals | Subphase 1 | Subphase 2 | | | | | | | | | | | | | |
| A[37:24]# ⁴ | AP0# | AP1# | | | | | | | | | | | | | |
| A[23:3]# | AP1# | AP0# | | | | | | | | | | | | | |
| REQ[4:0]# | AP1# | AP0# | | | | | | | | | | | | | |
| BCLK[1:0] | I | <p>The differential bus clock pair BCLK[1:0] (Bus Clock) determines the FSB frequency. All processor FSB agents must receive these signals to drive their outputs and latch their inputs.</p> <p>All external timing parameters are specified with respect to the rising edge of BCLK0 crossing V_{CROSS}.</p> | 3 | | | | | | | | | | | | |



Table 5-1. Signal Definitions (Sheet 2 of 7)

| Name | Type | Description | Notes |
|---|-----------------------------|--|-------|
| BINIT# | I/O | <p>BINIT# (Bus Initialization) may be observed and driven by all processor FSB agents and if used, must connect the appropriate pins of all such agents. If the BINIT# driver is enabled during power on configuration, BINIT# is asserted to signal any bus condition that prevents reliable future operation.</p> <p>If BINIT# observation is enabled during power-on configuration (see Section 7.1) and BINIT# is sampled asserted, symmetric agents reset their bus LOCK# activity and bus request arbitration state machines. The bus agents do not reset their I/O Queue (IOQ) and transaction tracking state machines upon observation of BINIT# assertion. Once the BINIT# assertion has been observed, the bus agents will re-arbitrate for the FSB and attempt completion of their bus queue and IOQ entries.</p> <p>If BINIT# observation is disabled during power-on configuration, a priority agent may handle an assertion of BINIT# as appropriate to the error handling architecture of the system.</p> | 3 |
| BNR# | I/O | <p>BNR# (Block Next Request) is used to assert a bus stall by any bus agent who is unable to accept new bus transactions. During a bus stall, the current bus owner cannot issue any new transactions.</p> <p>Since multiple agents might need to request a bus stall at the same time, BNR# is a wired-OR signal which must connect the appropriate pins of all processor FSB agents. In order to avoid wired-OR glitches associated with simultaneous edge transitions driven by multiple drivers, BNR# is activated on specific clock edges and sampled on specific clock edges.</p> | 3 |
| BPM5# BPM4# BPM3# BPM[2:1]# BPM0# | I/O O I/O O I/O | <p>BPM[5:0]# (Breakpoint Monitor) are breakpoint and performance monitor signals. They are outputs from the processor which indicate the status of breakpoints and programmable counters used for monitoring processor performance. BPM[5:0]# should connect the appropriate pins of all FSB agents.</p> <p>BPM4# provides PRDY# (Probe Ready) functionality for the TAP port. PRDY# is a processor output used by debug tools to determine processor debug readiness.</p> <p>BPM5# provides PREQ# (Probe Request) functionality for the TAP port. PREQ# is used by debug tools to request debug operation of the processors.</p> <p>BPM[5:4]# must be bussed to all bus agents. Please refer to the appropriate platform design guidelines for more detailed information.</p> | 2 |
| BPMb3# BPMb[2:1]# BPMb0# | I/O O I/O | <p>BPMb[3:0]# (Breakpoint Monitor) are a second set of breakpoint and performance monitor signals. They are additional outputs from the processor which indicate the status of breakpoints and programmable counters used for monitoring processor performance. BPMb[3:0]# should connect the appropriate pins of all FSB agents.</p> | 2 |
| BPRI# | I | <p>BPRI# (Bus Priority Request) is used to arbitrate for ownership of the processor FSB. It must connect the appropriate pins of all processor FSB agents. Observing BPRI# active (as asserted by the priority agent) causes all other agents to stop issuing new requests, unless such requests are part of an ongoing locked operation. The priority agent keeps BPRI# asserted until all of its requests are completed, then releases the bus by deasserting BPRI#.</p> | 3 |
| BR[1:0]# | I/O | <p>The BR[1:0]# signals are sampled on the active-to-inactive transition of RESET#. The signal which the agent samples asserted determines its agent ID. BRO# drives the BREQ0# signal in the system and is used by the processor to request the bus. These signals do not have on-die termination and must be terminated.</p> | 3 |
| BSEL[2:0] | O | <p>The BCLK[1:0] frequency select signals BSEL[2:0] are used to select the processor input clock frequency. Table 2-2 defines the possible combinations of the signals and the frequency associated with each combination. The required frequency is determined by the processors, chipset, and clock synthesizer. All FSB agents must operate at the same frequency. For more information about these signals, including termination recommendations, refer to the appropriate platform design guideline.</p> | |
| COMP[3:0] | I | <p>COMP[3:0] must be terminated to VSS on the baseboard using precision resistors. These inputs configure the AGTL+ drivers of the processor. Refer to the appropriate platform design guidelines for implementation details.</p> | |



Table 5-1. Signal Definitions (Sheet 3 of 7)

| Name | Type | Description | Notes | | | | | | | | | | | | | | | |
|------------|-------------------|---|------------|-------------------|-------|----------|-------|-----------|-----------|-----------|-------|-----------|---|---|-----------|---|---|---|
| D[63:0]# | I/O | <p>D[63:0]# (Data) are the data signals. These signals provide a 64-bit data path between the processor FSB agents, and must connect the appropriate pins on all such agents. The data driver asserts DRDY# to indicate a valid data transfer.</p> <p>D[63:0]# are quad-pumped signals, and will thus be driven four times in a common clock period. D[63:0]# are latched off the falling edge of both DSTBP[3:0]# and DSTBN[3:0]#. Each group of 16 data signals correspond to a pair of one DSTBP# and one DSTBN#. The following table shows the grouping of data signals to strobes and DBI#.</p> <table border="1" style="margin-left: auto; margin-right: auto;"> <thead> <tr> <th>Data Group</th> <th>DSTBN#/ DSTBP#</th> <th>DBI #</th> </tr> </thead> <tbody> <tr> <td>D[15:0]#</td> <td>0</td> <td>0</td> </tr> <tr> <td>D[31:16]#</td> <td>1</td> <td>1</td> </tr> <tr> <td>D[47:32]#</td> <td>2</td> <td>2</td> </tr> <tr> <td>D[63:48]#</td> <td>3</td> <td>3</td> </tr> </tbody> </table> <p>Furthermore, the DBI# signals determine the polarity of the data signals. Each group of 16 data signals corresponds to one DBI# signal. When the DBI# signal is active, the corresponding data group is inverted and therefore sampled active high.</p> | Data Group | DSTBN#/ DSTBP# | DBI # | D[15:0]# | 0 | 0 | D[31:16]# | 1 | 1 | D[47:32]# | 2 | 2 | D[63:48]# | 3 | 3 | 3 |
| Data Group | DSTBN#/ DSTBP# | DBI # | | | | | | | | | | | | | | | | |
| D[15:0]# | 0 | 0 | | | | | | | | | | | | | | | | |
| D[31:16]# | 1 | 1 | | | | | | | | | | | | | | | | |
| D[47:32]# | 2 | 2 | | | | | | | | | | | | | | | | |
| D[63:48]# | 3 | 3 | | | | | | | | | | | | | | | | |
| DBI[3:0]# | I/O | <p>DBI[3:0]# (Data Bus Inversion) are source synchronous and indicate the polarity of the D[63:0]# signals. The DBI[3:0]# signals are activated when the data on the data bus is inverted. If more than half the data bits, within, within a 16-bit group, would have been asserted electronically low, the bus agent may invert the data bus signals for that particular sub-phase for that 16-bit group.</p> <p>DBI [3:0] Assignment to Data Bus</p> <table border="1" style="margin-left: auto; margin-right: auto;"> <thead> <tr> <th>Bus Signal</th> <th>Data Bus Signals</th> </tr> </thead> <tbody> <tr> <td>DBI0#</td> <td>D[15:0]#</td> </tr> <tr> <td>DBI1#</td> <td>D[31:16]#</td> </tr> <tr> <td>DBI2#</td> <td>D[47:32]#</td> </tr> <tr> <td>DBI3#</td> <td>D[63:48]#</td> </tr> </tbody> </table> | Bus Signal | Data Bus Signals | DBI0# | D[15:0]# | DBI1# | D[31:16]# | DBI2# | D[47:32]# | DBI3# | D[63:48]# | 3 | | | | | |
| Bus Signal | Data Bus Signals | | | | | | | | | | | | | | | | | |
| DBI0# | D[15:0]# | | | | | | | | | | | | | | | | | |
| DBI1# | D[31:16]# | | | | | | | | | | | | | | | | | |
| DBI2# | D[47:32]# | | | | | | | | | | | | | | | | | |
| DBI3# | D[63:48]# | | | | | | | | | | | | | | | | | |
| DBR# | O | <p>DBR# is used only in systems where no debug port connector is implemented on the system board. DBR# is used by a debug port interposer so that an in-target probe can drive reset. If a debug port connector is implemented in the system, DBR# is a no-connect on the Quad-Core Intel® Xeon® Processor 5300 Series package. DBR# is not a processor signal.</p> | | | | | | | | | | | | | | | | |
| DBSY# | I/O | <p>DBSY# (Data Bus Busy) is asserted by the agent responsible for driving data on the processor FSB to indicate that the data bus is in use. The data bus is released after DBSY# is deasserted. This signal must connect the appropriate pins on all processor FSB agents.</p> | 3 | | | | | | | | | | | | | | | |
| DEFER# | I | <p>DEFER# is asserted by an agent to indicate that a transaction cannot be guaranteed in-order completion. Assertion of DEFER# is normally the responsibility of the addressed memory or I/O agent. This signal must connect the appropriate pins of all processor FSB agents.</p> | 3 | | | | | | | | | | | | | | | |
| DP[3:0]# | I/O | <p>DP[3:0]# (Data Parity) provide parity protection for the D[63:0]# signals. They are driven by the agent responsible for driving D[63:0]#, and must connect the appropriate pins of all processor FSB agents.</p> | 3 | | | | | | | | | | | | | | | |
| DRDY# | I/O | <p>DRDY# (Data Ready) is asserted by the data driver on each data transfer, indicating valid data on the data bus. In a multi-common clock data transfer, DRDY# may be deasserted to insert idle clocks. This signal must connect the appropriate pins of all processor FSB agents.</p> | 3 | | | | | | | | | | | | | | | |



Table 5-1. Signal Definitions (Sheet 4 of 7)

| Name | Type | Description | Notes | | | | | | | | | | |
|------------------------------------|--------------------|---|---------|--------------------|-----------------|---------|------------------|---------|------------------|---------|------------------|---------|---|
| DSTBN[3:0]# | I/O | Data strobe used to latch in D[63:0]#. <table border="1" data-bbox="506 390 943 585"> <thead> <tr> <th>Signals</th> <th>Associated Strobes</th> </tr> </thead> <tbody> <tr> <td>D[15:0]#, DBI0#</td> <td>DSTBN0#</td> </tr> <tr> <td>D[31:16]#, DBI1#</td> <td>DSTBN1#</td> </tr> <tr> <td>D[47:32]#, DBI2#</td> <td>DSTBN2#</td> </tr> <tr> <td>D[63:48]#, DBI3#</td> <td>DSTBN3#</td> </tr> </tbody> </table> | Signals | Associated Strobes | D[15:0]#, DBI0# | DSTBN0# | D[31:16]#, DBI1# | DSTBN1# | D[47:32]#, DBI2# | DSTBN2# | D[63:48]#, DBI3# | DSTBN3# | 3 |
| Signals | Associated Strobes | | | | | | | | | | | | |
| D[15:0]#, DBI0# | DSTBN0# | | | | | | | | | | | | |
| D[31:16]#, DBI1# | DSTBN1# | | | | | | | | | | | | |
| D[47:32]#, DBI2# | DSTBN2# | | | | | | | | | | | | |
| D[63:48]#, DBI3# | DSTBN3# | | | | | | | | | | | | |
| DSTBP[3:0]# | I/O | Data strobe used to latch in D[63:0]#. <table border="1" data-bbox="506 669 943 865"> <thead> <tr> <th>Signals</th> <th>Associated Strobes</th> </tr> </thead> <tbody> <tr> <td>D[15:0]#, DBI0#</td> <td>DSTBP0#</td> </tr> <tr> <td>D[31:16]#, DBI1#</td> <td>DSTBP1#</td> </tr> <tr> <td>D[47:32]#, DBI2#</td> <td>DSTBP2#</td> </tr> <tr> <td>D[63:48]#, DBI3#</td> <td>DSTBP3#</td> </tr> </tbody> </table> | Signals | Associated Strobes | D[15:0]#, DBI0# | DSTBP0# | D[31:16]#, DBI1# | DSTBP1# | D[47:32]#, DBI2# | DSTBP2# | D[63:48]#, DBI3# | DSTBP3# | 3 |
| Signals | Associated Strobes | | | | | | | | | | | | |
| D[15:0]#, DBI0# | DSTBP0# | | | | | | | | | | | | |
| D[31:16]#, DBI1# | DSTBP1# | | | | | | | | | | | | |
| D[47:32]#, DBI2# | DSTBP2# | | | | | | | | | | | | |
| D[63:48]#, DBI3# | DSTBP3# | | | | | | | | | | | | |
| FERR#/PBE# | O | FERR#/PBE# (floating-point error/pending break event) is a multiplexed signal and its meaning is qualified by STPCLK#. When STPCLK# is not asserted, FERR#/PBE# indicates a floating-point error and will be asserted when the processor detects an unmasked floating-point error. When STPCLK# is not asserted, FERR#/PBE# is similar to the ERROR# signal on the Intel 387 coprocessor, and is included for compatibility with systems using MS-DOS*-type floating-point error reporting. When STPCLK# is asserted, an assertion of FERR#/PBE# indicates that the processor has a pending break event waiting for service. The assertion of FERR#/PBE# indicates that the processor should be returned to the Normal state. For additional information on the pending break event functionality, including the identification of support of the feature and enable/disable information, refer to Vol. 3 of the <i>Intel® 64 and IA-32 Intel® Architecture Software Developer's Manual</i> and the <i>AP-485 Intel® Processor Identification and the CPUID Instruction</i> application note. | 2 | | | | | | | | | | |
| FORCEPR# | I | The FORCEPR# (force power reduction) input can be used by the platform to cause the Quad-Core Intel® Xeon® Processor 5300 Series to activate the Thermal Control Circuit (TCC). | | | | | | | | | | | |
| GTLREF_ADD_MID GTLREF_ADD_END | I | GTLREF_ADD determines the signal reference level for AGTL+ address and common clock input lands. GTLREF_ADD is used by the AGTL+ receivers to determine if a signal is a logical 0 or a logical 1. Please refer to Table 2-18 and the appropriate platform design guidelines for additional details. | | | | | | | | | | | |
| GTLREF_DATA_MID GTLREF_DATA_END | I | GTLREF_DATA determines the signal reference level for AGTL+ data input lands. GTLREF_DATA is used by the AGTL+ receivers to determine if a signal is a logical 0 or a logical 1. Please refer to Table 2-18 and the appropriate platform design guidelines for additional details. | | | | | | | | | | | |
| HIT# HITM# | I/O I/O | HIT# (Snoop Hit) and HITM# (Hit Modified) convey transaction snoop operation results. Any FSB agent may assert both HIT# and HITM# together to indicate that it requires a snoop stall, which can be continued by reasserting HIT# and HITM# together. | 3 | | | | | | | | | | |
| IERR# | O | IERR# (Internal Error) is asserted by a processor as the result of an internal error. Assertion of IERR# is usually accompanied by a SHUTDOWN transaction on the processor FSB. This transaction may optionally be converted to an external error signal (e.g., NMI) by system core logic. The processor will keep IERR# asserted until the assertion of RESET#. This signal does not have on-die termination. | 2 | | | | | | | | | | |



Table 5-1. Signal Definitions (Sheet 5 of 7)

| Name | Type | Description | Notes |
|------------|------|---|-------|
| IGNNE# | I | IGNNE# (Ignore Numeric Error) is asserted to force the processor to ignore a numeric error and continue to execute noncontrol floating-point instructions. If IGNNE# is deasserted, the processor generates an exception on a noncontrol floating-point instruction if a previous floating-point instruction caused an error. IGNNE# has no effect when the NE bit in control register 0 (CRO) is set. IGNNE# is an asynchronous signal. However, to ensure recognition of this signal following an I/O write instruction, it must be valid along with the TRDY# assertion of the corresponding I/O write bus transaction. | 2 |
| INIT# | I | INIT# (Initialization), when asserted, resets integer registers inside all processors without affecting their internal caches or floating-point registers. Each processor then begins execution at the power-on Reset vector configured during power-on configuration. The processor continues to handle snoop requests during INIT# assertion. INIT# is an asynchronous signal and must connect the appropriate pins of all processor FSB agents. | 2 |
| LINT[1:0] | I | LINT[1:0] (Local APIC Interrupt) must connect the appropriate pins of all FSB agents. When the APIC functionality is disabled, the LINT0/INTR signal becomes INTR, a maskable interrupt request signal, and LINT1/NMI becomes NMI, a nonmaskable interrupt. INTR and NMI are backward compatible with the signals of those names on the Pentium® processor. Both signals are asynchronous. These signals must be software configured via BIOS programming of the APIC register space to be used either as NMI/INTR or LINT[1:0]. Because the APIC is enabled by default after Reset, operation of these pins as LINT[1:0] is the default configuration. | 2 |
| LL_ID[1:0] | O | The LL_ID[1:0] signals are used to select the correct loadline slope for the processor. These signals are not connected to the processor die. A logic 0 is pulled to ground and a logic 1 is a no-connect on the Quad-Core Intel® Xeon® Processor 5300 Series package. | |
| LOCK# | I/O | LOCK# indicates to the system that a transaction must occur atomically. This signal must connect the appropriate pins of all processor FSB agents. For a locked sequence of transactions, LOCK# is asserted from the beginning of the first transaction to the end of the last transaction. When the priority agent asserts BPRI# to arbitrate for ownership of the processor FSB, it will wait until it observes LOCK# deasserted. This enables symmetric agents to retain ownership of the processor FSB throughout the bus locked operation and ensure the atomicity of lock. | 3 |
| MCERR# | I/O | MCERR# (Machine Check Error) is asserted to indicate an unrecoverable error without a bus protocol violation. It may be driven by all processor FSB agents. MCERR# assertion conditions are configurable at a system level. Assertion options are defined by the following options: <ul style="list-style-type: none"> • Enabled or disabled. • Asserted, if configured, for internal errors along with IERR#. • Asserted, if configured, by the request initiator of a bus transaction after it observes an error. • Asserted by any bus agent when it observes an error in a bus transaction. For more details regarding machine check architecture, refer to the <i>Intel® 64 and IA-32 Intel® Architecture Software Developer's Manual, Volume 3: System Programming Guide</i> . | |
| MS_ID[1:0] | O | These signals are provided to indicate the Market Segment for the processor and may be used for future processor compatibility or for keying. These signals are not connected to the processor die. A logic 0 is pulled to ground and a logic 1 is a no-connect on the Quad-Core Intel® Xeon® Processor 5300 Series package. | |
| PECI | I/O | PECI is a proprietary one-wire bus interface that provides a communication channel between Intel processor and chipset components to external thermal monitoring devices. See Section 6.3, "Platform Environment Control Interface (PECI)" for more on the Peci interface. | |
| PROCHOT# | O | PROCHOT# (Processor Hot) will go active when the processor's temperature monitoring sensor detects that the processor has reached its maximum safe operating temperature. This indicates that the Thermal Control Circuit (TCC) has been activated, if enabled. The TCC will remain active until shortly after the processor deasserts PROCHOT#. See Section 6.2.5 for more details. | |



Table 5-1. Signal Definitions (Sheet 6 of 7)

| Name | Type | Description | Notes |
|-------------------------------|------|---|-------|
| PWRGOOD | I | <p>PWRGOOD (Power Good) is an input. The processor requires this signal to be a clean indication that all processor clocks and power supplies are stable and within their specifications. "Clean" implies that the signal will remain low (capable of sinking leakage current), without glitches, from the time that the power supplies are turned on until they come within specification. The signal must then transition monotonically to a high state. PWRGOOD can be driven inactive at any time, but clocks and power must again be stable before a subsequent rising edge of PWRGOOD. It must also meet the minimum pulse width specification in Table 2-17, and be followed by a 1-10 ms RESET# pulse.</p> <p>The PWRGOOD signal must be supplied to the processor; it is used to protect internal circuits against voltage sequencing issues. It should be driven high throughout boundary scan operation.</p> | 2 |
| REQ[4:0]# | I/O | <p>REQ[4:0]# (Request Command) must connect the appropriate pins of all processor FSB agents. They are asserted by the current bus owner to define the currently active transaction type. These signals are source synchronous to ADSTB[1:0]#. Refer to the AP[1:0]# signal description for details on parity checking of these signals.</p> | 3 |
| RESET# | I | <p>Asserting the RESET# signal resets all processors to known states and invalidates their internal caches without writing back any of their contents. For a power-on Reset, RESET# must stay active for at least 1 ms after VCC and BCLK have reached their proper specifications. On observing active RESET#, all FSB agents will deassert their outputs within two clocks. RESET# must not be kept asserted for more than 10 ms while PWRGOOD is asserted.</p> <p>A number of bus signals are sampled at the active-to-inactive transition of RESET# for power-on configuration. These configuration options are described in the Section 7.1.</p> <p>This signal does not have on-die termination and must be terminated on the system board.</p> | 3 |
| RS[2:0]# | I | <p>RS[2:0]# (Response Status) are driven by the response agent (the agent responsible for completion of the current transaction), and must connect the appropriate pins of all processor FSB agents.</p> | 3 |
| RSP# | I | <p>RSP# (Response Parity) is driven by the response agent (the agent responsible for completion of the current transaction) during assertion of RS[2:0]#, the signals for which RSP# provides parity protection. It must connect to the appropriate pins of all processor FSB agents.</p> <p>A correct parity signal is high if an even number of covered signals are low and low if an odd number of covered signals are low. While RS[2:0]# = 000, RSP# is also high, since this indicates it is not being driven by any agent guaranteeing correct parity.</p> | 3 |
| SKTOCC# | O | <p>SKTOCC# (Socket occupied) will be pulled to ground by the processor to indicate that the processor is present. There is no connection to the processor silicon for this signal.</p> | |
| SMI# | I | <p>SMI# (System Management Interrupt) is asserted asynchronously by system logic. On accepting a System Management Interrupt, processors save the current state and enter System Management Mode (SMM). An SMI Acknowledge transaction is issued, and the processor begins program execution from the SMM handler.</p> <p>If SMI# is asserted during the deassertion of RESET# the processor will tri-state its outputs. See Section 7.1.</p> | 2 |
| STPCLK# | I | <p>STPCLK# (Stop Clock), when asserted, causes processors to enter a low power Stop-Grant state. The processor issues a Stop-Grant Acknowledge transaction, and stops providing internal clock signals to all processor core units except the FSB and APIC units. The processor continues to snoop bus transactions and service interrupts while in Stop-Grant state. When STPCLK# is deasserted, the processor restarts its internal clock to all units and resumes execution. The assertion of STPCLK# has no effect on the bus clock; STPCLK# is an asynchronous input.</p> | 2 |
| TCK | I | <p>TCK (Test Clock) provides the clock input for the processor Test Bus (also known as the Test Access Port).</p> | |
| TDI | I | <p>TDI (Test Data In) transfers serial test data into the processor. TDI provides the serial input needed for JTAG specification support.</p> | |
| TDO | O | <p>TDO (Test Data Out) transfers serial test data out of the processor. TDO provides the serial output needed for JTAG specification support.</p> | |
| TESTHI[11:10] TESTHI[7:0], | I | <p>TESTHI[11:10] and TESTHI[7:0], must be connected to a V_{TT} power source through a resistor for proper processor operation. Refer to Section 2.6 for TESTHI grouping restrictions.</p> | |



Table 5-1. Signal Definitions (Sheet 7 of 7)

| Name | Type | Description | Notes |
|---------------------------------|--------|--|-------|
| TESTIN1 TESTIN2 | I I | TESTIN1 must be connected to a VTT power source through a resistor as well as to the TESTIN2 land of the same socket for proper processor operation. TESTIN2 must be connected to a VTT power source through a resistor as well as to the TESTIN1 land of the same socket for proper processor operation. Refer to Section 2.6 for TESTIN restrictions. | |
| THERMTRIP# | O | Assertion of THERMTRIP# (Thermal Trip) indicates the processor junction temperature has reached a temperature beyond which permanent silicon damage may occur. Measurement of the temperature is accomplished through an internal thermal sensor. Upon assertion of THERMTRIP#, the processor will shut off its internal clocks (thus halting program execution) in an attempt to reduce the processor junction temperature. To protect the processor its core voltage (V _{CC}) must be removed following the assertion of THERMTRIP#. Intel also recommends the removal of V _{TT} when THERMTRIP# is asserted. Driving of the THERMTRIP# signals is enabled within 10 μs of the assertion of PWRGOOD and is disabled on de-assertion of PWRGOOD. Once activated, THERMTRIP# remains latched until PWRGOOD is de-asserted. While the de-assertion of the PWRGOOD signal will de-assert THERMTRIP#, if the processor's junction temperature remains at or above the trip level, THERMTRIP# will again be asserted within 10 μs of the assertion of PWRGOOD. | 1 |
| TMS | I | TMS (Test Mode Select) is a JTAG specification support signal used by debug tools. See the <i>Debug Port Design Guide for Blackford and Greencreek Systems (External Version)</i> for further information. | |
| TRDY# | I | TRDY# (Target Ready) is asserted by the target to indicate that it is ready to receive a write or implicit writeback data transfer. TRDY# must connect the appropriate pins of all FSB agents. | |
| TRST# | I | TRST# (Test Reset) resets the Test Access Port (TAP) logic. TRST# must be driven low during power on Reset. | |
| V _{CCPLL} | I | The Quad-Core Intel® Xeon® Processor 5300 Series implement an on-die PLL filter solution. The V _{CCPLL} input is used as a PLL supply voltage. | |
| VCC_DIE_SENSE VCC_DIE_SENSE2 | O | VCC_DIE_SENSE and VCC_DIE_SENSE2 provides an isolated, low impedance connection to the processor core power and ground. This signal should be connected to the voltage regulator feedback signal, which insures the output voltage (that is, processor voltage) remains within specification. Please see the applicable platform design guide for implementation details. | |
| VID[6:1] | O | VID[6:1] (Voltage ID) pins are used to support automatic selection of power supply voltages (V _{CC}). These are CMOS signals that are driven by the processor and must be pulled up through a resistor. Conversely, the voltage regulator output must be disabled prior to the voltage supply for these pins becomes invalid. The VID pins are needed to support processor voltage specification variations. See Table 2-3 for definitions of these pins. The VR must supply the voltage that is requested by these pins, or disable itself. | |
| VID_SELECT | O | VID_SELECT is an output from the processor which selects the appropriate VID table for the Voltage Regulator. This signal is not connected to the processor die. This signal is a no-connect on the Quad-Core Intel® Xeon® Processor 5300 Series package. | |
| VSS_DIE_SENSE VSS_DIE_SENSE2 | O | VSS_DIE_SENSE and VSS_DIE_SENSE2 provides an isolated, low impedance connection to the processor core power and ground. This signal should be connected to the voltage regulator feedback signal, which insures the output voltage (that is, processor voltage) remains within specification. Please see the applicable platform design guide for implementation details. | |
| VTT | P | The FSB termination voltage input pins. Refer to Table 2-12 for further details. | |
| VTT_OUT | O | The VTT_OUT signals are included in order to provide a local V _{TT} for some signals that require termination to V _{TT} on the motherboard. | |
| VTT_SEL | O | The VTT_SEL signal is used to select the correct V _{TT} voltage level for the processor. VTT_SEL is a no-connect on the Quad-Core Intel® Xeon® Processor 5300 Series package. | |

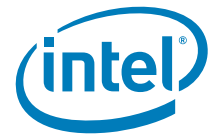
Notes:

- For this processor land on the Quad-Core Intel® Xeon® Processor 5300 Series, the maximum number of symmetric agents is one. Maximum number of priority agents is zero.
- For this processor land on the Quad-Core Intel® Xeon® Processor 5300 Series, the maximum number of symmetric agents is two. Maximum number of priority agents is zero.
- For this processor land on the Quad-Core Intel® Xeon® Processor 5300 Series, the maximum number of symmetric agents is two. Maximum number of priority agents is one.



4. Not all Quad-Core Intel® Xeon® Processor 5300 Series support signals A[37:36]#. Processors that support these signals will be outlined in the *Quad-Core Intel® Xeon® Processor 5300 Series NDA Specification Update*.

§



6 Thermal Specifications

6.1 Package Thermal Specifications

The Quad-Core Intel® Xeon® Processor 5300 Series requires a thermal solution to maintain temperatures within its operating limits. Any attempt to operate the processor outside these operating limits may result in permanent damage to the processor and potentially other components within the system. As processor technology changes, thermal management becomes increasingly crucial when building computer systems. Maintaining the proper thermal environment is key to reliable, long-term system operation.

A complete solution includes both component and system level thermal management features. Component level thermal solutions can include active or passive heatsinks attached to the processor integrated heat spreader (IHS). Typical system level thermal solutions may consist of system fans combined with ducting and venting.

This section provides data necessary for developing a complete thermal solution. For more information on designing a component level thermal solution, refer to the *Clovertown Processor Thermal/Mechanical Design Guidelines*.

Note: The boxed processor will ship with a component thermal solution. Refer to [Section 8](#) for details on the boxed processor.

6.1.1 Thermal Specifications

To allow the optimal operation and long-term reliability of Intel processor-based systems, the processor must remain within the minimum and maximum case temperature (T_{CASE}) specifications as defined by the applicable thermal profile (see [Table 6-1](#) and [Figure 6-1](#) for Quad-Core Intel® Xeon® Processor E5300 Series, [Table 6-3](#) and [Figure 6-2](#) for Quad-Core Intel® Xeon® Processor X5300 Series, and [Table 6-6](#) and [Figure 6-3](#) for Quad-Core Intel® Xeon® Processor L5300 Series). Thermal solutions not designed to provide this level of thermal capability may affect the long-term reliability of the processor and system. For more details on thermal solution design, please refer to the *Clovertown Processor Thermal/Mechanical Design Guidelines*.

The Quad-Core Intel® Xeon® Processor 5300 Series implement a methodology for managing processor temperatures which is intended to support acoustic noise reduction through fan speed control and to assure processor reliability. Selection of the appropriate fan speed is based on the relative temperature data reported by the processor's Platform Environment Control Interface (PECI) bus as described in [Section 6.3](#). The temperature reported over Peci is always a negative value and represents a delta below the onset of thermal control circuit (TCC) activation, as indicated by PROCHOT# (see [Section 6.2](#), Processor Thermal Features). Systems that implement fan speed control must be designed to use this data. Systems that do not alter the fan speed only need to guarantee the case temperature meets the thermal profile specifications.

The Quad-Core Intel® Xeon® Processor E5300 Series (see [Figure 6-1](#); [Table 6-2](#)) and Quad-Core Intel® Xeon® Processor L5300 Series (see [Figure 6-3](#); [Table 6-7](#)) support a single Thermal Profile. For these processors, it is expected that the Thermal Control Circuit (TCC) would only be activated for very brief periods of time when running the



most power-intensive applications. Refer to the *Clovertown Processor Thermal/Mechanical Design Guidelines* for details on system thermal solution design, thermal profiles and environmental considerations.

For the Quad-Core Intel® Xeon® Processor X5300 Series, Intel has developed two thermal profiles, either of which can be implemented. Both ensure adherence to Intel reliability requirements. Thermal Profile A (see [Figure 6-2](#); [Table 6-4](#)) is representative of a volumetrically unconstrained thermal solution (that is, industry enabled 2U heatsink). In this scenario, it is expected that the Thermal Control Circuit (TCC) would only be activated for very brief periods of time when running the most power intensive applications. Thermal Profile B (see [Figure 6-2](#); [Table 6-5](#)) is indicative of a constrained thermal environment (that is, 1U form factor). Because of the reduced cooling capability represented by this thermal solution, the probability of TCC activation and performance loss is increased. Additionally, utilization of a thermal solution that does not meet Thermal Profile B will violate the thermal specifications and may result in permanent damage to the processor. Refer to the *Clovertown Processor Thermal/Mechanical Design Guidelines* for details on system thermal solution design, thermal profiles and environmental considerations.

The upper point of the thermal profile consists of the Thermal Design Power (TDP) and the associated T_{CASE} value. It should be noted that the upper point associated with the Quad-Core Intel® Xeon® Processor X5300 Series Thermal Profile B ($x = TDP$ and $y = T_{CASE_MAX_B} @ TDP$) represents a thermal solution design point. In actuality the processor case temperature will not reach this value due to TCC activation (see [Figure 6-2](#) for Quad-Core Intel® Xeon® Processor X5300 Series). The lower point of the thermal profile consists of $x = P_{PROFILE_MIN}$ and $y = T_{CASE_MAX} @ P_{PROFILE_MIN}$. $P_{PROFILE_MIN}$ is defined as the processor power at which T_{CASE} , calculated from the thermal profile, is equal to 50°C.

Analysis indicates that real applications are unlikely to cause the processor to consume maximum power dissipation for sustained time periods. Intel recommends that complete thermal solution designs target the Thermal Design Power (TDP), instead of the maximum processor power consumption. The Thermal Monitor feature is intended to help protect the processor in the event that an application exceeds the TDP recommendation for a sustained time period. For more details on this feature, refer to [Section 6.2](#). To ensure maximum flexibility for future requirements, systems should be designed to the Flexible Motherboard (FMB) guidelines, even if a processor with lower power dissipation is currently planned. **Thermal Monitor 1 and Thermal Monitor 2 feature must be enabled for the processor to remain within its specifications.**

Table 6-1. Quad-Core Intel® Xeon® Processor E5300 Series Thermal Specifications

| Core Frequency | Maximum Power (W) | Thermal Design Power (W) | Minimum T_{CASE} (°C) | Maximum T_{CASE} (°C) | Notes |
|----------------|-------------------|--------------------------|-------------------------|--|------------------|
| Launch to FMB | 100 | 80 | 5 | See Figure 6-1 ; Table 6-2 | 1, 2, 3, 4, 5, 6 |

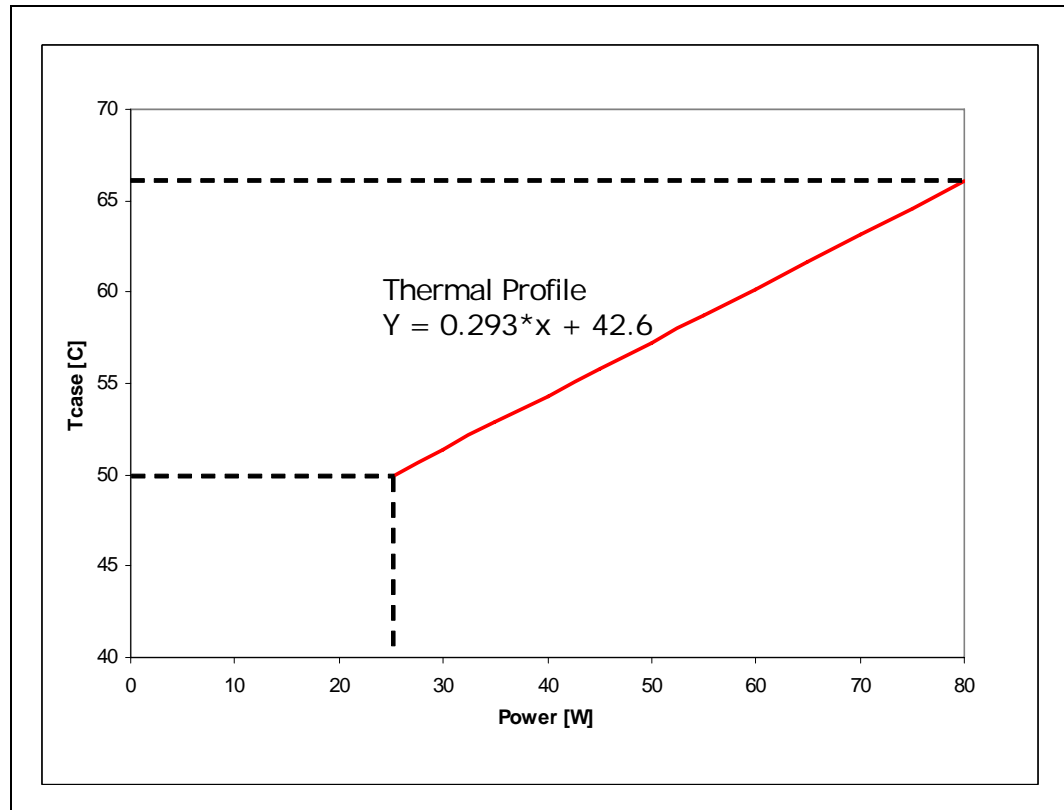
Notes:

- These values are specified at V_{CC_MAX} for all processor frequencies. Systems must be designed to ensure the processor is not to be subjected to any static V_{CC} and I_{CC} combination wherein V_{CC} exceeds V_{CC_MAX} at specified I_{CC} . Please refer to the loadline specifications in [Section 2](#).
- Maximum Power is the highest power the processor will dissipate, regardless of its VID. Maximum Power is measured at maximum T_{CASE} .
- Thermal Design Power (TDP) should be used for processor thermal solution design targets. TDP is not the maximum power that the processor can dissipate. TDP is measured at maximum T_{CASE} .
- These specifications are based on initial silicon characterization. These specifications may be further updated as more characterization data becomes available.
- Power specifications are defined at all VIDs found in [Table 2-3](#). The Quad-Core Intel® Xeon® Processor E5300 Series may be shipped under multiple VIDs for each frequency.



- FMB, or Flexible Motherboard, guidelines provide a design target for meeting all planned processor frequency requirements.

Figure 6-1. Quad-Core Intel® Xeon® Processor E5300 Series Thermal Profile



Notes:

- Please refer to [Table 6-2](#) for discrete points that constitute the thermal profile.
- Refer to the *Clovertown Processor Thermal/Mechanical Design Guidelines* for system and environmental implementation details.

Table 6-2. Quad-Core Intel® Xeon® Processor E5300 Series Thermal Profile Table

| Power (W) | T _{CASE_MAX} (°C) |
|--------------------------------|----------------------------|
| P _{PROFILE_MIN} =25.3 | 50.0 |
| 30 | 51.4 |
| 35 | 52.9 |
| 40 | 54.3 |
| 45 | 55.8 |
| 50 | 57.3 |
| 55 | 58.7 |
| 60 | 60.2 |
| 65 | 61.6 |
| 70 | 63.1 |
| 75 | 64.6 |
| 80 | 66.0 |



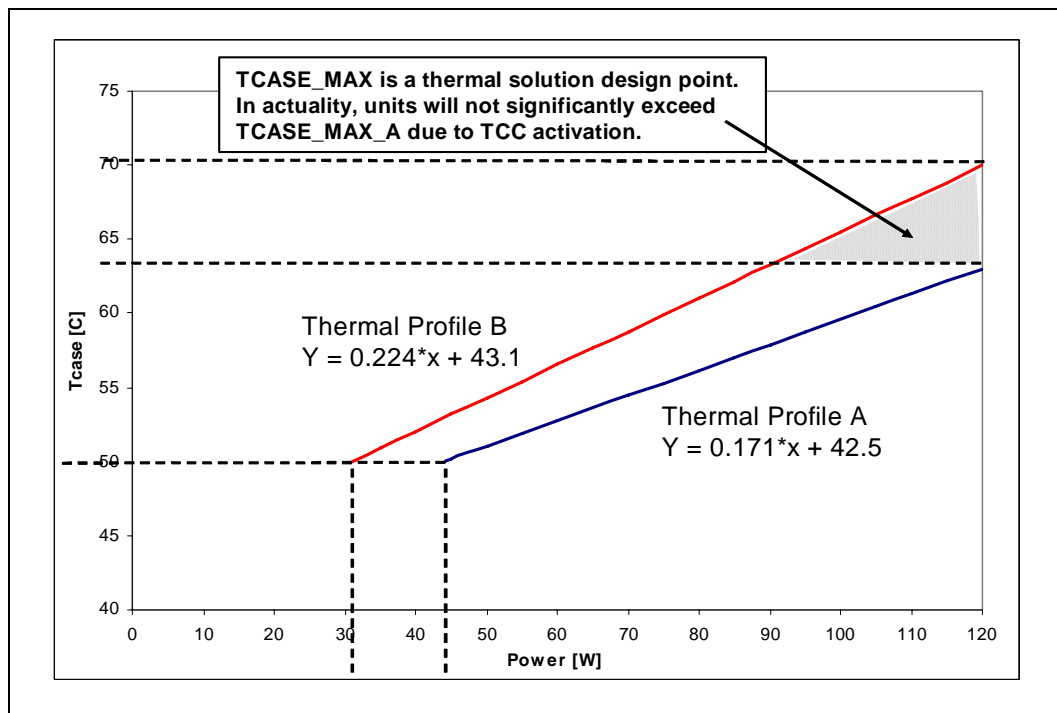
Table 6-3. Quad-Core Intel® Xeon® Processor X5300 Series Thermal Specifications

| Core Frequency | Maximum Power (W) | Thermal Design Power (W) | Minimum TCASE (°C) | Maximum TCASE (°C) | Notes |
|----------------|-------------------|--------------------------|--------------------|--|------------------|
| Launch to FMB | 145 | 120 | 5 | See Figure 6-2; Table 6-4; Table 6-5 | 1, 2, 3, 4, 5, 6 |

Notes:

1. These values are specified at V_{CC_MAX} for all processor frequencies. Systems must be designed to ensure the processor is not to be subjected to any static V_{CC} and I_{CC} combination wherein V_{CC} exceeds V_{CC_MAX} at specified I_{CC} . Please refer to the loadline specifications in Section 2.
2. Maximum Power is the highest power the processor will dissipate, regardless of its VID. Maximum Power is measured at maximum T_{CASE} .
3. Thermal Design Power (TDP) should be used for processor thermal solution design targets. TDP is not the maximum power that the processor can dissipate. TDP is measured at maximum T_{CASE} .
4. These specifications are based on initial silicon characterization. These specifications may be further updated as more characterization data becomes available.
5. Power specifications are defined at all VIDs found in Table 2-3. The Quad-Core Intel® Xeon® Processor X5300 Series may be shipped under multiple VIDs for each frequency.
6. FMB, or Flexible Motherboard, guidelines provide a design target for meeting all planned processor frequency requirements.

Figure 6-2. Quad-Core Intel® Xeon® Processor X5300 Series Thermal Profiles



Notes:

1. Quad-Core Intel® Xeon® Processor X5300 Series Thermal Profile A is representative of a volumetrically unconstrained platform. Please refer to Table 6-4 for discrete points that constitute the thermal profile.
2. Implementation of Quad-Core Intel® Xeon® Processor X5300 Series Thermal Profile A should result in virtually no TCC activation. Furthermore, utilization of thermal solutions that do not meet processor Quad-Core Intel® Xeon® Processor X5300 Series Thermal Profile A will result in increased probability of TCC activation and may incur measurable performance loss. (See Section 6.2 for details on TCC activation).
3. Quad-Core Intel® Xeon® Processor X5300 Series Thermal Profile B is representative of a volumetrically constrained platform. Please refer to Table 6-5 for discrete points that constitute the thermal profile.
4. Implementation of Thermal Profile B will result in increased probability of TCC activation and measurable performance loss. Furthermore, utilization of thermal solutions that do not meet Thermal Profile B do not meet the processor's thermal specifications and may result in permanent damage to the processor.
5. Refer to the *Clovertown Processor Thermal/Mechanical Design Guidelines* for system and environmental implementation details.



Table 6-4. Quad-Core Intel® Xeon® Processor X5300 Series Thermal Profile A Table

| Power (W) | T _{CASE_MAX} (°C) |
|----------------------|----------------------------|
| P_PROFILE_MIN_A=43.9 | 50.0 |
| 45 | 50.2 |
| 50 | 51.1 |
| 55 | 51.9 |
| 60 | 52.8 |
| 65 | 53.6 |
| 70 | 54.5 |
| 75 | 55.3 |
| 80 | 56.2 |
| 85 | 57.0 |
| 90 | 57.9 |
| 95 | 58.7 |
| 100 | 59.6 |
| 105 | 60.5 |
| 110 | 61.3 |
| 115 | 62.2 |
| 120 | 63.0 |

Table 6-5. Quad-Core Intel® Xeon® Processor X5300 Series Thermal Profile B Table

| Power (W) | T _{CASE_MAX} (°C) |
|----------------------|----------------------------|
| P_PROFILE_MIN_B=30.8 | 50.0 |
| 35 | 50.9 |
| 40 | 52.1 |
| 45 | 53.2 |
| 50 | 54.3 |
| 55 | 55.4 |
| 60 | 56.5 |
| 65 | 57.7 |
| 70 | 58.8 |
| 75 | 59.9 |
| 80 | 61.0 |
| 85 | 62.1 |
| 90 | 63.3 |
| 95 | 64.4 |
| 100 | 65.5 |
| 105 | 66.6 |
| 110 | 67.7 |
| 115 | 68.9 |
| 120 | 70.0 |



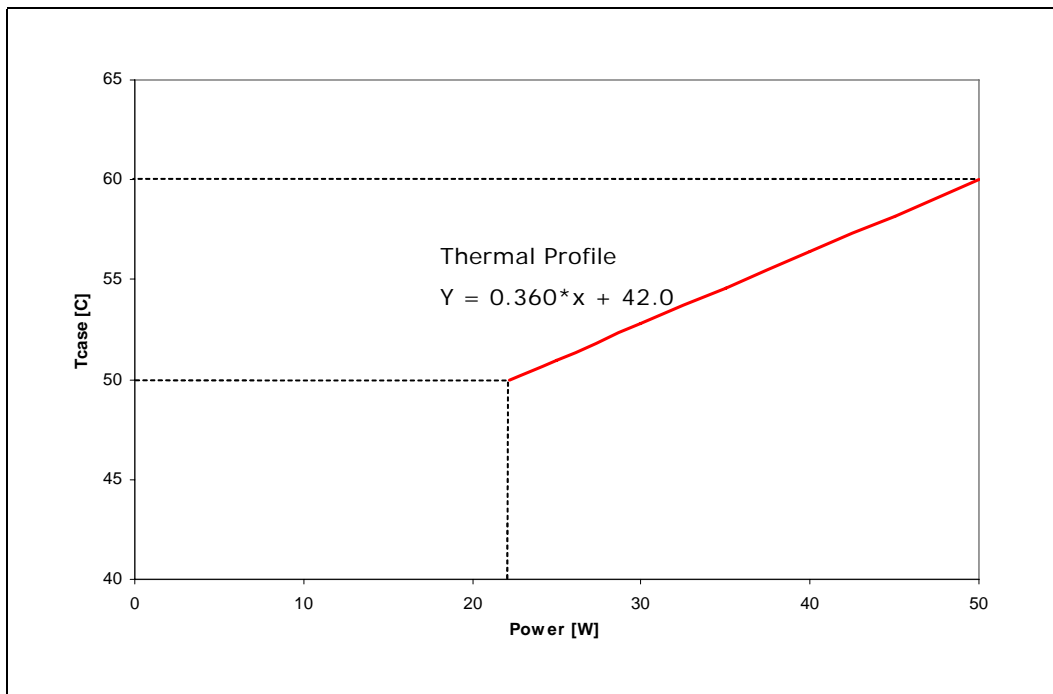
Table 6-6. Quad-Core Intel® Xeon® Processor L5300 Series Thermal Specifications

| Core Frequency | Maximum Power (W) | Thermal Design Power (W) | Minimum TCASE (°C) | Maximum TCASE (°C) | Notes |
|----------------|-------------------|--------------------------|--------------------|---------------------------|------------------|
| Launch to FMB | 65 | 50 | 5 | See Figure 6-3; Table 6-7 | 1, 2, 3, 4, 5, 6 |

Notes:

1. These values are specified at V_{CC_MAX} for all processor frequencies. Systems must be designed to ensure the processor is not to be subjected to any static V_{CC} and I_{CC} combination wherein V_{CC} exceeds V_{CC_MAX} at specified I_{CC} . Please refer to the loadline specifications in Section 2.
2. Maximum Power is the highest power the processor will dissipate, regardless of its VID. Maximum Power is measured at maximum T_{CASE} .
3. Thermal Design Power (TDP) should be used for processor thermal solution design targets. TDP is not the maximum power that the processor can dissipate. TDP is measured at maximum T_{CASE} .
4. These specifications are based on initial silicon characterization. These specifications may be further updated as more characterization data becomes available.
5. Power specifications are defined at all VIDs found in Table 2-3. The Quad-Core Intel® Xeon® Processor L5300 Series may be shipped under multiple VIDs for each frequency.
6. FMB, or Flexible Motherboard, guidelines provide a design target for meeting all planned processor frequency requirements.

Figure 6-3. Quad-Core Intel® Xeon® Processor L5300 Series Thermal Profile



Notes:

1. Please refer to Table 6-7 for discrete points that constitute the thermal profile.
2. Refer to the *Clovertown Processor Thermal/Mechanical Design Guidelines* for system and environmental implementation details.



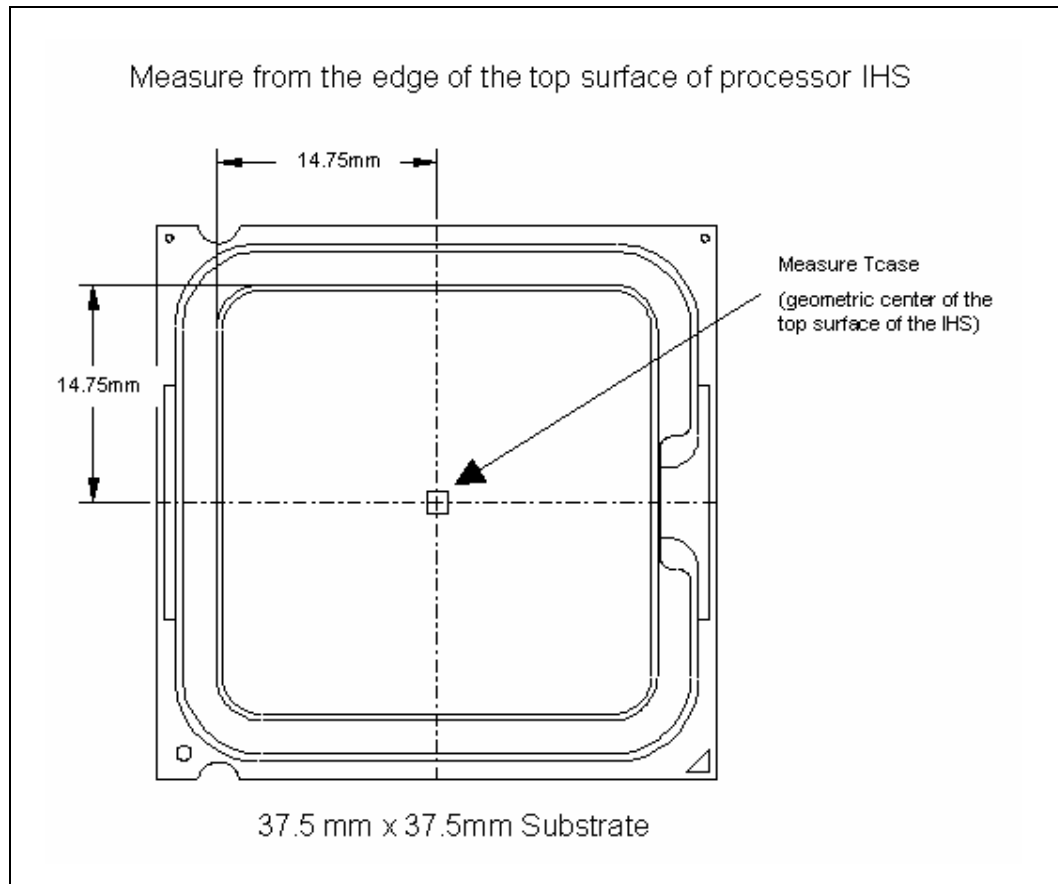
Table 6-7. Quad-Core Intel® Xeon® Processor L5300 Series Thermal Profile

| Power (W) | T _{CASE_MAX} (°C) |
|--------------------|----------------------------|
| P_PROFILE_MIN=22.2 | 50.0 |
| 25 | 51.0 |
| 30 | 52.8 |
| 35 | 54.6 |
| 40 | 56.4 |
| 45 | 58.2 |
| 50 | 60.0 |

6.1.2 Thermal Metrology

The minimum and maximum case temperatures (T_{CASE}) are specified in Table 6-1, through Table 6-7 and are measured at the geometric top center of the processor integrated heat spreader (IHS). Figure 6-4 illustrates the location where T_{CASE} temperature measurements should be made. For detailed guidelines on temperature measurement methodology, refer to the *Clovertown Processor Thermal/Mechanical Design Guidelines*.

Figure 6-4. Case Temperature (T_{CASE}) Measurement Location



Note: Figure is not to scale and is for reference only.



6.2 Processor Thermal Features

6.2.1 Thermal Monitor Features

Quad-Core Intel® Xeon® Processor 5300 Series provide two thermal monitor features, Thermal Monitor (TM1) and Enhanced Thermal Monitor (TM2). The TM1 and TM2 must both be enabled in BIOS for the processor to be operating within specifications. When both are enabled, TM2 will be activated first and TM1 will be added if TM2 is not effective.

6.2.2 Thermal Monitor (TM1)

The Thermal Monitor (TM1) feature helps control the processor temperature by activating the Thermal Control Circuit (TCC) when the processor silicon reaches its maximum operating temperature. The TCC reduces processor power consumption as needed by modulating (starting and stopping) the internal processor core clocks. The temperature at which Thermal Monitor activates the thermal control circuit is not user configurable and is not software visible. Bus traffic is snooped in the normal manner, and interrupt requests are latched (and serviced during the time that the clocks are on) while the TCC is active.

When the TM1 is enabled, and a high temperature situation exists (that is, TCC is active), the clocks will be modulated by alternately turning off and on at a duty cycle specific to the processor (typically 30 - 50%). Cycle times are processor speed dependent and will decrease as processor core frequencies increase. A small amount of hysteresis has been included to prevent rapid active/inactive transitions of the TCC when the processor temperature is near its maximum operating temperature. Once the temperature has dropped below the maximum operating temperature, and the hysteresis timer has expired, the TCC goes inactive and clock modulation ceases.

With thermal solutions designed to the Quad-Core Intel® Xeon® Processor E5300 Series Thermal Profile, the Quad-Core Intel® Xeon® Processor L5300 Series Thermal Profile, or Quad-Core Intel® Xeon® Processor X5300 Series Thermal Profile A it is anticipated that the TCC would only be activated for very short periods of time when running the most power intensive applications. The processor performance impact due to these brief periods of TCC activation is expected to be so minor that it would be immeasurable. A thermal solution that is designed to Quad-Core Intel® Xeon® Processor X5300 Series Thermal Profile B may cause a noticeable performance loss due to increased TCC activation. Thermal Solutions that exceed Thermal Profile B will exceed the maximum temperature specification and affect the long-term reliability of the processor. In addition, a thermal solution that is significantly under designed may not be capable of cooling the processor even when the TCC is active continuously Refer to the *Clovertown Processor Thermal/Mechanical Design Guidelines* for information on designing a thermal solution.

The duty cycle for the TCC, when activated by the TM1, is factory configured and cannot be modified. The TM1 does not require any additional hardware, software drivers, or interrupt handling routines.

6.2.3 Thermal Monitor 2

The Quad-Core Intel® Xeon® Processor 5300 Series adds support for an Enhanced Thermal Monitor capability known as Thermal Monitor 2 (TM2). This mechanism provides an efficient means for limiting the processor temperature by reducing the power consumption within the processor. TM2 requires support for dynamic VID transitions in the platform.



When TM2 is enabled, and a high temperature situation is detected, the Thermal Control Circuit (TCC) will be activated for all processor cores. The TCC causes the processor to adjust its operating frequency (via the bus multiplier) and input voltage (via the VID signals). This combination of reduced frequency and VID results in a reduction to the processor power consumption.

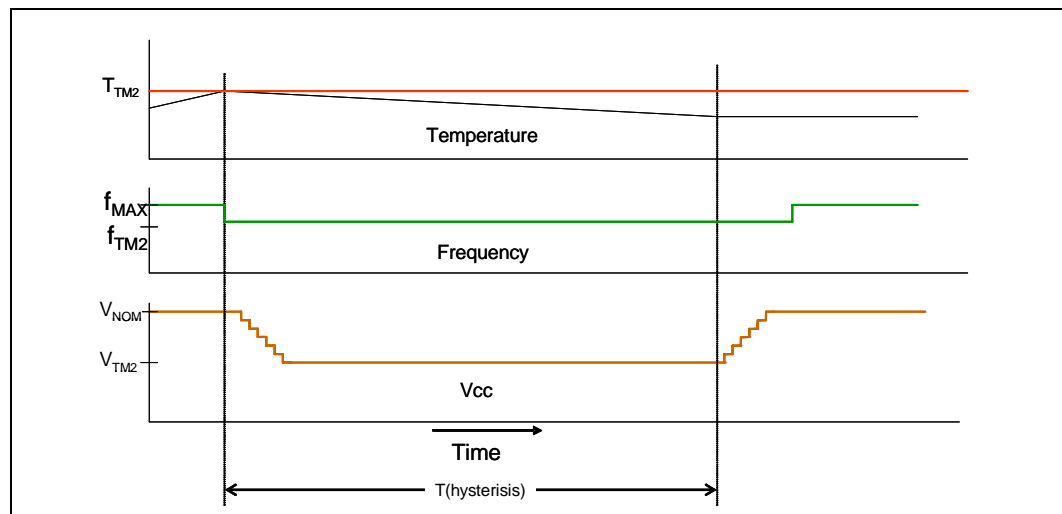
A processor enabled for TM2 includes two operating points, each consisting of a specific operating frequency and voltage, which is identical for both processor dies. The first operating point represents the normal operating condition for the processor. Under this condition, the core-frequency-to-system-bus multiplier utilized by the processor is that contained in the CLOCK_FLEX_MAX MSR and the VID that is specified in [Table 2-3](#).

The second operating point consists of both a lower operating frequency and voltage. The lowest operating frequency is determined by the lowest supported bus ratio (1/6 for the Quad-Core Intel® Xeon® Processor 5300 Series). When the TCC is activated, the processor automatically transitions to the new frequency. This transition occurs rapidly, on the order of 5 μ s. During the frequency transition, the processor is unable to service any bus requests, and consequently, all bus traffic is blocked. Edge-triggered interrupts will be latched and kept pending until the processor resumes operation at the new frequency.

Once the new operating frequency is engaged, the processor will transition to the new core operating voltage by issuing a new VID code to the voltage regulator. The voltage regulator must support dynamic VID steps in order to support Thermal Monitor 2. During the voltage change, it will be necessary to transition through multiple VID codes to reach the target operating voltage. Each step will be one VID table entry (see [Table 2-3](#)). The processor continues to execute instructions during the voltage transition. Operation at the lower voltage reduces the power consumption of the processor.

A small amount of hysteresis has been included to prevent rapid active/inactive transitions of the TCC when the processor temperature is near its maximum operating temperature. Once the temperature has dropped below the maximum operating temperature, and the hysteresis timer has expired, the operating frequency and voltage transition back to the normal system operating point. Transition of the VID code will occur first, in order to insure proper operation once the processor reaches its normal operating frequency. Refer to [Figure 6-5](#) for an illustration of this ordering.

Figure 6-5. Thermal Monitor 2 Frequency and Voltage Ordering





The PROCHOT# signal is asserted when a high temperature situation is detected, regardless of whether TM1 or TM2 is enabled.

6.2.4 On-Demand Mode

The processor provides an auxiliary mechanism that allows system software to force the processor to reduce its power consumption. This mechanism is referred to as “On-Demand” mode and is distinct from the Thermal Monitor 1 and Thermal Monitor 2 features. On-Demand mode is intended as a means to reduce system level power consumption. Systems utilizing the Quad-Core Intel® Xeon® Processor 5300 Series must not rely on software usage of this mechanism to limit the processor temperature. If bit 4 of the IA32_CLOCK_MODULATION MSR is set to a ‘1’, the processor will immediately reduce its power consumption via modulation (starting and stopping) of the internal core clock, independent of the processor temperature. When using On-Demand mode, the duty cycle of the clock modulation is programmable via bits 3:1 of the same IA32_CLOCK_MODULATION MSR. In On-Demand mode, the duty cycle can be programmed from 12.5% on/ 87.5% off to 87.5% on/12.5% off in 12.5% increments. On-Demand mode may be used in conjunction with the Thermal Monitor; however, if the system tries to enable On-Demand mode at the same time the TCC is engaged, the factory configured duty cycle of the TCC will override the duty cycle selected by the On-Demand mode.

6.2.5 PROCHOT# Signal

An external signal, PROCHOT# (processor hot) is asserted when the processor die temperature of any processor cores has reached its factory configured trip point. If Thermal Monitor is enabled (note that Thermal Monitor must be enabled for the processor to be operating within specification), the TCC will be active when PROCHOT# is asserted. The processor can be configured to generate an interrupt upon the assertion or de-assertion of PROCHOT#. Refer to the *Intel® 64 and IA-32 Architectures Software Developer’s Manual* and the *Conroe and Woodcrest Processor Family BIOS Writer’s Guide* for specific register and programming details.

PROCHOT# is designed to assert at or a few degrees higher than maximum T_{CASE} (as specified by Thermal Profile A) when dissipating TDP power, and cannot be interpreted as an indication of processor case temperature. This temperature delta accounts for processor package, lifetime and manufacturing variations and attempts to ensure the Thermal Control Circuit is not activated below maximum T_{CASE} when dissipating TDP power. There is no defined or fixed correlation between the PROCHOT# trip temperature, or the case temperature. Thermal solutions must be designed to the processor specifications and cannot be adjusted based on experimental measurements of T_{CASE} , or PROCHOT#.

6.2.6 FORCEPR# Signal

The FORCEPR# (force power reduction) input can be used by the platform to cause the Quad-Core Intel® Xeon® Processor 5300 Series to activate the TCC. If the processor supports Thermal Monitor 2 (TM2), and has Thermal Monitor 2 and Thermal Monitor (TM) properly enabled, assertion of the FORCEPR# signal will immediately activate Thermal Monitor 2. If the processor does not support Thermal Monitor 2, but has Thermal Monitor properly enabled, FORCEPR# signal assertion will cause Thermal Monitor to become active. Please refer to the *Quad-Core Intel® Xeon® Processor 5300 Series NDA Specification Update* to determine which processors support TM2 and *Conroe and Woodcrest Processor Family BIOS Writer’s Guide* for details on enabling these capabilities. Assertion of the FORCEPR# signal will activate TCC for all processor cores. The TCC will remain active until the system deasserts FORCEPR#.



FORCEPR# is an asynchronous input, which can be employed to thermally protect other system components. To use the voltage regulator (VR) as an example, TCC circuit activation will reduce the current consumption of the processor and the corresponding temperature of the VR.

It should be noted that assertion of FORCEPR# does not automatically assert PROCHOT#. As mentioned previously, the PROCHOT# signal is asserted when a high temperature situation is detected. A minimum pulse width of 500 μ s is recommended when FORCEPR# is asserted by the system. Sustained activation of the FORCEPR# signal may cause noticeable platform performance degradation.

Refer to the appropriate platform design guidelines for details on implementing the FORCEPR# signal feature.

6.2.7 THERMTRIP# Signal

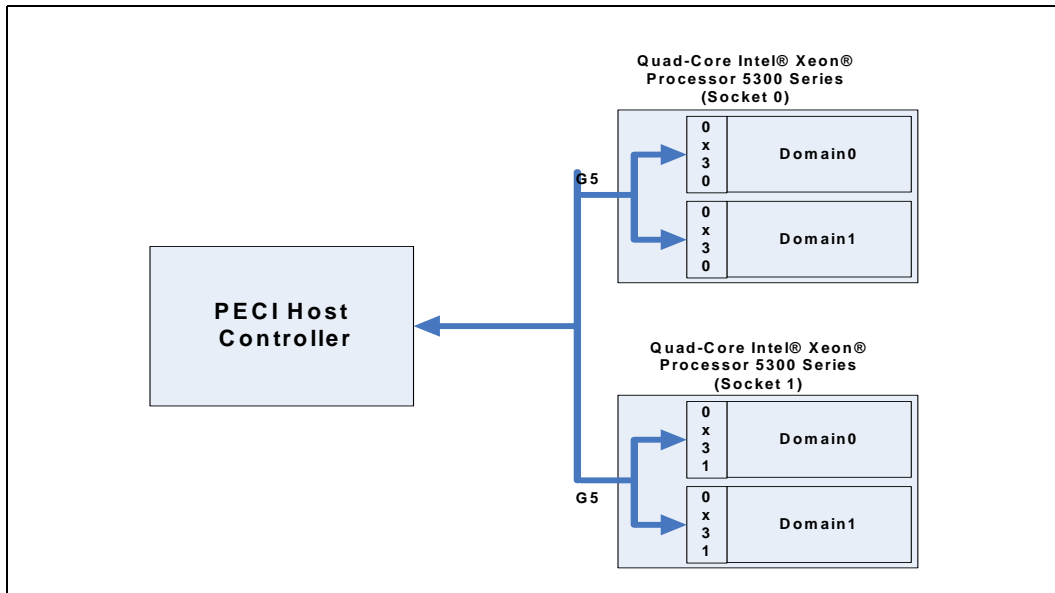
Regardless of whether or not TM1 or TM2 is enabled, in the event of a catastrophic cooling failure, the processor will automatically shut down when the silicon has reached an elevated temperature (refer to the THERMTRIP# definition in [Table 5-1](#)). At this point, the FSB signal THERMTRIP# will go active and stay active as described in [Table 5-1](#). THERMTRIP# activation is independent of processor activity and does not generate any bus cycles. Intel also recommends the removal of V_{TT} .

6.3 Platform Environment Control Interface (PECI)

6.3.1 Introduction

PECI offers an interface for thermal monitoring of Intel processor and chipset components. It uses a single wire, thus alleviating routing congestion issues. [Figure 6-6](#) shows an example of the PECI topology in a system with Quad-Core Intel® Xeon® Processor 5300 Series. PECI uses CRC checking on the host side to ensure reliable transfers between the host and client devices. Also, data transfer speeds across the PECI interface are negotiable within a wide range (2 Kbps to 2 Mbps). The PECI interface on Quad-Core Intel® Xeon® Processor 5300 Series is disabled by default and must be enabled through BIOS. More information on this can be found in the *Conroe and Woodcrest Processor Family BIOS Writer's Guide*.

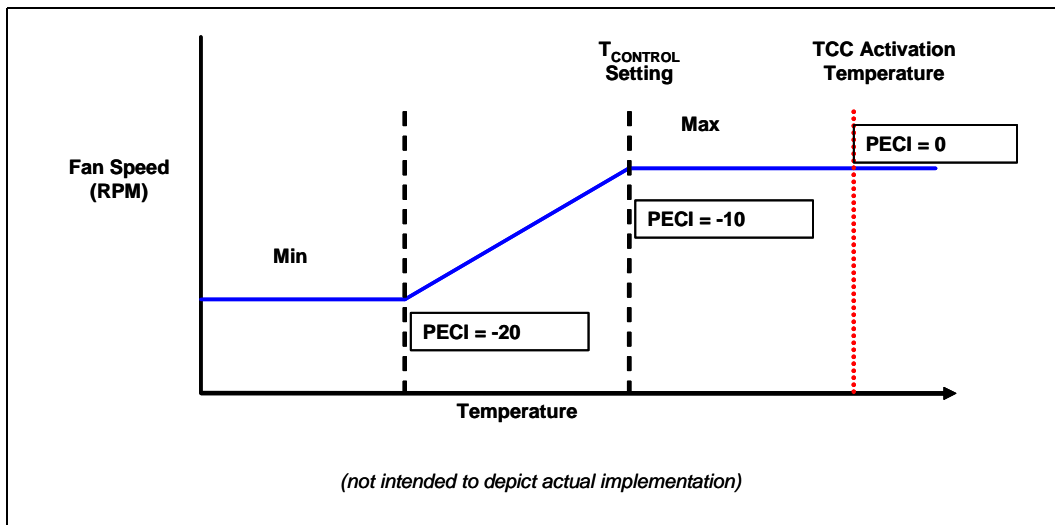
Figure 6-6. PECE Topology

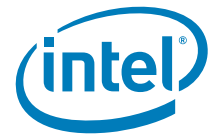


6.3.1.1 T_{CONTROL} and TCC Activation on PECE-Based Systems

Fan speed control solutions based on PECE utilize a T_{CONTROL} value stored in the processor IA32_TEMPERATURE_TARGET MSR. This MSR uses the same offset temperature format as PECE, though it contains no sign bit. Thermal management devices should infer the T_{CONTROL} value as negative. Thermal management algorithms should utilize the relative temperature value delivered over PECE in conjunction with the MSR value to control or optimize fan speeds. Figure 6-7 shows a conceptual fan control diagram using PECE temperatures.

Figure 6-7. Conceptual Fan Control Diagram For A PECE-Based Platform





6.3.1.2 Processor Thermal Data Sample Rate and Filtering

The DTS provides an improved capability to monitor device hot spots, which inherently leads to more varying temperature readings over short time intervals. The DTS sample interval range can be modified, and a data filtering algorithm can be activated to help moderate this. The DTS sample interval range is 82 ms (default) to 20 ms (max). This value can be set in BIOS.

To reduce the sample rate requirements on PECI and improve thermal data stability vs. time the processor DTS also implements an averaging algorithm that filters the incoming data. This is an alpha-beta filter with coefficients of 0.5, and is expressed mathematically as: $\text{Current_filtered_temp} = (\text{Previous_filtered_temp} / 2) + (\text{new_sensor_temp} / 2)$. This filtering algorithm is fixed and cannot be changed. It is on by default and can be turned off in BIOS.

Host controllers should utilize the min/max sample times to determine the appropriate sample rate based on the controller's fan control algorithm and targeted response rate. The key items to take into account when settling on a fan control algorithm are the DTS sample rate, whether the temperature filter is enabled, how often the PECI host will poll the processor for temperature data, and the rate at which fan speed is changed. Depending on the designer's specific requirements the DTS sample rate and alpha-beta filter may have no effect on the fan control algorithm.

6.3.2 PECI Specifications

6.3.2.1 PECI Device Address

The PECI device address for socket 0 is 0x30 and socket 1 is 0x31. Please note that each address also supports two domains (Domain 0 and Domain 1). For more information on PECI domains, please refer to the *Platform Environment Control Interface Specification*.

6.3.2.2 PECI Command Support

PECI command support is covered in detail in *Platform Environment Control Interface Specification*. Please refer to this document for details on supported PECI command function and codes

6.3.2.3 PECI Fault Handling Requirements

PECI is largely a fault tolerant interface, including noise immunity and error checking improvements over other compatible industry standard interfaces. The PECI client is as reliable as the device that it is embedded within, and thus given operating conditions that fall under the specification, the PECI client will always respond to requests and the protocol itself can be relied upon to detect any transmission failures. There are, however, certain scenarios where PECI is known to be unresponsive.

Prior to a power on RESET# and during RESET# assertion, PECI is not guaranteed to provide reliable thermal data. System designs should implement a default power-on condition that ensures proper processor operation during the time frame when reliable data is not available via PECI.

To protect platforms from potential operational or safety issues due to an abnormal condition on PECI, the PECI host controller should take action to protect the system from possible damage. It is recommended that the PECI host controller take appropriate action to protect the client processor device if valid temperature readings



have not been obtained in response to three consecutive `gettemp()`s or for a one second time interval. The PECI host controller may also implement an alert to software in the event of a critical or continuous fault condition.

6.3.2.4 PECI `GetTemp0()` and `GetTemp1()` Error Code Support

The error codes supported for the processor `GetTemp0()` and `GetTemp1()` command are listed in [Table 6-8](#) below:

Table 6-8. `GetTemp0()` and `GetTemp1()` Error Codes

| Error Code | Description |
|------------|--|
| 0x8000 | General sensor error |
| 0x8002 | Sensor is operational, but has detected a temperature below its operational range (underflow). |

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7 Features

7.1 Power-On Configuration Options

Several configuration options can be configured by hardware. Quad-Core Intel® Xeon® Processor 5300 Series sample its hardware configuration at reset, on the active-to-inactive transition of RESET#. For specifics on these options, please refer to [Table 7-1](#).

The sampled information configures the processor for subsequent operation. These configuration options cannot be changed except by another reset. All resets reconfigure the processor, for reset purposes, the processor does not distinguish between a “warm” reset (PWRGOOD signal remains asserted) and a “power-on” reset.

Table 7-1. Power-On Configuration Option Lands

| Configuration Option | Land Name | Notes |
|-----------------------------------|-----------|-------|
| Output tri state | SMI# | 1,2,3 |
| Execute BIST (Built-In Self Test) | A3# | 1,2 |
| Disable MCERR# observation | A9# | 1,2 |
| Disable BINIT# observation | A10# | 1,2 |
| Symmetric agent arbitration ID | BR[1:0]# | 1,2 |

Notes:

1. Asserting this signal during RESET# will select the corresponding option.
2. Address lands not identified in this table as configuration options should not be asserted during RESET#.
3. Requires de-assertion of PWRGOOD.

Disabling of any of the cores within the Quad-Core Intel® Xeon® Processor 5300 Series must be handled by configuring the EXT_CONFIG Model Specific Register (MSR). This MSR will allow for the disabling of a single core per die within the Quad-Core Intel® Xeon® Processor 5300 Series package. Additional details can be found in the *Conroe and Woodcrest Processor Family BIOS Writer's Guide*.

7.2 Clock Control and Low Power States

Quad-Core Intel® Xeon® Processor 5300 Series support the Extended HALT state (also referred to as C1E) in addition to the HALT state and Stop-Grant state to reduce power consumption by stopping the clock to internal sections of the processor, depending on each particular state. See [Figure 7-1](#) for a visual representation of the processor low power states. The Extended HALT state is a lower power state than the HALT state or Stop Grant state.

The Extended HALT state must be enabled via the BIOS for the processor to remain within its specifications. Refer to the *Conroe and Woodcrest Processor Family BIOS Writer's Guide*. For processors that are already running at the lowest bus to core frequency ratio for its nominal operating point, the processor will transition to the HALT state instead of the Extended HALT state.

The Stop Grant state requires chipset and BIOS support on multiprocessor systems. In a multiprocessor system, all the STPCLK# signals are bussed together, thus all processors are affected in unison. When the STPCLK# signal is asserted, the processor enters the Stop Grant state, issuing a Stop Grant Special Bus Cycle (SBC) for each processor. The chipset needs to account for a variable number of processors asserting



the Stop Grant SBC on the bus before allowing the processor to be transitioned into one of the lower processor power states. Refer to the applicable chipset specification and the *Conroe and Woodcrest Processor Family BIOS Writer's Guide* for more information.

7.2.1 Normal State

This is the normal operating state for the processor.

7.2.2 HALT or Extended HALT State

The Extended HALT state (C1E) is enabled via the BIOS. Refer to the *Conroe and Woodcrest Processor Family BIOS Writer's Guide*. **The Extended HALT state must be enabled for the processor to remain within its specifications.** The Extended HALT state requires support for dynamic VID transitions in the platform.

7.2.2.1 HALT State

HALT is a low power state entered when the processor has executed the HALT or MWAIT instruction. When one of the processor cores execute the HALT or MWAIT instruction, that processor core is halted; however, the other processor continues normal operation. The processor will transition to the Normal state upon the occurrence of SMI#, BINIT#, INIT#, LINT[1:0] (NMI, INTR), or an interrupt delivered over the front side bus. RESET# will cause the processor to immediately initialize itself.

The return from a System Management Interrupt (SMI) handler can be to either Normal Mode or the HALT state. See the *Intel® 64 and IA-32 Intel® Architecture Software Developer's Manual, Volume III: System Programming Guide* for more information.

The system can generate a STPCLK# while the processor is in the HALT state. When the system deasserts STPCLK#, the processor will return execution to the HALT state.

While in HALT state, the processor will process front side bus snoops and interrupts.

7.2.2.2 Extended HALT State

Extended HALT state is a low power state entered when all four processor cores have executed the HALT or MWAIT instructions and Extended HALT state has been enabled via the BIOS. When one of the processor cores executes the HALT instruction, that processor core is halted; however, the other processor cores continue normal operation. The Extended HALT state is a lower power state than the HALT state or Stop Grant state. The Extended HALT state must be enabled for the processor to remain within its specifications.

The processor will automatically transition to a lower core frequency and voltage operating point before entering the Extended HALT state. Note that the processor FSB frequency is not altered; only the internal core frequency is changed. When entering the low power state, the processor will first switch to the lower bus to core frequency ratio and then transition to the lower voltage (VID).

While in the Extended HALT state, the processor will process bus snoops.



Table 7-2. Extended HALT Maximum Power

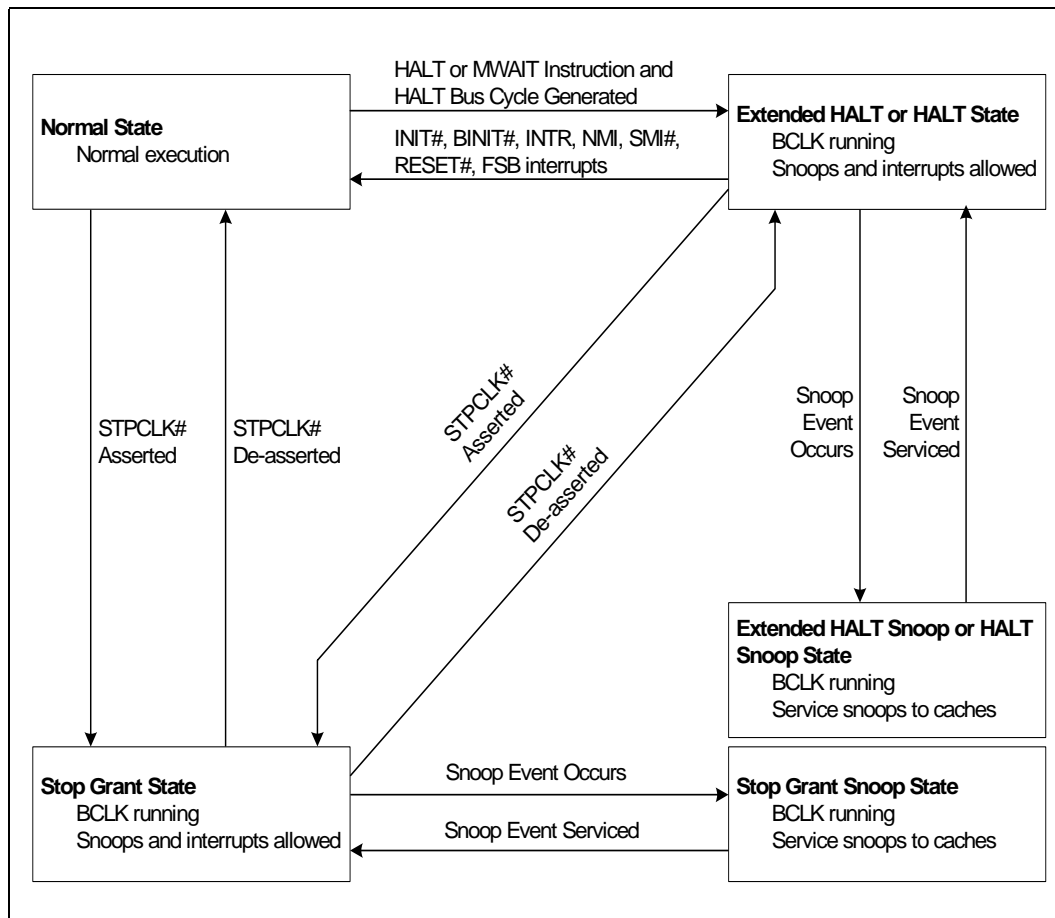
| Symbol | Parameter | Min | Typ | Max | Unit | Notes |
|---|---------------------------|-----|-----|-------|------|-------|
| $P_{\text{EXTENDED_HALT}}$ Quad-Core Intel® Xeon® Processor E5300 Series | Extended HALT State Power | | | 30/34 | W | 1,2,3 |
| $P_{\text{EXTENDED_HALT}}$ Quad-Core Intel® Xeon® Processor X5300 Series | Extended HALT State Power | | | 50 | W | 1,2 |
| $P_{\text{EXTENDED_HALT}}$ Quad-Core Intel® Xeon® Processor L5300 Series | Extended HALT State Power | | | 20 | W | 1 |

Notes:

1. The specification is at $T_{\text{CASE}} = 50^{\circ}\text{C}$ and nominal V_{CC} . The VID setting represents the maximum expected VID while running in HALT state.
2. This specification is characterized by design.
3. Processors running in the lowest bus ratio will enter the HALT state when the processor has executed the HALT and MWAIT instruction since the processor is already in the lowest core frequency and voltage operating point. Values represent SKUs with Extended HALT state (30 W) and without Extended HALT state (34 W).

The processor exits the Extended HALT state when a break event occurs. When the processor exits the Extended HALT state, it will first transition the VID to the original value and then change the bus to core frequency ratio back to the original value.

Figure 7-1. Stop Clock State Machine



7.2.3 Stop-Grant State

When the STPCLK# pin is asserted, the Stop-Grant state of the processor is entered 20 bus clocks after the response phase of the processor issued Stop Grant Acknowledge special bus cycle. The Quad-Core Intel® Xeon® Processor 5300 Series will issue two Stop Grant Acknowledge special bus cycles, once for each die. Once the STPCLK# pin has been asserted, it may only be deasserted once the processor is in the Stop Grant state. All processor cores will enter the Stop-Grant state once the STPCLK# pin is asserted. Additionally, all processor cores must be in the Stop Grant state before the deassertion of STPCLK#.

Since the AGTL+ signal pins receive power from the front side bus, these pins should not be driven (allowing the level to return to V_{TT}) for minimum power drawn by the termination resistors in this state. In addition, all other input pins on the front side bus should be driven to the inactive state.

BINIT# will not be serviced while the processor is in Stop-Grant state. The event will be latched and can be serviced by software upon exit from the Stop Grant state.

RESET# will cause the processor to immediately initialize itself, but the processor will stay in Stop-Grant state. A transition back to the Normal state will occur with the deassertion of the STPCLK# signal.



A transition to the Grant Snoop state will occur when the processor detects a snoop on the front side bus (see [Section 7.2.4.1](#)).

While in the Stop-Grant state, SMI#, INIT#, BINIT# and LINT[1:0] will be latched by the processor, and only serviced when the processor returns to the Normal state. Only one occurrence of each event will be recognized upon return to the Normal state.

While in Stop-Grant state, the processor will process snoops on the front side bus and it will latch interrupts delivered on the front side bus.

The PBE# signal can be driven when the processor is in Stop-Grant state. PBE# will be asserted if there is any pending interrupt latched within the processor. Pending interrupts that are blocked by the EFLAGS.IF bit being clear will still cause assertion of PBE#. Assertion of PBE# indicates to system logic that it should return the processor to the Normal state.

7.2.4 Extended HALT Snoop or HALT Snoop State, Stop Grant Snoop State

The Extended HALT Snoop state is used in conjunction with the Extended HALT state. If the Extended HALT state is not enabled in the BIOS, the default Snoop state entered will be the HALT Snoop state. Refer to the sections below for details on HALT Snoop state, Stop Grant Snoop state and Extended HALT Snoop state.

7.2.4.1 HALT Snoop State, Stop Grant Snoop State

The processor will respond to snoop or interrupt transactions on the front side bus while in Stop-Grant state or in HALT state. During a snoop or interrupt transaction, the processor enters the HALT/Grant Snoop state. The processor will stay in this state until the snoop on the front side bus has been serviced (whether by the processor or another agent on the front side bus) or the interrupt has been latched. After the snoop is serviced or the interrupt is latched, the processor will return to the Stop-Grant state or HALT state, as appropriate.

7.2.4.2 Extended HALT Snoop State

The Extended HALT Snoop state is the default Snoop state when the Extended HALT state is enabled via the BIOS. The processor will remain in the lower bus to core frequency ratio and VID operating point of the Extended HALT state.

While in the Extended HALT Snoop state, snoops and interrupt transactions are handled the same way as in the HALT Snoop state. After the snoop is serviced or the interrupt is latched, the processor will return to the Extended HALT state.

7.3 Enhanced Intel SpeedStep® Technology

Quad-Core Intel® Xeon® Processor 5300 Series support Enhanced Intel SpeedStep® Technology. This technology enables the processor to switch between multiple frequency and voltage points, which results in platform power savings. Enhanced Intel SpeedStep Technology requires support for dynamic VID transitions in the platform. Switching between voltage/frequency states is software controlled. For more configuration details also refer to the *Conroe and Woodcrest Processor Family BIOS Writer's Guide*.

Note: Not all Quad-Core Intel® Xeon® Processor 5300 Series are capable of supporting Enhanced Intel SpeedStep Technology. More details on which processor frequencies will



support this feature will be provided in future releases of the *Quad-Core Intel® Xeon® Processor 5300 Series NDA Specification Update* when available.

Enhanced Intel SpeedStep Technology creates processor performance states (P-states) or voltage/frequency operating points. P-states are lower power capability states within the Normal state as shown in [Figure 7-1](#). Enhanced Intel SpeedStep Technology enables real-time dynamic switching between frequency and voltage points. It alters the performance of the processor by changing the bus to core frequency ratio and voltage. This allows the processor to run at different core frequencies and voltages to best serve the performance and power requirements of the processor and system. The Quad-Core Intel® Xeon® Processor 5300 Series have hardware logic that coordinates the requested voltage (VID) between the processor cores. The highest voltage that is requested from the four processor cores is selected for that processor package. Note that the front side bus is not altered; only the internal core frequency is changed. In order to run at reduced power consumption, the voltage is altered in step with the bus ratio.

The following are key features of Enhanced Intel SpeedStep Technology:

- Multiple voltage/frequency operating points provide optimal performance at reduced power consumption.
- Voltage/frequency selection is software controlled by writing to processor MSR's (Model Specific Registers), thus eliminating chipset dependency.
 - If the target frequency is higher than the current frequency, V_{CC} is incremented in steps (+12.5 mV) by placing a new value on the VID signals and the processor shifts to the new frequency. Note that the top frequency for the processor can not be exceeded.
 - If the target frequency is lower than the current frequency, the processor shifts to the new frequency and V_{CC} is then decremented in steps (-12.5 mV) by changing the target VID through the VID signals.

Refer to the *Conroe and Woodcrest Processor Family BIOS Writer's Guide* for specific information to enable and configure Enhanced Intel SpeedStep Technology in BIOS.

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8 Boxed Processor Specifications

8.1 Introduction

Intel boxed processors are intended for system integrators who build systems from components available through distribution channels. The Quad-Core Intel® Xeon® Processor 5300 Series will be offered as an Intel boxed processor.

Intel will offer the Quad-Core Intel® Xeon® Processor 5300 Series boxed processor with two heat sink configurations available for each processor frequency: 1U passive/3U+ active combination solution and a 2U passive only solution. The 1U passive/3U+ active combination solution is based on a 1U passive heat sink with a removable fan that will be pre-attached at shipping. This heat sink solution is intended to be used as either a 1U passive heat sink, or a 3U+ active heat sink. Although the active combination solution with removable fan mechanically fits into a 2U keepout, its use is not recommended in that configuration.

The 1U passive/3U+ active combination solution in the active fan configuration is primarily designed to be used in a pedestal chassis where sufficient air inlet space is present and strong side directional airflow is not an issue. The 1U passive/3U+ active combination solution with the fan removed and the 2U passive thermal solution require the use of chassis ducting and are targeted for use in rack mount or pedestal servers. The retention solution used for these products is called the Common Enabling Kit, or CEK. The CEK base is compatible with both thermal solutions and uses the same hole locations as the Dual-Core Intel® Xeon® processor 5100 series.

The 1U passive/3U+ active combination solution will utilize a removable fan capable of 4-pin pulse width modulated (PWM) control. Use of a 4-pin PWM controlled active thermal solution helps customers meet acoustic targets in pedestal platforms through the motherboards's ability to directly control the RPM of the processor heat sink fan. See [Section 8.3](#) for more details on fan speed control, and see [Section 6.3](#) for more on the PWM and PECI interface along with Digital Thermal Sensors (DTS). [Figure 8-1](#) through [Figure 8-3](#) are representations of the two heat sink solutions.

Figure 8-1. Boxed Quad-Core Intel® Xeon® Processor 5300 Series 1U Passive/3U+ Active Combination Heat Sink (With Removable Fan)

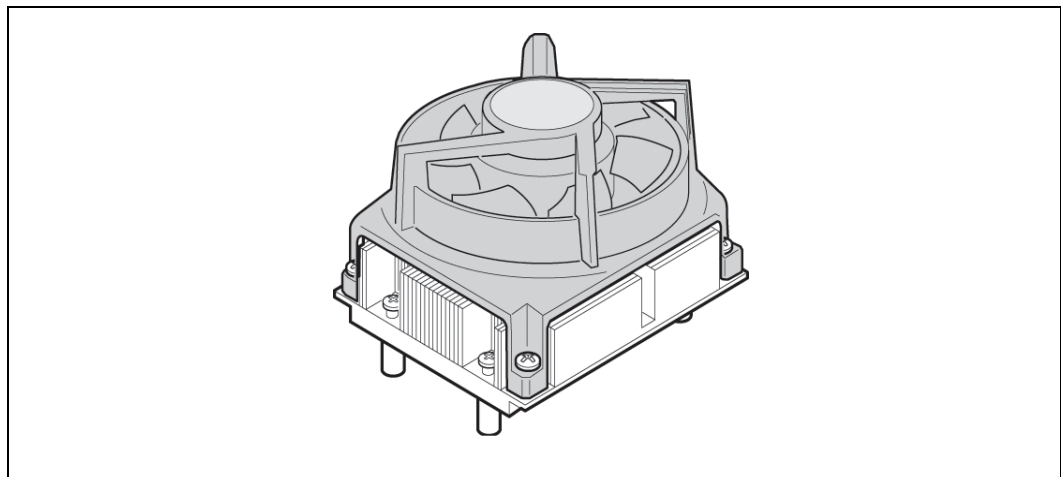


Figure 8-2. Boxed Quad-Core Intel® Xeon® Processor 5300 Series 2U Passive Heat Sink

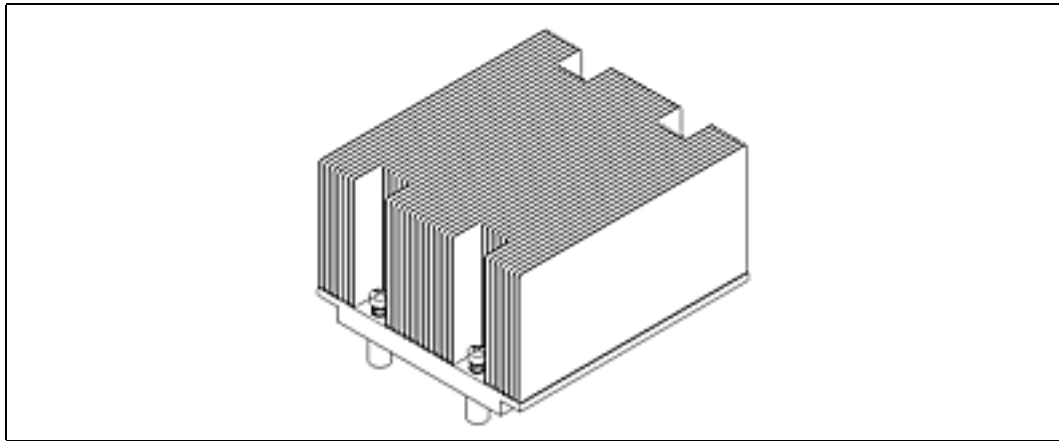
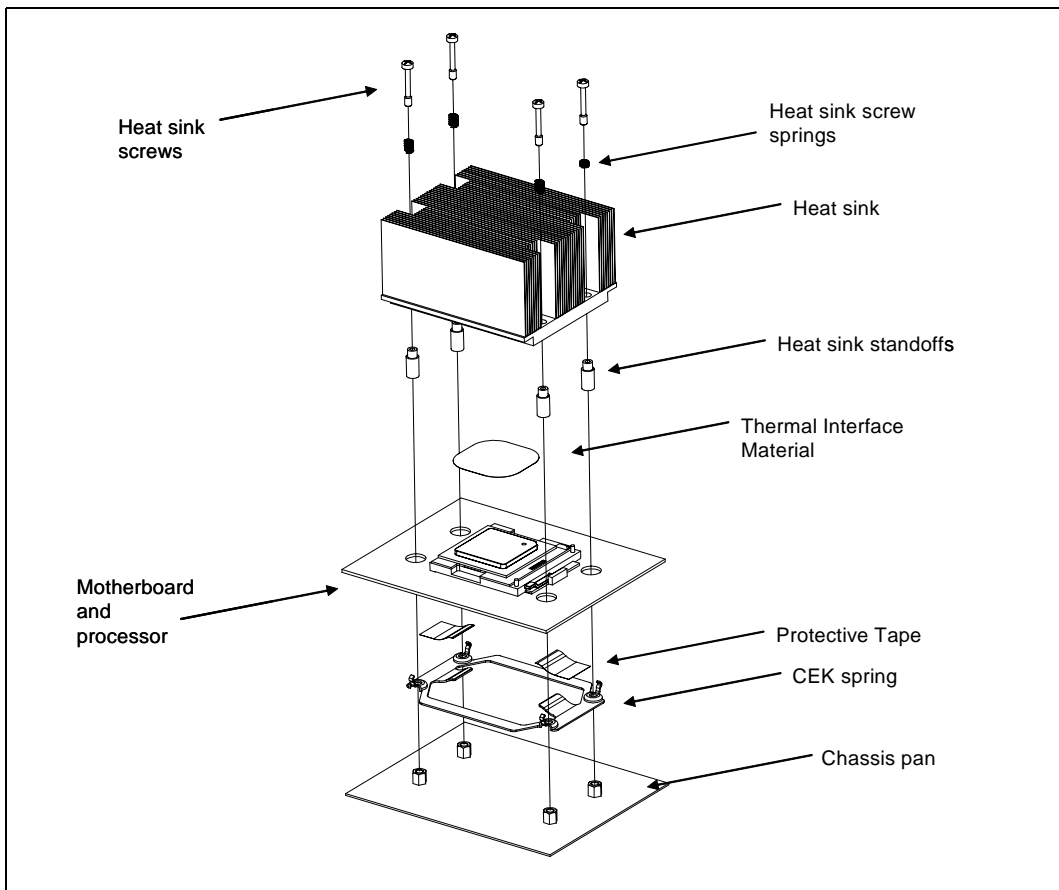


Figure 8-3. 2U Passive Quad-Core Intel® Xeon® Processor 5300 Series Processor Thermal Solution (Exploded View)



Note:

1. The heat sinks and fan assemblies represented in [Figure 8-1](#), [Figure 8-2](#), and [Figure 8-3](#) are for reference only, and may not represent the final boxed processor heat sinks.
2. The screws, springs, and standoffs will be captive to the heat sink. This image shows all of the components in an exploded view.
3. It is intended that the CEK spring will ship with the base board and be pre-attached prior to shipping.



8.2 Mechanical Specifications

This section documents the mechanical specifications of the boxed processor.

8.2.1 Boxed Processor Heat Sink Dimensions (CEK)

The boxed processor will be shipped with an unattached thermal solution. Clearance is required around the thermal solution to ensure unimpeded airflow for proper cooling. The physical space requirements and dimensions for the boxed processor and assembled heat sink are shown in [Figure 8-4](#) through [Figure 8-8](#). [Figure 8-9](#) through [Figure 8-10](#) are the mechanical drawings for the 4-pin board fan header and 4-pin connector used for the active CEK fan heat sink solution.



Figure 8-4. Top Side Board Keepout Zones (Part 1)

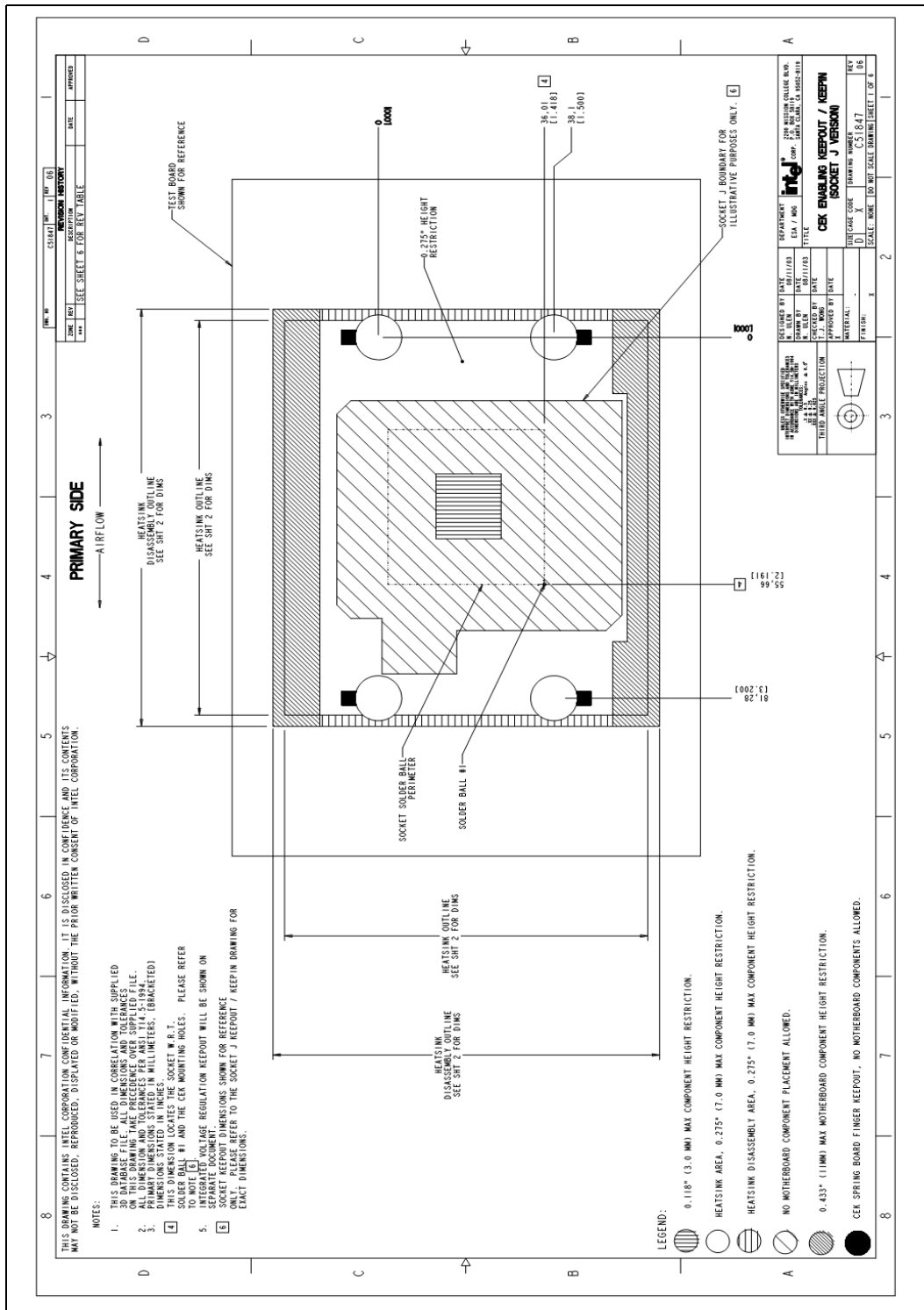


Figure 8-6. Bottom Side Board Keepout Zones

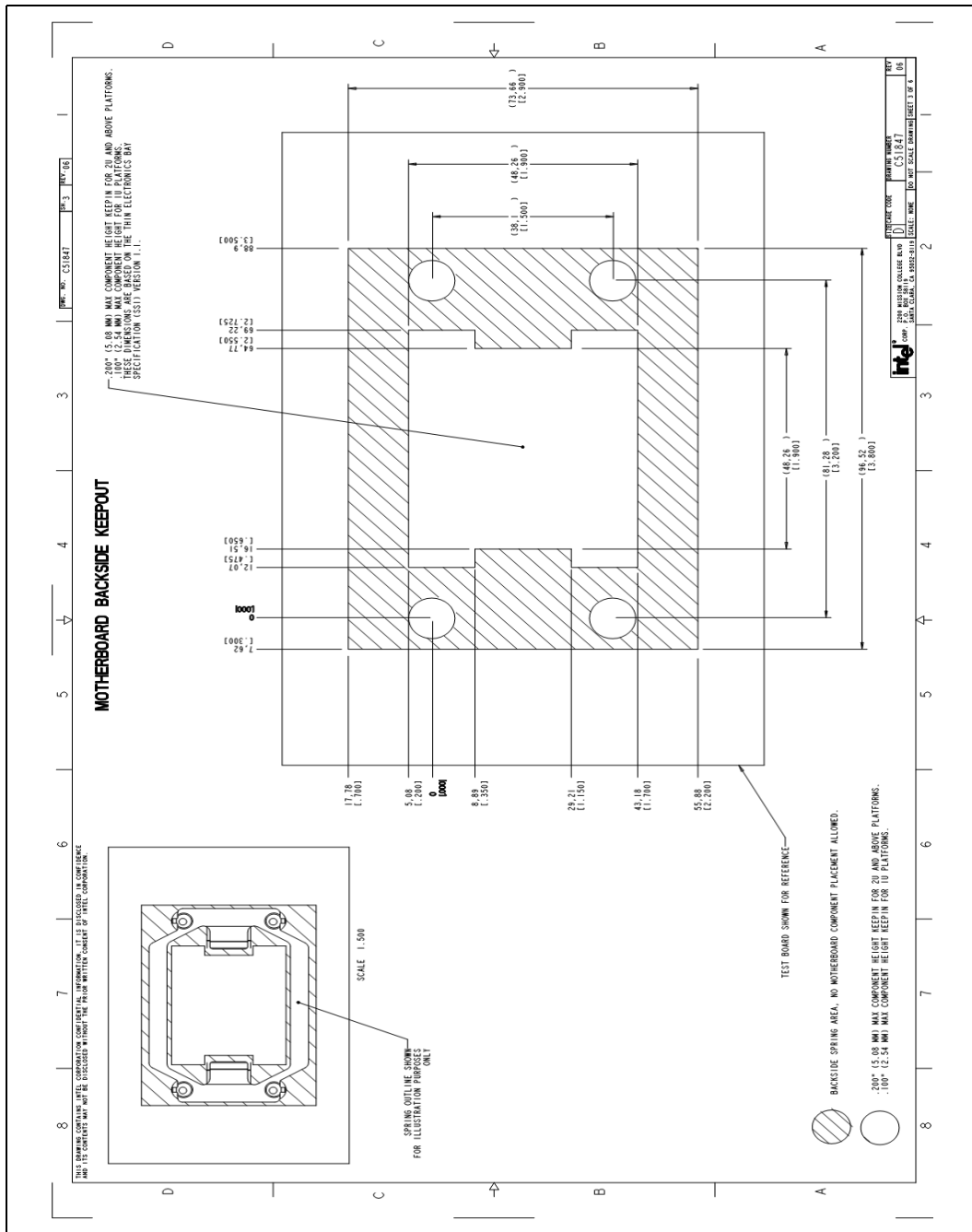




Figure 8-7. Board Mounting-Hole Keepout Zones

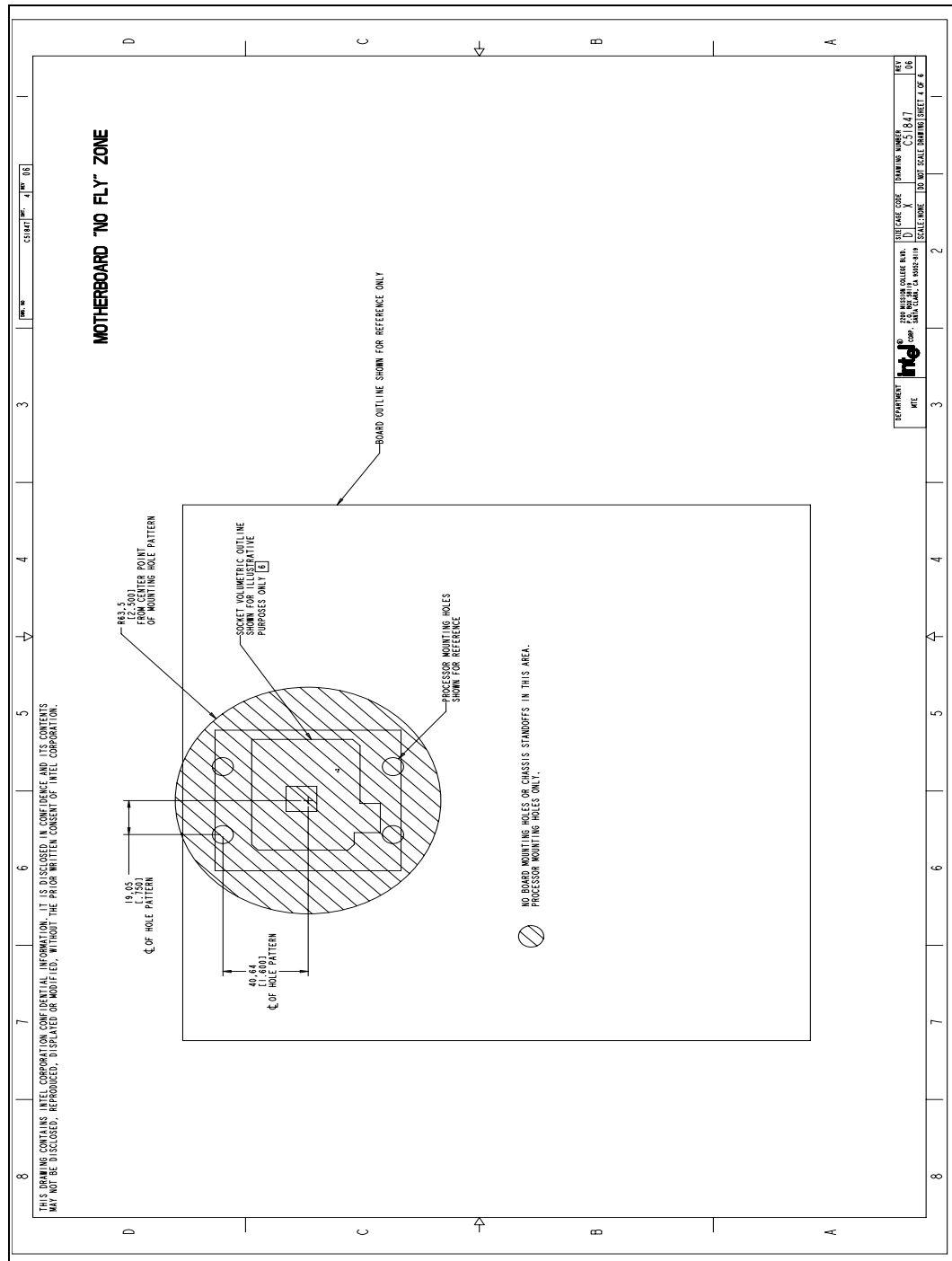


Figure 8-8. Volumetric Height Keep-Ins

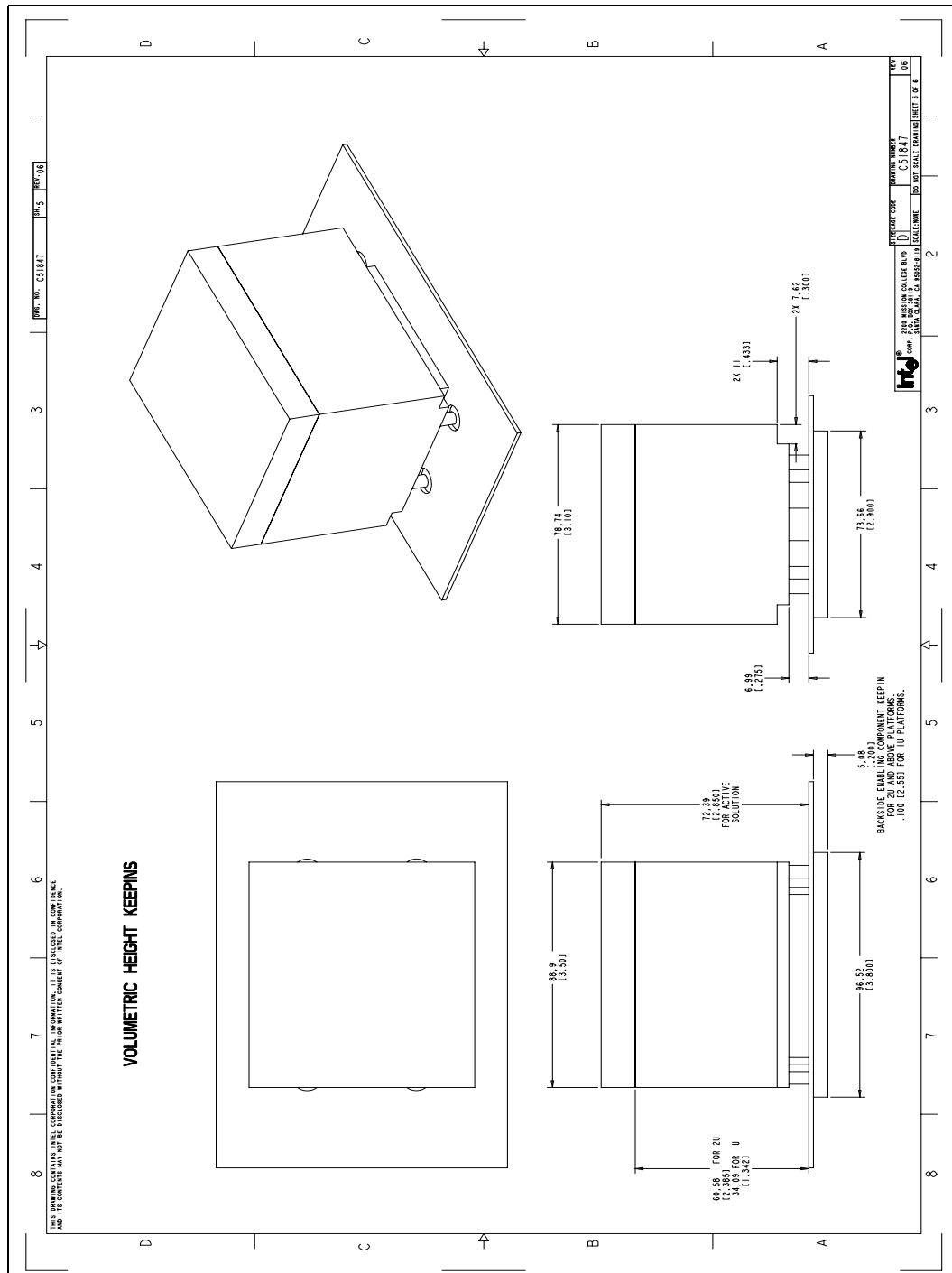
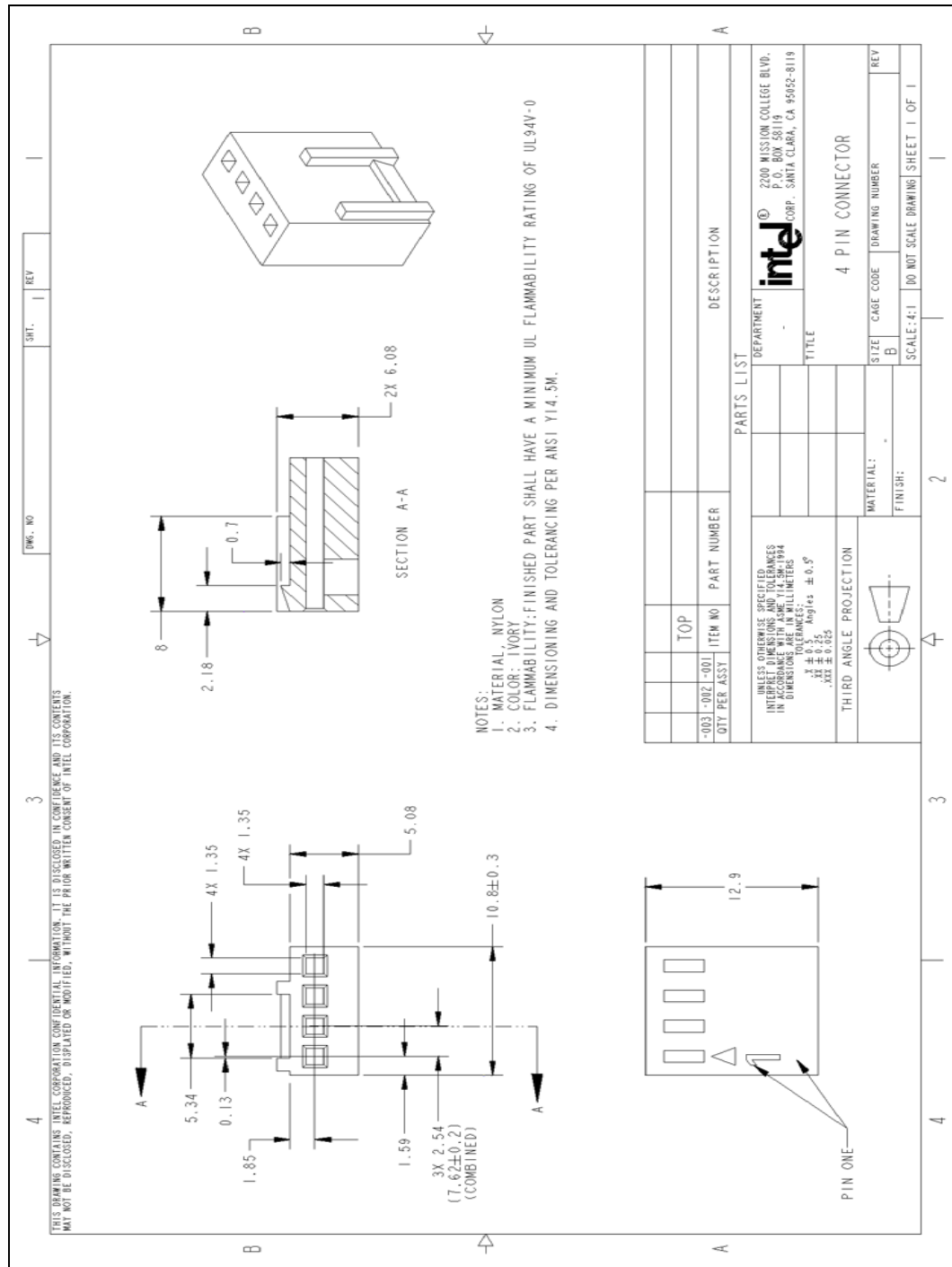




Figure 8-9. 4-Pin Fan Cable Connector (For Active CEK Heat Sink)





8.2.2 Boxed Processor Heat Sink Weight

8.2.2.1 Thermal Solution Weight

The 1U passive/3U+ active combination heat sink solution and the 2U passive heat sink solution will not exceed a mass of 1050 grams. Note that this is per processor, a dual processor system will have up to 2100 grams total mass in the heat sinks. This large mass will require a minimum chassis stiffness to be met in order to withstand force during shock and vibration.

See [Section 3](#) for details on the processor weight.

8.2.3 Boxed Processor Retention Mechanism and Heat Sink Support (CEK)

Baseboards and chassis designed for use by a system integrator should include holes that are in proper alignment with each other to support the boxed processor. Refer to the Server System Infrastructure Specification (SSI-EEB 3.6, TEB 2.1 or CEB 1.1). These specification can be found at: <http://www.ssiforum.org>.

[Figure 8-3](#) illustrates the Common Enabling Kit (CEK) retention solution. The CEK is designed to extend air-cooling capability through the use of larger heat sinks with minimal airflow blockage and bypass. CEK retention mechanisms can allow the use of much heavier heat sink masses compared to legacy limits by using a load path directly attached to the chassis pan. The CEK spring on the secondary side of the baseboard provides the necessary compressive load for the thermal interface material. The baseboard is intended to be isolated such that the dynamic loads from the heat sink are transferred to the chassis pan via the stiff screws and standoffs. The retention scheme reduces the risk of package pullout and solder joint failures.

All components of the CEK heat sink solution will be captive to the heat sink and will only require a Phillips screwdriver to attach to the chassis pan. When installing the CEK, the CEK screws should be tightened until they will no longer turn easily. This should represent approximately 6-8 inch-pounds of torque. More than that may damage the retention mechanism components.

8.3 Electrical Requirements

8.3.1 Fan Power Supply (Active CEK)

The 4-pin PWM controlled active thermal solution is being offered to help provide better control over pedestal chassis acoustics. This is achieved through more accurate measurement of processor die temperature through the processor's Digital Thermal Sensors. Fan RPM is modulated through the use of an ASIC located on the baseboard, that sends out a PWM control signal to the 4th pin of the connector labeled as Control. This thermal solution requires a constant +12 V supplied to pin 2 of the active thermal solution and does not support variable voltage control or 3-pin PWM control. See [Table 8-2](#) for details on the 4-pin active heat sink solution connectors.

If the 4-pin active fan heat sink solution is connected to an older 3-pin baseboard CPU fan header it will default back to a thermistor controlled mode, allowing compatibility with legacy 3-wire designs. When operating in thermistor controlled mode, fan RPM is automatically varied based on the TINLET temperature measured by a thermistor located at the fan inlet of the heat sink solution.

The fan power header on the baseboard must be positioned to allow the fan heat sink power cable to reach it. The fan power header identification and location must be documented in the suppliers platform documentation, or on the baseboard itself. The baseboard fan power header should be positioned within 177.8 mm [7 in.] from the center of the processor socket.

Table 8-1. PWM Fan Frequency Specifications for 4-Pin Active CEK Thermal Solution

| Description | Min Frequency | Nominal Frequency | Max Frequency | Unit |
|-----------------------------|---------------|-------------------|---------------|------|
| PWM Control Frequency Range | 21,000 | 25,000 | 28,000 | Hz |

Table 8-2. Fan Specifications for 4-Pin Active CEK Thermal Solution

| Description1 | Min | Typ Steady | Max Steady | Max Startup | Unit |
|---------------------------------|------|------------|------------|-------------|---------------------------|
| +12 V: 12 volt fan power supply | 10.8 | 12 | 12 | 13.2 | V |
| IC: Fan Current Draw | N/A | 1 | 1.25 | 1.5 | A |
| SENSE: SENSE frequency | 2 | 2 | 2 | 2 | Pulses per fan revolution |

Note:

- System board should pull this pin up to Vcc with a resistor

Figure 8-11. Fan Cable Connector Pin Out for 4-Pin Active CEK Thermal Solution

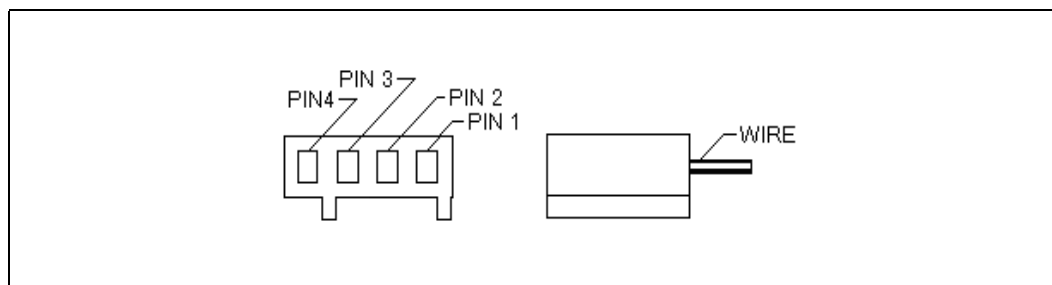


Table 8-3. Fan Cable Connector Pin Out for 4-Pin Active CEK Thermal Solution

| Pin Number | Signal | Color |
|------------|---------------------------------------|--------|
| 1 | Ground | Black |
| 2 | Power: (+12 V) | Yellow |
| 3 | Sense: 2 pulses per revolution | Green |
| 4 | Control: 21 KHz-28 KHz | Blue |

Note: System board should provide an open drain / open collector for pin 4. Fan will pull this pin up to a specific voltage (5.25V max).

8.3.2 Boxed Processor Cooling Requirements

As previously stated the boxed processor will be available in two product configurations. Each configuration will require unique design considerations. Meeting the processor’s temperature specifications is also the function of the thermal design of the entire system, and ultimately the responsibility of the system integrator. The processor temperature specifications are found in [Section 6](#) of this document.



8.3.2.1 1U Passive/3U+ Active Combination Heat Sink Solution (1U Rack Passive)

In the 1U configuration it is assumed that a chassis duct will be implemented to provide a minimum airflow of 15 cfm at 0.38 in. H₂O (25.5 m³/hr at 94.6 Pa) of flow impedance. The duct should be carefully designed to minimize the airflow bypass around the heatsink. It is assumed that a 40°C T_{LA} is met. This requires a superior chassis design to limit the T_{RISE} at or below 5°C with an external ambient temperature of 35°C. Following these guidelines will allow the designer to meet Quad-Core Intel® Xeon® Processor X5300 Series Thermal Profile and conform to the thermal requirements of the processor.

8.3.2.2 1U Passive/3U+ Active Combination Heat Sink Solution (Pedestal Active)

The active configuration of the combination solution is designed to help pedestal chassis users to meet the thermal processor requirements without the use of chassis ducting. It may be still be necessary to implement some form of chassis air guide or air duct to meet the T_{LA} temperature of 40°C depending on the pedestal chassis layout. Also, while the active thermal solution design will mechanically fit into a 2U volumetric, it may not provide adequate airflow. This is due to the requirement of additional space at the top of the thermal solution to allow sufficient airflow into the heat sink fan. Use of the active configuration in a 2U rackmount chassis is not recommended.

It is recommended that the ambient air temperature outside of the chassis be kept at or below 35°C. The air passing directly over the processor thermal solution should not be preheated by other system components. Meeting the processor's temperature specification is the responsibility of the system integrator.

8.3.2.3 2U Passive Heat Sink Solution (2U+ Rack or Pedestal)

In the 2U+ passive configuration it is assumed that a chassis duct will be implemented to provide a minimum airflow of 27 cfm at 0.182 in. H₂O (45.9 m³/hr at 45.3 Pa) of flow impedance. The duct should be carefully designed to minimize the airflow bypass around the heatsink. The T_{LA} temperature of 40°C should be met. This may require the use of superior design techniques to keep T_{RISE} at or below 5°C based on an ambient external temperature of 35°C.

8.4 Boxed Processor Contents

A direct chassis attach method must be used to avoid problems related to shock and vibration, due to the weight of the thermal solution required to cool the processor. The board must not bend beyond specification in order to avoid damage. The boxed processor contains the components necessary to solve both issues. The boxed processor will include the following items:

- Quad-Core Intel® Xeon® Processor 5300 Series
- Unattached heat sink solution
- Four screws, four springs, and four heat sink standoffs (all captive to the heat sink)
- Foam air bypass pad and skirt (included with 1U passive/3U+ active solution)
- Thermal interface material (pre-applied on heat sink)
- Installation and warranty manual
- Intel Inside Logo



The other items listed in [Figure 8-3](#) that are required to complete this solution will be shipped with either the chassis or boards. They are as follows:

- CEK Spring (supplied by baseboard vendors)
- Heat sink standoffs (supplied by chassis vendors)

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9 Debug Tools Specifications

Please refer to the *Debug Port Design Guide for UP/DP Systems* and the appropriate platform design guidelines for information regarding debug tool specifications. [Section 1.3](#) provides collateral details.

9.1 Debug Port System Requirements

The Quad-Core Intel® Xeon® Processor 5300 Series debug port is the command and control interface for the In-Target Probe (ITP) debugger. The ITP enables run-time control of the processors for system debug. The debug port, which is connected to the FSB, is a combination of the system, JTAG and execution signals. There are several mechanical, electrical and functional constraints on the debug port that must be followed. The mechanical constraint requires the debug port connector to be installed in the system with adequate physical clearance. Electrical constraints exist due to the mixed high and low speed signals of the debug port for the processor. While the JTAG signals operate at a maximum of 75 MHz, the execution signals operate at the common clock FSB frequency. The functional constraint requires the debug port to use the JTAG system via a handshake and multiplexing scheme.

In general, the information in this chapter may be used as a basis for including all run-control tools in Quad-Core Intel® Xeon® Processor 5300 Series based systems designs including tools from vendors other than Intel.

Note: The debug port and JTAG signal chain must be designed into the processor board to utilize the XDP for debug purposes except for interposer solutions.

9.2 Target System Implementation

9.2.1 System Implementation

Specific connectivity and layout guidelines for the Debug Port are provided in the *Debug Port Design Guide for UP/DP Systems* and the appropriate platform design guidelines.

9.3 Logic Analyzer Interface (LAI)

Intel is working with two logic analyzer vendors to provide logic analyzer interfaces (LAIs) for use in debugging Quad-Core Intel® Xeon® Processor 5300 Series systems. Tektronix and Agilent should be contacted to obtain specific information about their logic analyzer interfaces. The following information is general in nature. Specific information must be obtained from the logic analyzer vendor.

Due to the complexity of Quad-Core Intel® Xeon® Processor 5300 Series based multiprocessor systems, the LAI is critical in providing the ability to probe and capture FSB signals. There are two sets of considerations to keep in mind when designing a Quad-Core Intel® Xeon® Processor 5300 Series based system that can make use of an LAI: mechanical and electrical.



9.3.1 Mechanical Considerations

The LAI is installed between the processor socket and the processor. The LAI plugs into the socket, while the processor plugs into a socket on the LAI. Cabling that is part of the LAI egresses the system to allow an electrical connection between the processor and a logic analyzer. The maximum volume occupied by the LAI, known as the keepout volume, as well as the cable egress restrictions, should be obtained from the logic analyzer vendor. System designers must make sure that the keepout volume remains unobstructed inside the system. In some cases, it is known that some of the electrolytic capacitors fall inside of the keepout volume for the LAI. In this case, it is necessary to move these capacitors to the backside of the board before using the LAI. Additionally, note that it is possible that the keepout volume reserved for the LAI may include different requirements from the space normally occupied by the heatsink. If this is the case, the logic analyzer vendor will provide either a cooling solution as part of the LAI or additional hardware to mount the existing cooling solution.

9.3.2 Electrical Considerations

The LAI will also affect the electrical performance of the FSB, therefore it is critical to obtain electrical load models from each of the logic analyzer vendors to be able to run system level simulations to prove that their tool will work in the system. Contact the logic analyzer vendor for electrical specifications and load models for the LAI solution they provide.

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